

## 4 Gb, 3 V, 2K Page Size, x8 I/O, SLC NAND Flash Memory for Embedded

### Distinctive Characteristics

#### ■ Density

- 4 Gb

#### ■ Architecture

- Input / Output Bus Width: 8 bits
- Page Size
  - 4 Gb: (2048 + 128) bytes; 128-byte spare area
- Block Size: 64 Pages
  - 4 Gb: 128 KB + 8 KB
- Plane Size
  - 4 Gb: 2048 blocks per plane or (256 MB + 16 MB)
- Device Size
  - 4 Gb: 2 planes per device or 512 Mbyte

#### ■ NAND Flash Interface

- Open NAND Flash Interface (ONFI) 1.0 compliant
- Address, Data, and Commands multiplexed

#### ■ Supply voltage

- 3.3-V device:  $V_{CC} = 2.7\text{ V} \sim 3.6\text{ V}$

#### ■ Security

- One Time Programmable (OTP) area
- Serial number (unique ID)
- Hardware program/erase disabled during power transition
- Volatile and Permanent Block Protection

#### ■ Electronic Signature

- Manufacturer ID: 01h
- Device ID: follow industry standard for single and stacked die implementation

#### ■ Operating Temperature

- Industrial:  $-40^{\circ}\text{C}$  to  $85^{\circ}\text{C}$
- Industrial Plus:  $-40^{\circ}\text{C}$  to  $105^{\circ}\text{C}$

#### ■ Additional Features

- Multiplane Program and Erase commands
- Copy Back Program
- Multiplane Copy Back Program
- Reset (FFh) command is required after power-on as a first command

### Performance

#### ■ Page Read / Program

- Read Page Time ( $t_R$ ):
  - 45  $\mu\text{s}$  (Typ) / Single Plane
  - 55  $\mu\text{s}$  (Typ) / Multi Plane
- Program time / Multiplane Program time: 350  $\mu\text{s}$  (Typ)

#### ■ Block Erase / Multiplane Erase

- Block Erase time: 4 ms (Typ)

#### ■ Reliability

- 80,000 Program/Erase cycles (Typ)
- 10 Year Data retention (Typ)
- Blocks 0-7 are good at the time of shipment

#### ■ Package Options

- Pb-free and low halogen
- 48-Pin TSOP  $12 \times 20 \times 1.2\text{ mm}$
- 63-Ball BGA  $9 \times 11 \times 1\text{ mm}$

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## 1. General Description

The S34ML04G3 is offered with a 3.3 V VCC power supply, and a x8 I/O interface. Its NAND cell provides the most cost-effective solution for the solid state mass storage market. The memory is divided into blocks that can be erased independently so it is possible to preserve valid data while old data is erased. The page size for x8 is (2048 + 128 spare) bytes.

To protect the system bus from transmission errors, the implementation of a 1 bit ECC is recommended.

The chip supports CE# don't care function. This function allows the direct download of the code from the NAND flash memory device by a microcontroller, because the CE# transitions do not stop the read operation.

Like all other 2-KB page NAND flash devices, a program operation typically writes 2 KB in 350  $\mu$ s and an erase operation can typically be performed in 4.0 ms on a 128-KB block. In addition, thanks to multiplane architecture, it is possible to program two pages at a time (one per plane) or to erase two blocks at a time (again, one per plane). The multiplane architecture allows program time to be reduced by 40% and erase time to be reduced by 50%.

In multiplane operations, data in the page can be read out at 20 ns cycle time per byte. The I/O pins serve as the ports for command and address input as well as data input/output. This interface allows a reduced pin count and easy migration towards different densities, without any rearrangement of the footprint.

Commands, Data, and Addresses are asynchronously introduced using CE#, WE#, ALE, and CLE control pins.

The on-chip Program/Erase Controller automates all read, program, and erase functions including pulse repetition, where required, and internal verification and margining of data. A WP# pin is available to provide hardware protection against program and erase operations.

The output pin R/B# (open drain buffer) signals the status of the device during each operation. It identifies if the program/erase/read controller is currently active. The use of an open-drain output allows the Ready/Busy pins from several memories to connect to a single pull-up resistor. In a system with multiple memories the R/B# pins can be connected all together to provide a global status signal.

The Reprogram function allows the optimization of defective block management — when a Page Program operation fails the data can be directly programmed in another page inside the same array section without the time consuming serial data insertion phase.

The VPE input pin (Volatile Protection Enable) provides block granularity hardware protection against undesired data modification (program/erase). This input has a weak internal pull-down (IPD) to disable the volatile protection features if the input is left floating.

Multiplane Copy Back is also supported. Data read out after Copy Back Read (both for single and multiplane cases) is allowed.

The devices provide two innovative features: Page Reprogram and Multiplane Page Reprogram. The Page Reprogram re-programs one page. Normally, this operation is performed after a failed Page Program operation. Similarly, the Multiplane Page Reprogram re-programs two pages in parallel, one per plane. The first page must be in the first plane while the second page must be in the second plane. The Multiplane Page Reprogram operation is performed after a failed Multiplane Page Program operation. The Page Reprogram and Multiplane Page Reprogram guarantee improved performance, because data insertion can be omitted during re-program operations.

The device is available in the TSOP48 (12 x 20 mm) and BGA63 (9 x 11 mm) packages and come with the following security features:

- OTP (one time programmable) area, which is a restricted access area where sensitive data/code can be stored permanently.
- Serial number (unique identifier), which allows the devices to be uniquely identified.
- Volatile and Permanent Block Protection

**Table 1. Product List**

| Device    | Density (bits) |         | Number of Planes | Number of Blocks per Plane |
|-----------|----------------|---------|------------------|----------------------------|
|           | Main           | Spare   |                  |                            |
| S34ML04G3 | 512M x 8       | 32M x 8 | 2                | 2048                       |

## 1.1 Logic Diagram

Figure 1. Logic Diagram

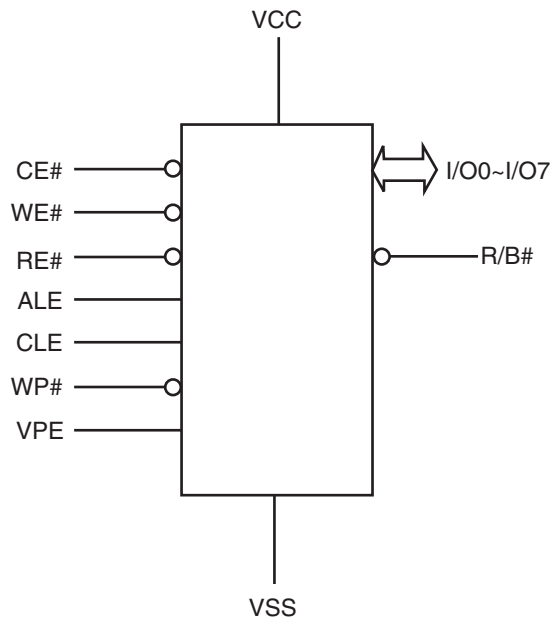


Table 2. Signal Names

| I/O7 - I/O0 (×8) | Data Input / Outputs       |
|------------------|----------------------------|
| CLE              | Command Latch Enable       |
| ALE              | Address Latch Enable       |
| CE#              | Chip Enable                |
| RE#              | Read Enable                |
| WE#              | Write Enable               |
| WP#              | Write Protect              |
| R/B#             | Read/Busy                  |
| VPE              | Volatile Protection Enable |
| VCC              | Power Supply               |
| VSS              | Ground                     |
| NC               | Not Connected              |

## 1.2 Connection Diagram

Figure 2. 48-Pin TSOP1 Contact x8<sup>[1]</sup>

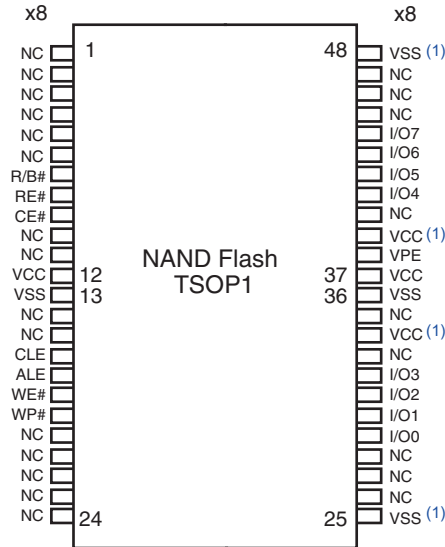
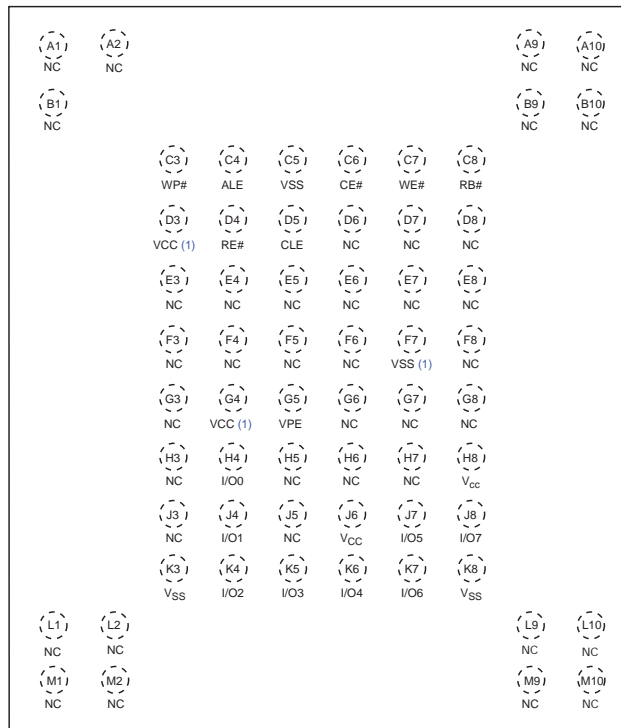


Figure 3. 63-BGA Contact, x8 Device (Balls Down, Top View)<sup>[2]</sup>



**Notes**

1. These pins should be connected to power supply or ground (as designated) following the ONFI specification, however they might not be bonded internally.

### 1.3 Pin Description

**Table 3. Pin Description**<sup>[3, 4]</sup>

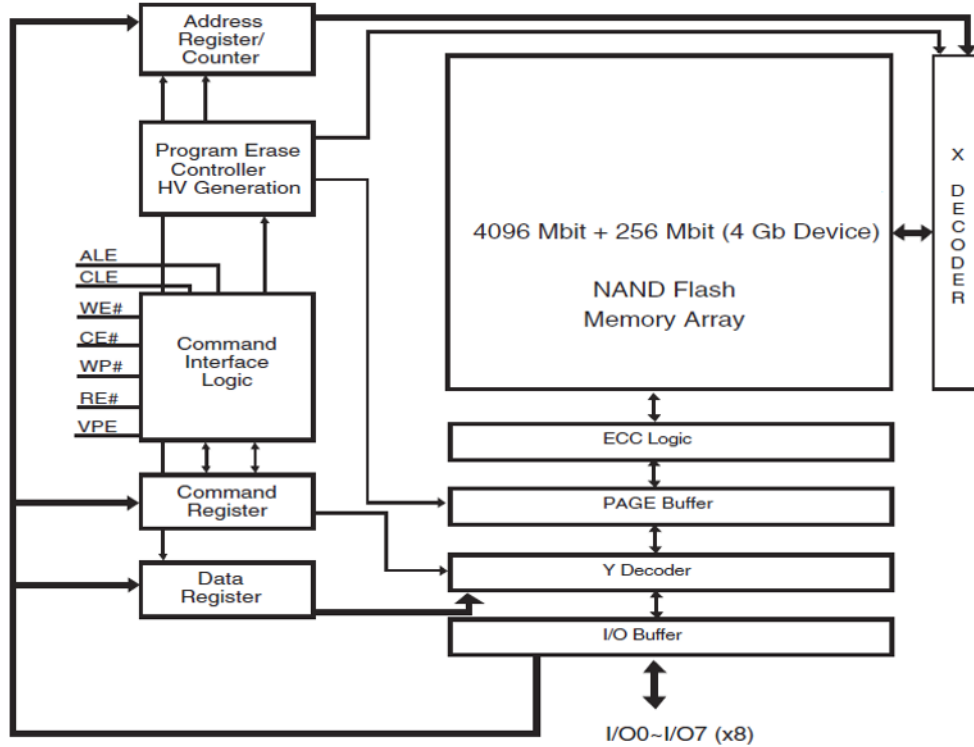
| Pin Name                  | Description   |
|---------------------------|---|
| I/O0 - I/O7 ( <b>×8</b> ) | <b>Inputs/Outputs.</b> The I/O pins are used for command input, address input, data input, and data output. The I/O pins float to High-Z when the device is deselected or the outputs are disabled.   |
| CLE                       | <b>Command Latch Enable.</b> This input activates the latching of the I/O inputs inside the Command Register on the rising edge of Write Enable (WE#).  |
| ALE                       | <b>Address Latch Enable.</b> This input activates the latching of the I/O inputs inside the Address Register on the rising edge of Write Enable (WE#).  |
| CE#                       | <b>Chip Enable.</b> This input controls the selection of the device. When the device is not busy CE# low selects the memory.  |
| WE#                       | <b>Write Enable.</b> This input latches Command, Address and Data. The I/O inputs are latched on the rising edge of WE#.  |
| RE#                       | <b>Read Enable.</b> The RE# input is the serial data-out control, and when active drives the data onto the I/O bus. Data is valid $t_{REA}$ after the falling edge of RE# which also increments the internal column address counter by one.   |
| WP#                       | <b>Write Protect.</b> The WP# pin, when low, provides hardware protection against undesired data modification (program / erase).  |
| R/B#                      | <b>Ready Busy.</b> The Ready/Busy output is an Open Drain pin that signals the state of the memory.   |
| VPE                       | <b>Volatile Protection Enable.</b> The Volatile Protection Enable input, when high during power-on, provides block granularity hardware protection against undesired data modification (program/erase). This input has a weak internal pull-down (IPD) to disable the volatile protection features if the input is left floating. |
| VCC                       | <b>Supply Voltage.</b> The $V_{CC}$ supplies the power for all the operations (Read, Program, Erase). An internal lock circuit prevents the insertion of Commands when $V_{CC}$ is less than $V_{LKO}$ .  |
| VSS                       | <b>Ground.</b>  |
| NC                        | <b>Not Connected.</b>   |

**Notes**

- A 0.1  $\mu$ F capacitor should be connected between the  $V_{CC}$  Supply Voltage pin and the  $V_{SS}$  Ground pin to decouple the current surges from the power supply. The PCB track widths must be sufficient to carry the currents required during program and erase operations.
- An internal voltage detector disables all functions whenever  $V_{CC}$  is below 1.8 V to protect the device from any involuntary program/erase during power transitions.

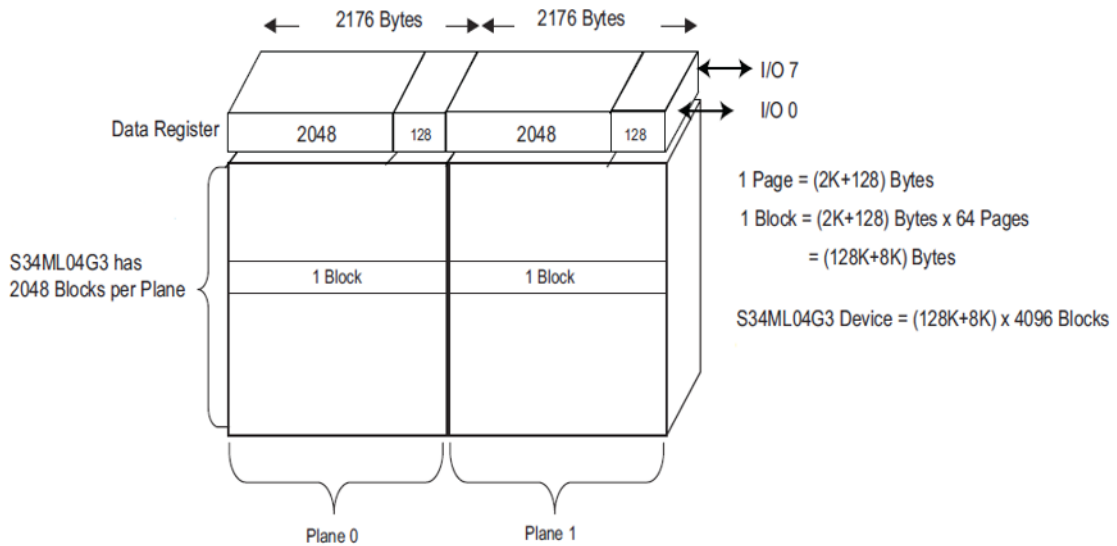
### 1.4 Block Diagram

Figure 5. Functional Block Diagram



### 1.5 Array Organization

Figure 6. Array Organization



## 1.6 Addressing

### 1.6.1 Memory Address Phase Cycles

Table 4 provides the memory organization and the address bit requirements for each devices supported.

**Table 4. Memory Array Organization and Address Bit Requirements**

| Density<br>Page Size | Device and Array Organization |     |        |                  |                |                     |                    |     |                   |         |         | Address bits |
|----------------------|-------------------------------|-----|--------|------------------|----------------|---------------------|--------------------|-----|-------------------|---------|---------|--------------|
|                      | Page Size                     | LUN | Planes | #block per Plane | Page per Block | Spare Byte per Page | Spare Byte per NOP | NOP | Partial Word Size | CA Bits | PA Bits | BA Bits      |
| 04Gb_2KB             | 2KB                           | 1   | 2      | 2048             | 64             | 128                 | 32                 | 4   | 512B              | 12      | 6       | 12           |

**Legend:**

CA = Column address bit.

PA = Page Address bit.

BA = Block Address bit.

Table 5 provides the address phase cycles for the X8 mode of operation.

**Table 5. Address Phase Cycles for X8 Mode of Operation**

| Bus Cycle | Name           | IO[7] | IO[6] | IO[5] | IO[4]  | IO[3]  | IO[2]  | IO[1]  | IO[0]  |
|-----------|----------------|-------|-------|-------|--------|--------|--------|--------|--------|
| 1st       | Col Add 1 (C1) | CA[7] | CA[6] | CA[5] | CA[4]  | CA[3]  | CA[2]  | CA[1]  | CA[0]  |
| 2nd       | Col Add 2 (C2) | L     | L     | L     | CA[12] | CA[11] | CA[10] | CA[9]  | CA[8]  |
| 3rd       | Row Add 1 (R1) | BA[1] | BA[0] | PA[5] | PA[4]  | PA[3]  | PA[2]  | PA[1]  | PA[0]  |
| 4th       | Row Add 2 (R2) | BA[9] | BA[8] | BA[7] | BA[6]  | BA[5]  | BA[4]  | BA[3]  | BA[2]  |
| 5th       | Row Add 3 (R3) | L     | L     | L     | L      | L      | L      | BA[11] | BA[10] |

**Note**

5. Block address concatenated with page address = actual page address, also known as the row address.

**Legend:**

CAx = Column Address bit.

PAx = Page Address bit.

BAx = Block Address bit.

| Density_Page Size | x8 Bus Width       | Additional Notes                      |
|-------------------|--------------------|---------------------------------------|
|                   | CA[12:0]           |                                       |
| 04Gb_2KB          | CA[12]=L, CA[11:0] | If CA[11]=1 then CA[10:7] must be Low |

**Note**

6. Block address BA[11:0].

| Density_Page Size | #of LUNs | # of Planes | #Blocks per Plane | BA       | Additional Notes                |
|-------------------|----------|-------------|-------------------|----------|---------------------------------|
| 04Gb_2KB          | 1        | 2           | 2048              | BA[11:0] | BA[0] controls plane selection. |



## 1.7 Mode Selection

**Table 6. Mode Selection<sup>[7]</sup>**

| Mode                    |               | CLE  | ALE  | CE#  | WE#    | RE#                 | WP#                                 |
|-------------------------|---------------|------|------|------|--------|---------------------|-------------------------------------|
| Read Mode               | Command Input | High | Low  | Low  | Rising | High                | X                                   |
|                         | Address Input | Low  | High | Low  | Rising | High                | X                                   |
| Program or Erase Mode   | Command Input | High | Low  | Low  | Rising | High                | High                                |
|                         | Address Input | Low  | High | Low  | Rising | High                | High                                |
| Data Input              |               | Low  | Low  | Low  | Rising | High                | High                                |
| Data Output (on going)  |               | Low  | Low  | Low  | High   | Falling             | X                                   |
| Data Output (suspended) |               | X    | X    | X    | High   | High                | X                                   |
| Busy Time in Read       |               | X    | X    | X    | High   | High <sup>[9]</sup> | X                                   |
| Busy Time in Program    |               | X    | X    | X    | X      | X                   | High                                |
| Busy Time in Erase      |               | X    | X    | X    | X      | X                   | High                                |
| Write Protect           |               | X    | X    | X    | X      | X                   | Low                                 |
| Stand By                |               | X    | X    | High | X      | X                   | 0V / V <sub>CC</sub> <sup>[8]</sup> |

**Notes**

7. X can be V<sub>IL</sub> or V<sub>IH</sub>. High = Logic level high, Low = Logic level low.
8. WP# should be biased to CMOS high or CMOS low for stand-by mode.
9. During Busy Time in Read, RE# must be held high to prevent unintended data out.

## 2. Bus Operation

There are six standard bus operations that control the device: Command Input, Address Input, Data Input, Data Output, Write Protect, and Standby (see [Table 6](#)).

Typically glitches less than 5 ns on Chip Enable, Write Enable, and Read Enable are ignored by the memory and do not affect bus operations.

### 2.1 Command Input

The Command Input bus operation is used to give a command to the memory device. Commands are accepted with Chip Enable low, Command Latch Enable high, Address Latch Enable low, and Read Enable high and latched on the rising edge of Write Enable. Moreover, for commands that start a modify operation (program/erase) the Write Protect pin must be high. See [Figure 20](#) and [Table 27](#) for details of the timing requirements.

### 2.2 Address Input

The Address Input bus operation allows the insertion of the memory address. For S34ML04G3 devices, five write cycles are needed to input the addresses. Addresses are accepted with Chip Enable low, Address Latch Enable high, Command Latch Enable low, and Read Enable high and latched on the rising edge of Write Enable. Moreover, for commands that start a modify operation (program/erase) the Write Protect pin must be high. See [Figure 21](#) and [Table 27](#) for details of the timing requirements.

### 2.3 Data Input

The Data Input bus operation allows the data to be programmed to be sent to the device. The data insertion is serial and timed by the Write Enable cycles. Data is accepted only with Chip Enable low, Address Latch Enable low, Command Latch Enable low, Read Enable high, and Write Protect high and latched on the rising edge of Write Enable. See [Figure 22](#) and [Table 27](#) for details of the timing requirements.

### 2.4 Data Output

The Data Output bus operation allows data to be read from the memory array and to check the Status Register content, and the ID data. Data can be serially shifted out by toggling the Read Enable pin with Chip Enable low, Write Enable high, Address Latch Enable low, and Command Latch Enable low. See [Figure 23](#) and [Table 27](#) for details of the timings requirements.

### 2.5 Write Protect

The Hardware Write Protection is activated when the Write Protect pin is low. In this condition, modify operations do not start and the content of the memory is not altered. The Write Protect pin is not latched by Write Enable to ensure the protection even during power up.

### 2.6 Standby

In Standby, the device is deselected, outputs are disabled, and power consumption is reduced.

### 3. Command Set

**Table 7. Command Set**

| Command  | CMD Cycle #1        | # of Valid Addr. Cycles | Data Input Cycles | CMD Cycle #2 | CMD Cycle #3 | CMD Cycle #4 | Valid While Selected LUN is Busy | Valid While Other LUNs is Busy | Notes |
|--|---------------------|-------------------------|-------------------|--------------|--------------|--------------|----------------------------------|--------------------------------|-------|
| RESET  | FFh                 | 0                       |                   |              |              |              | Yes                              | Yes                            |       |
| READ ID  | 90h                 | 1                       |                   |              |              |              | No                               | Yes                            |       |
| READ ID2   | 30h-65h-00h         |                         |                   | 30h          |              |              | No                               | Yes                            |       |
| READ ONFI SIGNATURE  | 90h                 | 1                       |                   |              |              |              | No                               | Yes                            |       |
| READ PARAMETER PAGE  | ECh                 | 1                       |                   |              |              |              | No                               | No                             |       |
| READ UNIQUE ID   | EDh                 | 1                       |                   |              |              |              | No                               | No                             |       |
| GET FEATURES   | EEh                 | 1                       |                   |              |              |              | No                               | No                             |       |
| SET FEATURES   | EFh                 | 1                       | 4                 |              |              |              | No                               | No                             |       |
| READ STATUS REGISTER                                       | 70h                 | 0                       |                   |              |              |              | Yes                              | Yes                            |       |
| READ STATUS ENHANCED                                       | 78h                 | 3                       |                   |              |              |              | Yes                              | Yes                            |       |
| RANDOM DATA OUTPUT   | 05h                 | 2                       |                   | E0h          |              |              | No                               | Yes                            |       |
| RANDOM DATA INPUT  | 85h                 | 2                       | Optional          |              |              |              | No                               | Yes                            |       |
| READ MODE  | 00h                 | 0                       |                   |              |              |              | No                               | Yes                            |       |
| PAGE READ  | 00h                 | 5                       |                   | 30h          |              |              | No                               | Yes                            |       |
| PAGE PROGRAM   | 80h                 | 5                       | Yes               | 10h          |              |              | No                               | Yes                            |       |
| BLOCK ERASE  | 60h                 | 3                       |                   | D0h          |              |              | No                               | Yes                            |       |
| COPY BACK READ   | 00h                 | 5                       |                   | 35h          |              |              | No                               | Yes                            |       |
| COPY BACK PROGRAM  | 85h                 | 5                       | Optional          | 10h          |              |              | No                               | Yes                            |       |
| LEGACY OTP AREA ENTRY                                      | 29h-17h-04h-19h     |                         | No                |              |              |              | No                               | No                             |       |
| LEGACY OTP PROTECTION                                      | 4Ch-03h-1Dh-41h-80h | 5(00h,00h,00h,00h,00h)  | Yes               | 10h          |              |              | No                               | No                             | [10]  |
| MULTIPLANE PROGRAM   | 80h                 | 5                       | Yes               | 11h          | 81h          | 10h          | No                               | No                             |       |
| MULTIPLANE READ  | 00h                 | 5                       |                   | 32h          | 30h          |              | No                               | Yes                            |       |
| ONFI MULTIPLANE PROGRAM                                    | 80h                 | 5                       |                   | 11h          | 80h          | 10h          | No                               | No                             |       |
| PAGE REPROGRAM   | 8Bh                 | 5                       | Yes               | 10h          |              |              | No                               | Yes                            |       |
| MULTIPLANE PAGE REPROGRAM                                  | 8Bh                 |                         | Yes               | 11h          | 8Bh          | 10h          | No                               | No                             |       |
| MULTIPLANE BLOCK ERASE                                     | 60h                 | 3                       |                   | 60h          | D0h          |              | No                               | No                             |       |
| ONFI MULTIPLANE BLOCK ERASE                                | 60h                 | 3                       |                   | D1h          | 60h          | D0h          | No                               | No                             |       |
| MULTIPLANE COPY BACK PROGRAM                               | 85h                 | 5                       |                   | 11h          | 81h          | 10h          | No                               | No                             |       |
| ONFI MULTIPLANE COPY BACK PROGRAM                          | 85h                 | 5                       |                   | 11h          | 85h          | 10h          | No                               | No                             |       |
| <b>Block Lock Operations for Volatile Block Protection</b> |                     |                         |                   |              |              |              |                                  |                                |       |
| VOLATILE LOCK ALL  | 2Ah                 |                         |                   |              |              |              | No                               | Yes                            |       |
| BLOCK UNLOCK UPPER   | 24h                 | 3                       |                   |              |              |              | No                               | Yes                            |       |
| BLOCK UNLOCK LOWER   | 23h                 | 3                       |                   |              |              |              | No                               | Yes                            |       |
| LOCK DOWN COMMAND  | 2Ch                 |                         |                   |              |              |              | No                               | Yes                            |       |
| BLOCK PROTECTION STATUS                                    | 7Ah                 | 3                       |                   |              |              |              | No                               | Yes                            |       |

**Note**

10. If the device is in OTP mode, the OTP protection setup command is locking the OTP and not permanently protecting block group 0. Vice-versa, If the device is not in OTP mode, the OTP protection setup command is not locking the OTP but is permanently protecting block group 0. See [Section 4.2. Permanent Block Protection \(PBP\) Overview](#).

**Table 7. Command Set** (Continued)

| Command   | CMD Cycle #1        | # of Valid Addr. Cycles | Data Input Cycles | CMD Cycle #2 | CMD Cycle #3 | CMD Cycle #4 | Valid While Selected LUN is Busy | Valid While Other LUNs is Busy | Notes |
|---|---------------------|-------------------------|-------------------|--------------|--------------|--------------|----------------------------------|--------------------------------|-------|
| <b>Block Lock Operations for Permanent Block Protection</b> |                     |                         |                   |              |              |              |                                  |                                |       |
| PROGRAM PBP SETTINGS  | 4Ch-03h-1Dh-41h-80h | 5(00h,00h,00h,0Yh,00h)  |                   | 10h          |              |              | No                               | No                             | [10]  |
| PBP LOCK DOWN   | 4Ch-03h-1Dh-41h-80h | 5(00h,00h,00h,1Yh,00h)  |                   | 10h          |              |              | No                               | No                             | [10]  |

**Note**

10. If the device is in OTP mode, the OTP protection setup command is locking the OTP and not permanently protecting block group 0. Vice-versa, If the device is not in OTP mode, the OTP protection setup command is not locking the OTP but is permanently protecting block group 0. See [Section 4.2. Permanent Block Protection \(PBP\) Overview](#).

### 3.1 Page Read

Page Read is initiated by writing 00h and 30h to the command register along with five address cycles. Two types of operations are available: random read and serial page read. Random read mode is enabled when the page address is changed. All data within the selected page are transferred to the data registers. The system controller may detect the completion of this data transfer (tR) by analyzing the output of the R/B pin. Once the data in a page is loaded into the data registers, they may be read out in 25 ns cycle time by sequentially pulsing RE#. The repetitive high to low transitions of the RE# signal makes the device output the data, starting from the selected column address up to the last column address.

The device may output random data in a page instead of the sequential data by writing Random Data Output command. The column address of next data, which is going to be out, may be changed to the address that follows Random Data Output command. Random Data Output can be performed as many times as needed.

### 3.2 Multiplane Page Read

The S34ML04G3 devices support Multiplane read, making it possible to read two pages in parallel, one page per plane.

A Multiplane Read cycle consists of a double serial data loading period in which up to 4352 bytes of data may be loaded into the data register, followed by a nonvolatile read period where the loaded data is read out. The serial data loading period begins with inputting the Serial Data Input command (00h), followed by the five cycle address inputs for outputting the data of the first page. The address for this page must be in the 1st plane BA(0). The device supports Random Data Input exactly the same as in the case of a page read operation. The Dummy Page read Confirm command (32h) stops the 1st page data input and the device becomes busy for a short time (tDBSY). Once it is ready again, the '00h' command must be issued, followed by the 2nd page address (5 cycles). The address for this page must be in the 2nd plane BA(0).

After the 30h command is written, page data is transferred from both planes to their data registers in tR where R/B# goes LOW. When the transfers are complete, R/B# goes HIGH. To read out the data from the first plane data register, CMD (00h) followed by 1st plane five cycle address input and RANDOM DATA READ (05h-E0h) must be issued before toggling RE# repeatedly. The same sequence with the 2nd plane address must be followed to read the data from the second plane data register. [Figure 28](#) details the sequence.

### 3.3 Page Program

A page program cycle consists of a serial data loading period in which up to 2 kB (x8) of data may be loaded into the data register, followed by a non-volatile programming period where the loaded data is programmed into the appropriate cell.

The serial data loading period begins by inputting the Serial Data Input command (80h), followed by the five cycle address inputs and then serial data. The words other than those to be programmed do not need to be loaded. The device supports Random Data Input within a page. The column address of next data, which will be entered, may be changed to the address that follows the Random Data Input command (85h). Random Data Input may be performed as many times as needed.

The Page Program confirm command (10h) initiates the programming process. The internal write state controller automatically executes the algorithms and controls timings necessary for program and verify, thereby freeing the system controller for other tasks.

Once the program process starts, the Read Status Register commands (70h or 78h) may be issued to read the Status Register. The system controller can detect the completion of a program cycle by monitoring the R/B# output, or the Status bit (I/O6) of the Status Register. Only the Read Status commands (70h or 78h) or Reset command are valid while programming is in progress. When the Page Program is complete, the Write Status Bit (I/O0) may be checked. The internal write verify detects only errors for 1's that are not successfully programmed to 0's. The command register remains in Read Status command mode until another valid command is written to the command register. [Figure 29](#) and [Figure 32](#) detail the sequence.

The device is programmable by page, but it also allows multiple partial page programming of a word or consecutive bytes up to 2 kB (x8) in a single page program cycle.

The number of consecutive partial page programming operations (NOP) within the same page must not exceed the number indicated in [Table 31](#). Both main data and user spare will be input at the same time for NOP operation; otherwise, data is not guaranteed.

If a Page Program operation is interrupted by hardware reset, power failure or other means, the host must ensure that the interrupted page is not used for further reading or programming operations until the next uninterrupted block erase is complete.

### 3.4 Multiplane Program

The S34ML04G3 devices support Multiplane Program, making it possible to program two pages in parallel, one page per plane.

A Multiplane Program cycle consists of a double serial data loading period in which up to 4352 bytes (x8) of data may be loaded into the data register, followed by a non-volatile programming period where the loaded data is programmed into the appropriate cell. The serial data loading period begins with inputting the Serial Data Input command (80h), followed by the five cycle address inputs and serial data for the 1st page. The address for this page must be in the 1st plane (BA[0]=0). The device supports Random Data Input exactly the same as in the case of page program operation. The Dummy Page Program Confirm command (11h) stops 1st page data input and the device becomes busy for a short time ( $t_{DBSY}$ ). Once it has become ready again, the '81h' command must be issued, followed by 2nd page address (5 cycles) and its serial data input. The address for this page must be in the 2nd plane (BA[0]=1). The Program Confirm command (10h) starts parallel programming of both pages.

[Figure 34](#) describes the sequences using the legacy protocol. In this case, the block address bits for both planes are the same except for the bit(s) that select the plane. [Figure 35](#) describes the sequences using the ONFI protocol. For both addresses issued in this protocol, the block address bits must be the same except for the bit(s) that select the plane.

The user can check operation status by monitoring R/B# pin or reading the Status Register (command 70h or 78h). The Read Status Register command is also available during Dummy Busy time ( $t_{DBSY}$ ). In case of failure in either page program, the fail bit of the Status Register will be set. Refer to [Section 3.9. Read Status Register](#) for further info.

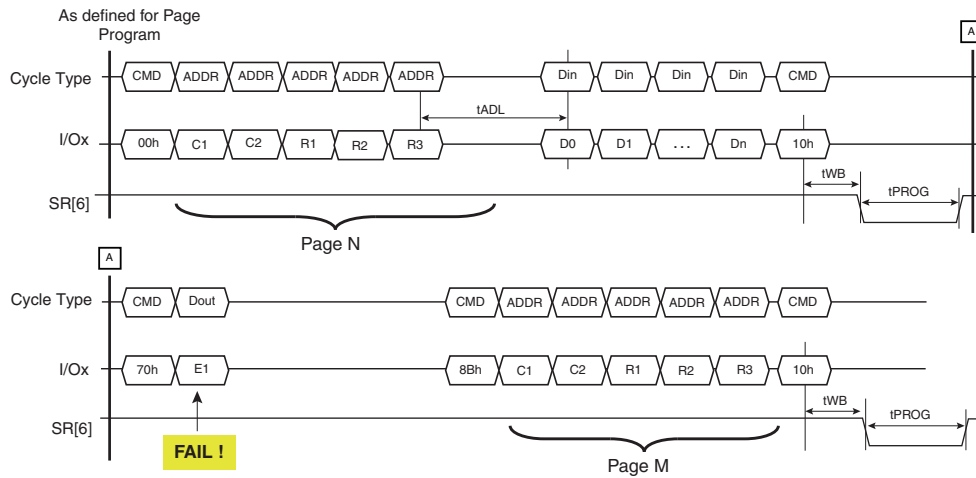
The number of consecutive partial page programming operations (NOP) within the same page must not exceed the number indicated in [Table 31](#). Pages may be programmed in any order within a block.

If a Multiplane Program operation is interrupted by hardware reset, power failure or other means, the host must ensure that the interrupted pages are not used for further reading or programming operations until the next uninterrupted block erases are complete for the applicable blocks.

### 3.5 Page Reprogram

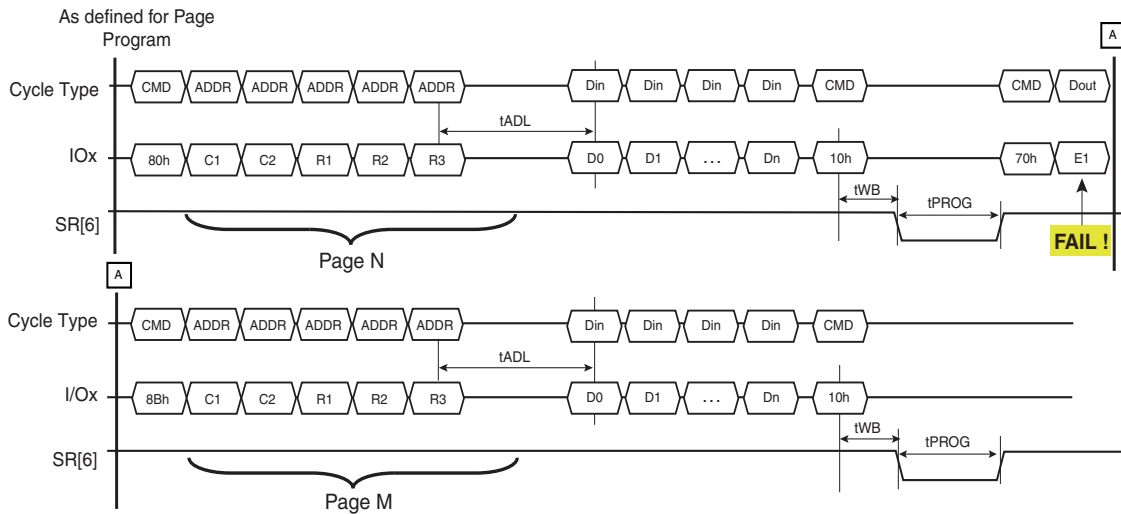
Page Program may result in a fail, which can be detected by Read Status Register. In this event, the host may call Page Reprogram. This command allows the reprogramming of the same pattern of the last (failed) page into another memory location. The command sequence initiates with reprogram setup (8Bh), followed by the five cycle address inputs of the target page. If the target pattern for the destination page is not changed compared to the last page, the program confirm can be issued (10h) without any data input cycle, as described in [Figure 7](#).

Figure 7. Page Reprogram



On the other hand, if the pattern bound for the target page is different from that of the previous page, data in cycles can be issued before program confirm '10h', as described in [Figure 8](#).

Figure 8. Page Reprogram with Data Manipulation



The device supports Random Data Input within a page. The column address of next data, which will be entered, may be changed to the address which follows the Random Data Input command (85h). Random Data Input may be operated multiple times regardless of how many times it is done in a page.

The Program Confirm command (10h) initiates the re-programming process. The internal write state controller automatically executes the algorithms and controls timings necessary for program and verify, thereby freeing the system controller for other tasks. Once the program process starts, the Read Status Register command may be issued to read the Status Register. The system controller can detect the completion of a program cycle by monitoring the R/B# output, or the Status bit (I/O6) of the Status Register. Only the Read Status command and Reset command are valid when programming is in progress. When the Page Program is complete, the Write Status Bit (I/O0) may be checked. The internal write verify detects only errors for 1's that are not successfully programmed to 0's. The command register remains in Read Status command mode until another valid command is written to the command register.

The Page Reprogram must be issued in the same plane as the Page Program that failed. To program the data to a different plane, use the Page Program operation instead. The Multiplane Page Reprogram can re-program two pages in parallel, one per plane. The Multiplane Page Reprogram operation is performed after a failed Multiplane Page Program operation. The command sequence is very similar to [Figure 34](#), except that it requires the Page Reprogram Command (8Bh) instead of 80h and 81h.

If a Page Reprogram operation is interrupted by hardware reset, power failure or other means, the host must ensure that the interrupted page is not used for further reading or programming operations until the next uninterrupted block erase is complete.

### 3.6 Block Erase

The Block Erase operation is done on a block basis. Block address loading is accomplished in three cycles initiated by an Erase Setup command (60h). Only the block address bits are valid while the page address bits are ignored.

The Erase Confirm command (D0h) following the block address loading initiates the internal erasing process. This two-step sequence of setup followed by the execution command ensures that memory contents are not accidentally erased due to external noise conditions.

At the rising edge of WE# after the erase confirm command input, the internal write controller handles erase and erase verify. Once the erase process starts, the Read Status Register commands (70h or 78h) may be issued to read the Status Register.

The system controller can detect the completion of an erase by monitoring the R/B# output, or the Status bit (I/O6) of the Status Register. Only the Read Status commands (70h or 78h) and Reset command are valid while erasing is in progress. When the erase operation is completed, the Write Status Bit (I/O0) may be checked. [Figure 36](#) details the sequence.

If a Block Erase operation is interrupted by hardware reset, power failure or other means, the host must ensure that the interrupted block is erased under continuous power conditions before that block can be trusted for further programming and reading operations.

### 3.7 Multiplane Block Erase

Multiplane Block Erase allows the erase of two blocks in parallel, one block per memory plane.

The Block erase setup command (60h) must be repeated two times, followed by 1st and 2nd block address respectively (3 cycles each). As for block erase, D0h command makes embedded operation start. In this case, multiplane erase does not need any Dummy Busy Time between 1st and 2nd block insertion. See [Table 31](#) for performance information.

For the Multiplane Block Erase operation, the address of the first block must be within the first plane (BA[0] = 0) and the address of the second block in the second plane (BA[0] = 1). See [Figure 38](#) for a description of the legacy protocol. In this case, the block address bits for both planes are the same except for the bit(s) that select the plane. [Figure 39](#) describes the sequences using the ONFI protocol. For both addresses issued in this protocol, the block address bits must be the same except for the bit(s) that select the plane.

The user can check operation status by monitoring R/B# pin or reading the Status Register (command 70h or 78h). The Read Status Register command is also available during Dummy Busy time ( $t_{DBSY}$ ). In case of failure in either erase, the fail bit of the Status Register will be set.

If a Multiplane Block Erase operation is interrupted by hardware reset, power failure or other means, the host must ensure that the interrupted blocks are erased under continuous power conditions before those blocks can be trusted for further programming and reading operations.

### 3.8 Copy Back Program

The copy back feature is intended to quickly and efficiently rewrite data stored in one page without utilizing an external memory. Since the time-consuming cycles of serial access and re-loading cycles are removed, the system performance is greatly improved. The benefit is especially obvious when a portion of a block needs to be updated and the rest of the block also needs to be copied to the newly assigned free block. The operation for performing a copy back is a sequential execution of page-read (without mandatory serial access) and Copy Back Program with the address of destination page. A read operation with the '35h' command and the address of the source page moves the whole page of data into the internal data register. Because of the sub plane structure of the device, copy-back read requires additional read time of 30µs for Multi-Plane operation and 15µs for 2KB Page-single Plane. As soon as the device returns to the Ready state, optional data read-out is allowed by toggling RE# (see Figure 40), or the Copy Back Program command (85h) with the address cycles of the destination page may be written. The Program Confirm command (10h) is required to actually begin programming.

The source and the destination pages in the Copy Back Program sequence must belong to the same device plane (same BA[0] for S34ML04G3). Copy Back Read and Copy Back Program for a given plane must be between odd address pages or between even address pages for the device to meet the program time (t<sub>PROG</sub>) specification. Copy Back Program may not meet this specification when copying from an odd address page (source page) to an even address page (target page) or from an even address page (source page) to an odd address page (target page).

The data input cycle for modifying a portion or multiple distinct portions of the source page is allowed as shown in Figure 41.

If a Copy Back Program operation is interrupted by hardware reset, power failure or other means, the host must ensure that the interrupted page is not used for further reading or programming operations until the next uninterrupted block erase is complete.

#### 3.8.1 Multiplane Copy Back Program

The device supports Multiplane Copy Back Program with exactly the same sequence and limitations as the Page Program. Multiplane Copy Back Program must be preceded by two single page Copy Back Read command sequences (1st page must be read from the 1st plane and 2nd page from the 2nd plane).

Multiplane Copy Back cannot cross plane boundaries — the contents of the source page of one device plane can be copied only to a destination page of the same plane.

The Multiplane Copy Back Program sequence represented in Figure 42 shows the legacy protocol. In this case, the block address bits select the respective blocks for each plane. Figure 43 describes the sequence using the ONFI protocol.

If a Multiplane Copy Back Program operation is interrupted by hardware reset, power failure or other means, the host must ensure that the interrupted pages are not used for further reading or programming operations until the next uninterrupted block erases are complete for the applicable blocks.

### 3.9 Read Status Register

The Status Register is used to retrieve the status value for the last operation issued. After writing 70h command to the command register, a read cycle outputs the content of the Status Register to the I/O pins on the falling edge of CE# or RE#, whichever occurs last. This two-line control allows the system to poll the progress of each device in multiple memory connections even when R/B# pins are common-wired.

If the Read Status Register command is issued during multiplane operations then Status Register polling will return the combined status value related to the outcome of the operation in the two planes according to the following table.

| Status Register Bit | Composite Status Value |
|---------------------|------------------------|
| Bit 0, Pass/Fail    | OR                     |

In other words, the Status Register is dynamic; the user is not required to toggle RE# / CE# to update it.

The command register remains in Status Read mode until further commands are issued. Therefore, if the Status Register is read during a random read cycle, the read command (00h) must be issued before starting read cycles.

**Note** The Read Status Register command should not be used for concurrent operations in multi-die stack configurations (single CE#). "Read Status Enhanced" must be used instead.

Using the READ STATUS (70h) command for interleaved operations will result in bus contention since the status will be reported by more than one die simultaneously.



### 3.10 Read Status Enhanced

Read Status Enhanced is used to retrieve the status value for a previous operation in the specified plane.

Figure 45 defines the Read Status Enhanced behavior and timings. The plane and die address must be specified in the command sequence to retrieve the status of the die and the plane of interest.

The command register remains in Status Read mode until further commands are issued. The Status Register is dynamic; the user is not required to toggle RE# / CE# to update it.

### 3.11 Read Status Register Field Definition

Table 8 below lists the meaning of each bit of the Read Status Register and Read Status Enhanced.

**Table 8. Read Status Register Coding**

| SR Bit                | Value Definition   | Block Erase   | Page Program                         | Page Read                     | OTP Block Protect           |
|-----------------------|--|---------------|--------------------------------------|-------------------------------|-----------------------------|
| 0 <sup>[11, 12]</sup> | Pass: "0"<br>Fail: "1"   | Pass / Fail   | Pass / Fail                          | Not Used                      | Pass/Fail                   |
| 1                     | Reserved   | Not Used      | Not Used                             | Not Used                      | Not Used                    |
| 2                     | Reserved   | Not Used      | Not Used                             | Not Used                      | Not Used                    |
| 3 <sup>[13]</sup>     | OTP Not Protected: "0"<br>OTP Protected: "1"   | Not Used      | Not Used                             | Not Used                      | Not Protected/<br>Protected |
| 4 <sup>[14]</sup>     | 1: (Flag 1*) Page Recommended to Rewrite<br>1: (Flag 2) Page Uncorrectable<br>0: Normal mode | Not Used      | Not Used                             | Flag 1 (default)<br>or Flag 2 | Not Used                    |
| 5 <sup>[15]</sup>     | Busy: "0"<br>Ready: "1"  | Not Used      | Program in<br>progress/<br>Completed | Not Used                      | Not Used                    |
| 6                     | Busy: "0"<br>Ready: "1"  | Ready/Busy    | Ready/Busy                           | Ready/Busy                    | Ready/Busy                  |
| 7 <sup>[16]</sup>     | Protected: "0"<br>Not Protected: "1"   | Write Protect | Write Protect                        | Write Protect                 | Write Protect               |

**Notes**

- 11. SR[0] value is 0 when power-up with VPE=L, else don't care; SR[0] value is a don't care after read operation.
- 12. Bit 0: This bit is only valid for Program and Erase operations. If cleared to zero, then the last command was successful. If set to one, then the last command failed. For two plane operation, it indicates that one or both planes failed. The Read Status Enhanced (78h) operation can be used to determine with plane the operation failed. If a block is protected, this bit should fail.
- 13. Bit 3: This bit indicates whether the OTP is lock down, and should be cleared to zero, when not in OTP mode, or FF command is issued, or on power up. This bit should be set to one after lock down command is issued, or when OTP operation (program/erase/erase) command is issued and OTP is lock down.
- 14. Bit 4: This bit indicates if the last page read contained a high number of ECC errors.
  - The Flag 1(default) or Flag 2 mode, is selectable using the Set Feature command (see Table 17 on page 26).
  - Flag 1 mode: When set to 1, this bit[4] indicates that the page read had a high ECC error count. When such situation occurs, the user is recommended to re-program the page read.
  - Flag 2 mode: When set to one, this bit[4] indicates that the page read had more ECC errors than the internal ECC engine could correct.
- 15. Bit 5: If set to one then there is no array operation in progress. If cleared to zero, then there is a command being progressed.
- 16. Bit 7: If set to one, then the device is not write protected. If cleared to zero, then the device is write protected. This bit will always be valid regardless of state of the R/B#. For Status Enhanced command, signal follows WP pin and also indicate protection of the block specified in the 78h command address field.

### 3.12 Reset

The Reset feature is executed by writing FFh to the command register. If the device is in the Busy state during random read, program, or erase mode, the Reset operation will abort these operations. The contents of memory cells being altered are no longer valid, as the data may be partially programmed or erased. The command register is cleared to wait for the next command, and the Status Register is cleared to value E0h when WP# is high or value 60h when WP# is low. If the device is already in reset state a new Reset command will not be accepted by the command register. The R/B# pin transitions to low for  $t_{RST}$  after the Reset command is written. Refer to [Figure 46](#) for further details.

Reset (FFh) command is required after power-on as a first command and must be issued to all CE#s.

### 3.13 Read ID

The device contains a product identification mode, initiated by writing 90h to the command register, followed by an address input of 00h.

**Note:** If you want to execute Read Status command (0x70) after Read ID sequence, you should input dummy command (0x00) before Read Status command (0x70).

For the S34ML04G3 devices, five read cycles sequentially output the manufacturer code (01h), and the device code and 3rd, 4th, and 5th cycle ID, respectively. The command register remains in Read ID mode until further commands are issued to it. [Figure 7.24](#) shows the operation sequence, while [Table 9](#) to [Table 13](#) explain the byte meaning.

**Table 9. Read ID for Supported Configurations**

| Density | Org | V <sub>CC</sub> | 1st | 2nd | 3rd | 4th | 5th |
|---------|-----|-----------------|-----|-----|-----|-----|-----|
| 4 Gb    |     |                 | 01h | DCh | 00h | 05h | 04h |

**Table 10. Read ID Bytes**

| Device Identifier Byte | Description                                     |
|------------------------|---|
| 1st                    | Manufacturer Code                               |
| 2nd                    | Device Identifier                               |
| 3rd                    | Internal chip number, cell type                 |
| 4th                    | Page Size, Block Size, Spare Size, Organization |
| 5th                    | Multiplane information                          |

### 3<sup>rd</sup> ID Data

**Table 11. Read ID Byte 3 Description**

|                      | Description   | I/O7 | I/O6 | I/O5 I/O4 | I/O3 I/O2 | I/O1 I/O0 |
|----------------------|---------------|------|------|-----------|-----------|-----------|
| Internal Chip Number | 1             |      |      |           |           | 0 0       |
|                      | 2             |      |      |           |           | 0 1       |
|                      | 4             |      |      |           |           | 1 0       |
|                      | 8             |      |      |           |           | 1 1       |
| Cell type            | 2-level cell  |      |      |           | 0 0       |           |
|                      | 4-level cell  |      |      |           | 0 1       |           |
|                      | 8-level cell  |      |      |           | 1 0       |           |
|                      | 16-level cell |      |      |           | 1 1       |           |
| Reserved             | 0             | 0    | 0    | 0         |           |           |

#### 4<sup>th</sup> ID Data

**Table 12. Read ID Byte 4 Description**

|                                    | Description      | I/O7   | I/O6 | I/O5 I/O4  | I/O3   | I/O2   | I/O1 I/O0  |
|------------------------------------|------------------|--------|------|------------|--------|--------|------------|
| Page Size<br>(without spare area)  | 2 KB<br>4 KB     |        |      |            |        |        | 0 1<br>1 0 |
| Block Size<br>(without spare area) | 128 KB<br>256 KB | 0<br>0 |      | 0 0<br>0 1 |        |        |            |
| Spare Area Size                    | 128B<br>256B     |        |      |            | 0<br>1 | 1<br>0 |            |
| Organization                       | ×8               |        | 0    |            |        |        |            |

#### 5<sup>th</sup> ID Data

**Table 13. Read ID Byte 5 Description — S34ML02G3 and S34ML04G3**

|              | Description | I/O7 | I/O6 I/O5 I/O4 | I/O3 I/O2 | I/O1 I/O0 |
|--------------|-------------|------|----------------|-----------|-----------|
| Plane Number | 1           |      |                | 0 0       |           |
|              | 2           |      |                | 0 1       |           |
|              | 4           |      |                | 1 0       |           |
|              | 8           |      |                | 1 1       |           |
| Reserved     |             | 0    | 0              |           | 0         |

### 3.14 Read ID2

The device contains an alternate identification mode, initiated by writing 30h-65h-00h to the command register, followed by address inputs, followed by command 30h. The address for S34ML04G3 will be 00h-02h-02h-00h-00h. The ID2 data can then be read from the device by pulsing RE#. The command register remains in Read ID2 mode until further commands are issued to it. [Figure 48](#) shows the Read ID2 command sequence. Read ID2 values are all 0xFs, unless specific values are requested when ordering.

### 3.15 Read ONFI Signature

To retrieve the ONFI signature, the command 90h together with an address of 20h is entered (i.e. it is not valid to enter an address of 00h and read 36 bytes to get the ONFI signature). The ONFI signature is the ASCII encoding of 'ONFI' where 'O' = 4Fh, 'N' = 4Eh, 'F' = 46h, and 'I' = 49h. Reading beyond four bytes yields indeterminate values. [Figure 49](#) shows the operation sequence.

### 3.16 Read Parameter Page

The device supports the ONFI Read Parameter Page operation, initiated by writing ECh to the command register, followed by an address input of 00h. The host may monitor the R/B# pin or wait for the maximum data transfer time ( $t_R$ ) before reading the Parameter Page data. The command register remains in Parameter Page mode until further commands are issued to it. If the Status Register is read to determine when the data is ready, the Read Command (00h) must be issued before starting read cycles. [Figure 50](#) shows the operation sequence, while [Table 14](#) explains the parameter fields.

**Table 14. Parameter Page Description**

| Byte   | O/M | Description  | Values   |
|--|-----|--|--|
| <b>Revision Information and Features Block</b> |     |  |  |
| 0-3  | M   | Parameter page signature<br>Byte 0: 4Fh, "O"<br>Byte 1: 4Eh, "N"<br>Byte 2: 46h, "F"<br>Byte 3: 49h, "I"   | 4Fh, 4Eh, 46h, 49h   |
| 4-5  | M   | Revision number<br>2-15 Reserved (0)<br>1 1 = supports ONFI version 1.0<br>0 Reserved (0)  | 02h, 00h   |
| 6-7  | M   | Features supported<br>5-15 Reserved (0)<br>4 1 = supports odd to even page Copyback<br>3 1 = supports interleaved operations<br>2 1 = supports non-sequential page programming<br>1 1 = supports multiple LUN operations<br>0 1 = supports 16-bit data bus width                       | S34ML04G300 (*8): 18h, 00h   |
| 8-9  | M   | Optional commands supported<br>6-15 Reserved (0)<br>5 1 = supports Read Unique ID<br>4 1 = supports Copyback<br>3 1 = supports Read Status Enhanced<br>2 1 = supports Get Features and Set Features<br>1 1 = supports Read Cache commands<br>0 1 = supports Page Cache Program command | S34ML04G3: 3Ch, 00h  |
| 10-31  |     | Reserved (0)   | 00h  |
| <b>Manufacturer Information Block</b>          |     |  |  |
| 32-43  | M   | Device manufacturer (12 ASCII characters)  | 53h, 50h, 41h, 4Eh, 53h, 49h, 4Fh, 4Eh, 20h, 20h, 20h, 20h   |
| 44-63  | M   | Device model (20 ASCII characters)   | S34ML04G3: 53h, 33h, 34h, 4Dh, 4Ch, 30h, 34h, 47h, 33h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h, 20h |
| 64   | M   | JEDEC manufacturer ID  | 01h  |
| 65-66  | O   | Date code  | 00h  |
| 67-79  |     | Reserved (0)   | 00h  |
| <b>Memory Organization Block</b>               |     |  |  |
| 80-83  | M   | Number of data bytes per page  | 00h, 08h, 00h, 00h   |
| 84-85  | M   | Number of spare bytes per page   | S34ML04G3: 80h, 00h  |
| 86-89  | M   | Number of data bytes per partial page  | 00h, 02h, 00h, 00h   |
| 90-91  | M   | Number of spare bytes per partial page   | 20h, 00h   |
| 92-95  | M   | Number of pages per block  | 40h, 00h, 00h, 00h   |
| 96-99  | M   | Number of blocks per logical unit (LUN)  | S34ML04G3: 00h, 10h, 00h, 00h  |
| 100  | M   | Number of logical units (LUNs)   | 01h  |

**Note**  
17. O" Stands for Optional, "M" for Mandatory.

**Table 14. Parameter Page Description (Continued)**

| Byte                               | O/M | Description  | Values  |
|------------------------------------|-----|--|---|
| 101                                | M   | Number of address cycles<br>4-7 Column address cycles<br>0-3 Row address cycles  | S34ML04G3: 23h  |
| 102                                | M   | Number of bits per cell  | 01h   |
| 103-104                            | M   | Bad blocks maximum per LUN   | S34ML04G3: 50h, 00h                                   |
| 105-106                            | M   | Block endurance  | 08h, 04h (–40°C to 85°C)<br>06h, 04h (–40°C to 105°C) |
| 107                                | M   | Guaranteed valid blocks at beginning of target   | 08h   |
| 108-109                            | M   | Block endurance for guaranteed valid blocks  | 00h, 00h  |
| 110                                | M   | Number of programs per page  | 04h   |
| 111                                | M   | Partial programming attributes<br>5-7 Reserved<br>4 1 = partial page layout is partial page data followed by partial page spare<br>1-3 Reserved<br>0 1 = partial page programming has constraints  | 00h   |
| 112                                | M   | Number of bits ECC correctability  | 00h   |
| 113                                | M   | Number of interleaved address bits<br>4-7 Reserved (0)<br>0-3 Number of interleaved address bits   | S34ML04G3: 01h  |
| 114                                | O   | Interleaved operation attributes<br>4-7 Reserved (0)<br>3 Address restrictions for program cache<br>2 1 = program cache supported<br>1 1 = no block address restrictions<br>0 Overlapped / concurrent interleaving support                             | S34ML04G3: 00h  |
| 115-127                            |     | Reserved (0)   | 00h   |
| <b>Electrical Parameters Block</b> |     |  |   |
| 128                                | M   | I/O pin capacitance  | 0Ah   |
| 129-130                            | M   | Timing mode support<br>6-15 Reserved (0)<br>5 1 = supports timing mode 5<br>4 1 = supports timing mode 4<br>3 1 = supports timing mode 3<br>2 1 = supports timing mode 2<br>1 1 = supports timing mode 1<br>0 1 = supports timing mode 0, should be 1  | 3Fh, 00h  |
| 131-132                            | O   | Program cache timing mode support<br>6-15 Reserved (0)<br>5 1 = supports timing mode 5<br>4 1 = supports timing mode 4<br>3 1 = supports timing mode 3<br>2 1 = supports timing mode 2<br>1 1 = supports timing mode 1<br>0 1 = supports timing mode 0 | 00h, 00h  |
| 133-134                            | M   | t <sub>PROG</sub> Maximum page program time (μs)   | 58h, 02h  |
| 135-136                            | M   | t <sub>BERS</sub> Maximum block erase time (μs)  | 10h, 27h  |
| 137-138                            | M   | t <sub>R</sub> Maximum page read time (μs)   | C2h, 01h  |

**Note**

17. "O" Stands for Optional, "M" for Mandatory.

**Table 14. Parameter Page Description (Continued)**

| Byte                             | O/M | Description  | Values   |
|----------------------------------|-----|--|--|
| 139-140                          | M   | t <sub>CCS</sub> Minimum Change Column setup time (ns) | C8h, 00h   |
| 141-163                          |     | Reserved (0)   | 00h  |
| <b>Vendor Block</b>              |     |  |  |
| 164-165                          | M   | Vendor specific Revision number                        | 00h  |
| 166-253                          |     | Vendor specific  | 00h  |
| 254-255                          | M   | Integrity CRC  | 7Bh, 03h (–40°C to 85°C)<br>F1h, 2Bh (–40°C to 85°C) |
| <b>Redundant Parameter Pages</b> |     |  |  |
| 256-511                          | M   | Value of bytes 0-255                                   | Repeat Value of bytes 0-255                          |
| 512-767                          | M   | Value of bytes 0-255                                   | Repeat Value of bytes 0-255                          |
| 768+                             | O   | Additional redundant parameter pages                   | FFh  |

**Note**

17. O" Stands for Optional, "M" for Mandatory.

### 3.17 Read Unique ID

The device supports the ONFI Read Unique ID function, initiated by writing EDh to the command register, followed by an address input of 00h. The host must monitor the R/B# pin or wait for the maximum data transfer time (t<sub>R</sub>) before reading the Unique ID data. The first sixteen bytes returned by the flash is a unique value. The next sixteen bytes returned are the bit-wise complement of the unique value. The host can verify the Unique ID was read correctly by performing an XOR of the two values. The result should be all ones. The command register remains in Unique ID mode until further commands are issued to it. [Figure 51](#) shows the operation sequence, while [Table 15](#) shows the Unique ID data contents.

**Table 15. Unique ID Data Description**

| Byte    | Description   |
|---------|---------------|
| 0-15    | Unique ID     |
| 16-31   | ID Complement |
| 32-47   | ID Complement |
| 48-63   | Unique ID     |
| 64-79   | Unique ID     |
| 80-95   | ID Complement |
| 96-111  | ID Complement |
| 112-127 | Unique ID     |
| 128-143 | Unique ID     |
| 144-159 | ID Complement |
| 160-175 | ID Complement |
| 176-191 | Unique ID     |
| 192-207 | Unique ID     |
| 208-223 | ID Complement |
| 224-239 | ID Complement |
| 240-255 | Unique ID     |
| 256-271 | Unique ID     |
| 272-287 | ID Complement |
| 288-303 | ID Complement |
| 304-319 | Unique ID     |

**Table 15. Unique ID Data Description (Continued)**

| Byte    | Description   |
|---------|---------------|
| 320-335 | Unique ID     |
| 336-351 | ID Complement |
| 352-367 | ID Complement |
| 368-383 | Unique ID     |
| 384-399 | Unique ID     |
| 400-415 | ID Complement |
| 416-431 | ID Complement |
| 432-447 | Unique ID     |
| 448-463 | Unique ID     |
| 464-479 | ID Complement |
| 480-495 | ID Complement |
| 496-511 | Unique ID     |

### 3.18 One-Time Programmable (OTP)

The device contains a one-time programmable (OTP) area, that consists of one block (64 pages), which is accessed in two different ways:

1. Legacy vendor command method
2. SET FEATURE method

#### 3.18.1 OTP Access

Legacy Vendor Method: The OTP area is located in block #6.

The OTP entry/program/read sequences are as follows:

Entry: 29h - 17h - 04h - 19h

Program: 80h - 00h - 00h - 80h - 01h - 00h - 10h

Read: 00h - 00h - 00h - 80h - 01h - 00h - 30h

SET FEATURE Method: Issue SET FEATURE (EFh) command followed by feature address 90h and the data

P1 = 09h, P2 = 00h, P3 = 00h, and P4 = 00h (See "SET FEATURES, GET FEATURES ONFI Commands" Section for more details on P1/P2/P3/P4 definition)

Once in OTP mode, all subsequent Page Read and Page Program commands are applied to the OTP area. ERASE commands are not valid in OTP mode.

Copyback and Reprogram commands shown in the commands Set are not supported in OTP mode.

#### 3.18.2 OTP Protection

Legacy Vendor Method: Issue OTP protection vendor command sequence 4Ch-03h-1Dh-41h-80h followed by an address of 00h/00h/00h/00h and 10h command.

SET FEATURE Method: Issue SET FEATURE (EFh) command followed by feature address 90h and the data

P1 = 0Bh, P2 = 00h, P3 = 00h, and P4 = 00h.

The status register read command can be used to poll the status register to determine when the programming operation is completed and verify that the OTP area is protected.

The OTP protection sequences described above assume the device is in OTP mode.

### 3.18.3 OTP Exit

Legacy Vendor Method: Issue the Reset (FFh) command to exit the OTP mode

SET FEATURE Method: Issue SET FEATURE (EFh) command with feature address 90h and the data

P1 = 08h, P2 = 00h, P3 = 00h, and P4 = 00h

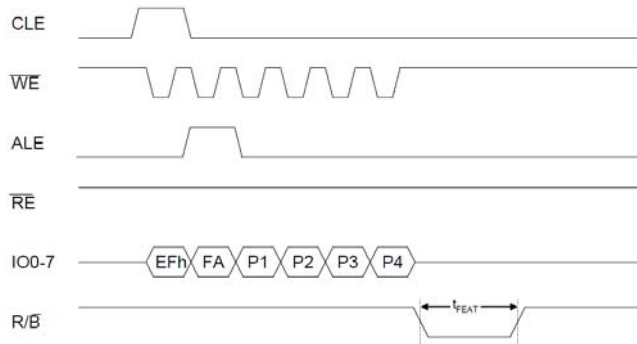
The OTP area is of a single erase block size (64 pages), and hence only row addresses between 00h and 3Fh are allowed. The Block Erase command is not allowed in the OTP mode.

## 3.19 Feature Operations

### 3.19.1 Set Features

The Set Features function modifies the settings of a particular feature. For example, this function can be used to enable a feature that is disabled at power-on. Feature settings are volatile across power cycles. Feature setting value is retained across resets unless otherwise specified in the Features table. [Figure 9](#) defines the Set Features behavior and timings.

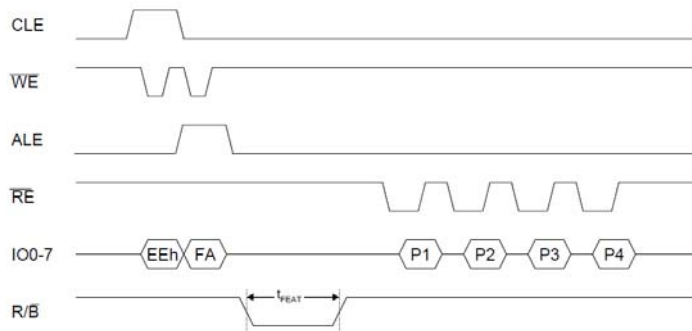
**Figure 9. Set Features Timing**<sup>[18, 19, 20, 21, 22]</sup>



### 3.19.2 Get Features

The Get Features function is the mechanism the host uses to determine the current settings for a particular feature. This function will return the current settings for the feature (including modifications that may have been previously made with the Set Features function). After reading the first byte of data, the host must complete reading all desired data before issuing another command (including Read Status or Read Status Enhanced). [Figure 10](#) defines the Get Features behavior and timings.

**Figure 10. Get Features Timing**<sup>[23, 24, 25, 26, 27, 28]</sup>



**Notes**

- 18. FA Feature address identifying feature to modify settings for.
- 19. P1-P4 Parameters identifying new settings for the feature specified.
- 20. P1 Sub feature parameter 1
- 21. P2 Sub feature parameter 2
- 22. P3 Sub feature parameter 3
- 23. FA Feature address identifying feature to return parameters for.
- 24. P1-P4 Current settings/parameters for the feature identified by argument P1.
- 25. P1 Sub feature parameter 1 setting.
- 26. P2 Sub feature parameter 2 setting.
- 27. P3 Sub feature parameter 3 setting.
- 28. P4 Sub feature parameter 4 setting.



### 3.19.3 Feature Parameter Definitions

**Table 16. Feature Address Definition**

| Feature Address | Description     |
|-----------------|-----------------|
| 00h             | Reserved        |
| 01h             | Timing Mode     |
| 02h-7Fh         | Reserved        |
| 80h-FFh         | Vendor specific |

**Table 17. Feature Address 90h-Array Operation Mode (P1 Register)<sup>[29, 30]</sup>**

| Bits | Field Name     | Function                        | Default Value | Description   |
|------|----------------|---------------------------------|---------------|---|
| 7    | Reserved       |                                 | 0             |   |
| 6    | Reserved       |                                 | 0             |   |
| 5    | Reserved       |                                 | 0             |   |
| 4    | ECC_STATUS_SEL | ECC Status register Flag Select | 0             | 0: Flag1 (Default)<br>1: Flag2<br>This bit selects the ECC status register Flag.  |
| 3    | Reserved       |                                 | 1             | This bit must always be set to "1".   |
| 2    | Reserved       |                                 | 0             |   |
| 1    | OTP_LOCK_EN    | OTP Protection Enable           | 0             | 1: Set OTP Protection (Lock).<br>0: Power on value<br><br>The OTP protection is irreversible and becomes effective only if OTP mode is enabled. |
| 0    | OTP_MODE_EN    | OTP Mode Enable                 | 0             | 0: Normal (Array operation)<br>1: OTP mode enable   |

**Notes**

29. P2/P3/P4 are 00h.

30. A software reset command (FFh) does not alter the content of the 90h feature register.

## 4. Security Features

The security features below provide block protection from program and erase operations.

Two security methods are supported:

- Volatile Block Protection (VBP).

The VBP parameter settings are volatile. Power cycling will reset the settings to the default status (all blocks protected if VPE pin is high). This VBP method can protect one range of contiguous blocks.

This method requires use of a Volatile Protection Enable (VPE) input pin. To activate the VBP method using the VPE input, the host must power up the device with VPE input high during the Power-On Reset (POR) period and issue a set of commands to set the VBP parameter settings which consist of a Lower Boundary Address (LB\_ADD) and an Upper Boundary Address (UB\_ADD).

- Permanent Block Protection (PBP)

The PBP parameter settings are non-volatile. These settings will be maintained after a power cycle. The PBP method can protect up to 64 blocks (block 0 to 63) organized in groups of 4 contiguous blocks. Each group can be protected individually and are permanently protected. Once a group is protected, the group can no longer be unprotected.

### 4.1 Volatile Block Protection (VBP) Overview

The VBP feature can protect all blocks, or one selected range of contiguous blocks, from erase and program operations. The VBP parameter settings are reset to default value after a power-cycle (all blocks protected if VPE input is high) and must be re-programmed by the host.

The VPE input level, latched during Power-On Reset (POR), determines whether the VBP is enabled or disabled. If the VPE input is low at power-on, the VBP feature is disabled and the Write Protect (WP#) input controls the protection of all blocks. If the VPE input is high at power-on, all blocks are protected from programming or erasing even if the WP# input is high. VPE must be high (VPE=H) when issuing all VBP function commands. See [Figure 54](#) and [Figure 55](#).

The Unlock Block commands (23h & 24h) are used to unprotect a range of blocks. The Unlock Block commands set the protection registers (UB\_ADD and LB\_ADD).

Once the selected blocks are unprotected, those blocks can be protected again by using a Lock All Blocks (2Ah) commands or by asserting WP# low for more than 100ns.

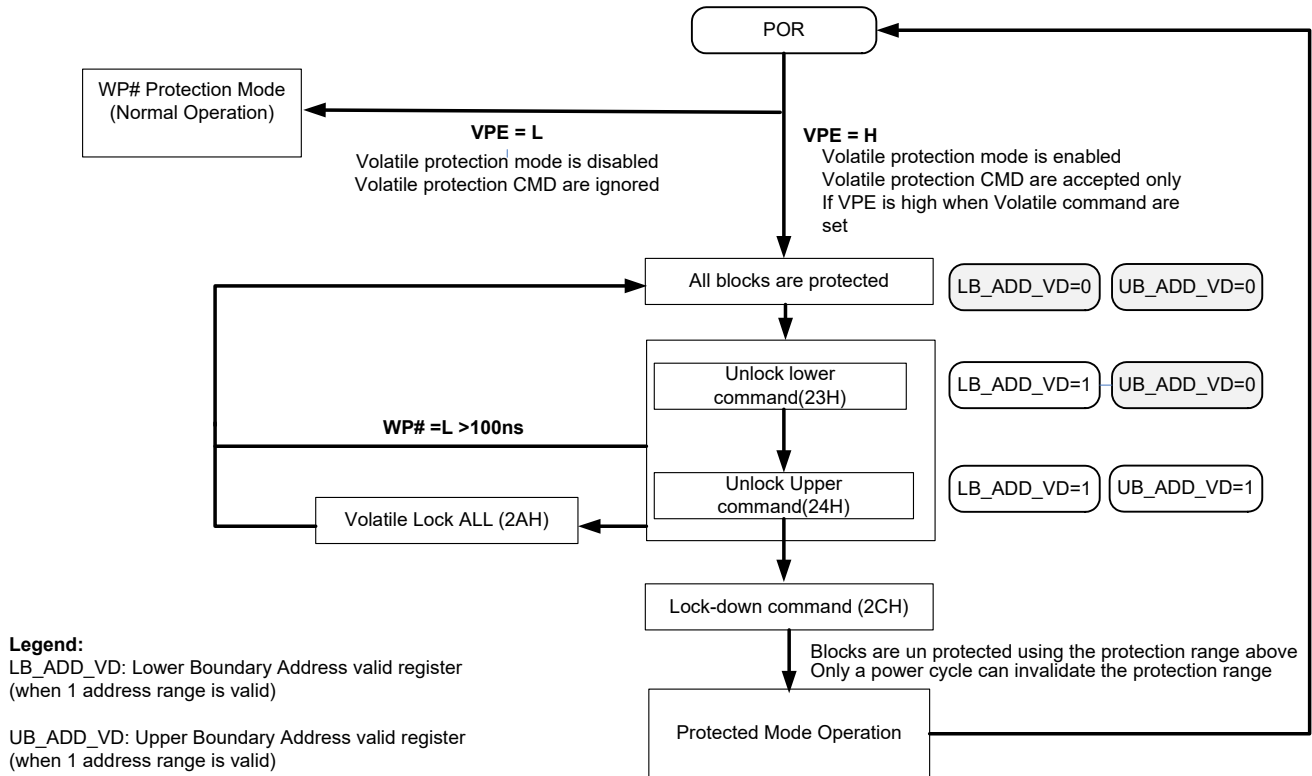
Once the selected blocks are unprotected, the host can issue a Lock-down command (2Ch) to lock the VBP protection range configuration until the next power off to on cycle.

After, the Lock-down command is issued:

- VPE signal value and the VBP commands are ignored until the next power cycle.
- WP# can be used to protect all the blocks from program and erase, but will no longer invalidate the volatile protection parameter registers.

Figure 11 provides an overview of the VBP mechanism.

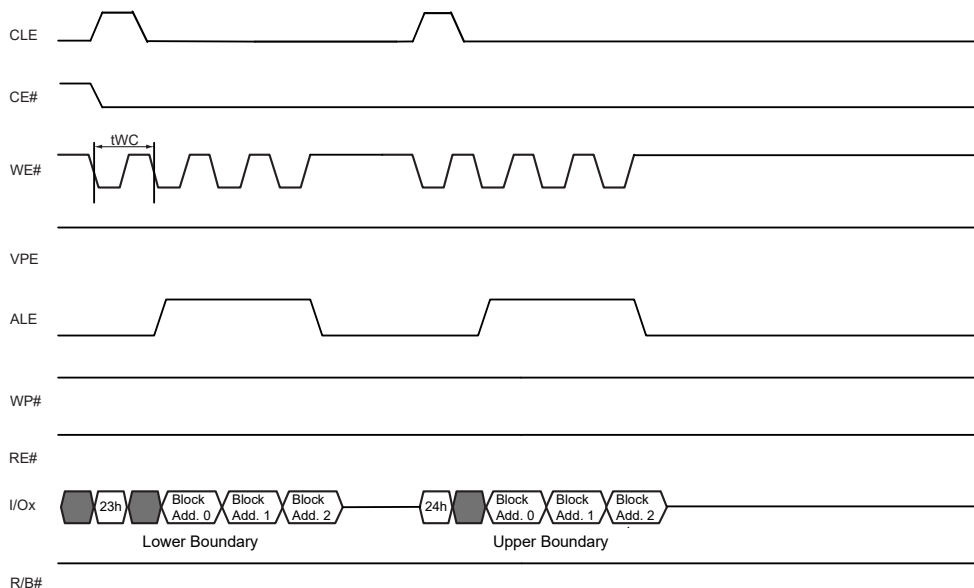
Figure 11. VBP Flowchart



### 4.1.1 VBP Unlock Block (23h and 24h) Commands Waveforms

The Unlock Block commands define the range of blocks to be unprotected. The Unlock Lower command (23h) sets the lower block address, and must be followed by the Unlock Upper command (24h) that sets the upper block address (see Figure 12).

Figure 12. Waveforms for Block Unprotect



To unprotect the complementary range of block (see Figure 13), the host can set an invert-bit in the Unlock command address field (see Table 18). If the invert-bit is set to 0, the unprotected area is within and inclusive of the upper and lower block addresses; if the bit is set to 1, the unprotected area is outside and exclusive of the upper and lower block addresses.

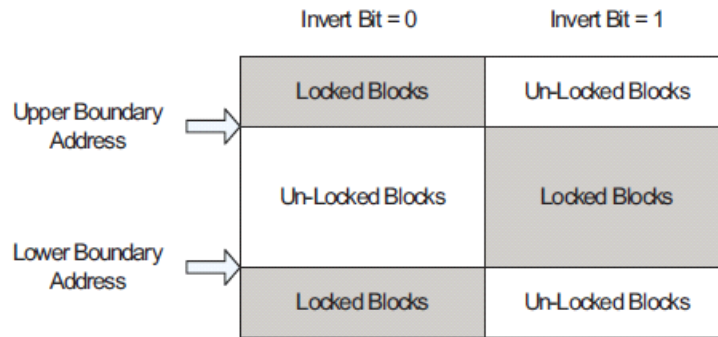
**Table 18. Address Definition of Unlock Block**

| Address Cycle Mapping          |           |       |       |       |       |       |       |        |                 |
|--------------------------------|-----------|-------|-------|-------|-------|-------|-------|--------|-----------------|
|                                | Bus Cycle | IO[7] | IO[6] | IO[5] | IO[4] | IO[3] | IO[2] | IO[1]  | IO[0]           |
| Block Address 1                | 1st       | BA[1] | BA[0] | L     | L     | L     | L     | L      | Invert Bit (31) |
| Block Address 2                | 2nd       | BA[9] | BA[8] | BA[7] | BA[6] | BA[5] | BA[4] | BA[3]  | BA[2]           |
| Block Address 3                | 3rd       | L     | L     | L     | L     | L     | L     | BA[11] | BA[10]          |
| BA[0] controls plane selection |           |       |       |       |       |       |       |        |                 |

**Note**

31. The Invert bit is set by 24h command to select whether the unprotected range is inside or outside of the range boundary. The bit is a don't care for the 23h command.

**Figure 13. Unlock Range Option**



In multiplane operations, the lower and upper address range BA[0] is internally respectively set to 0 and 1. For instance if a block range being protected is defined to be between 1 and 4, the device will protect block 0 to 5.

Table 19 illustrates how internally the blocks are being protected for single and multiplane operations (shaded area) when the lower and upper addresses are respectively set to 1 and 4.

**Table 19. Single and Dual Plane Block Protection Example<sup>[32]</sup>**

| Single Plane Operation |         | Multiplane Operation |         |
|------------------------|---------|----------------------|---------|
| Block 0                | Block 1 | Block 0              | Block 1 |
| Block 2                | Block 3 | Block 2              | Block 3 |
| Block 4                | Block 5 | Block 4              | Block 5 |

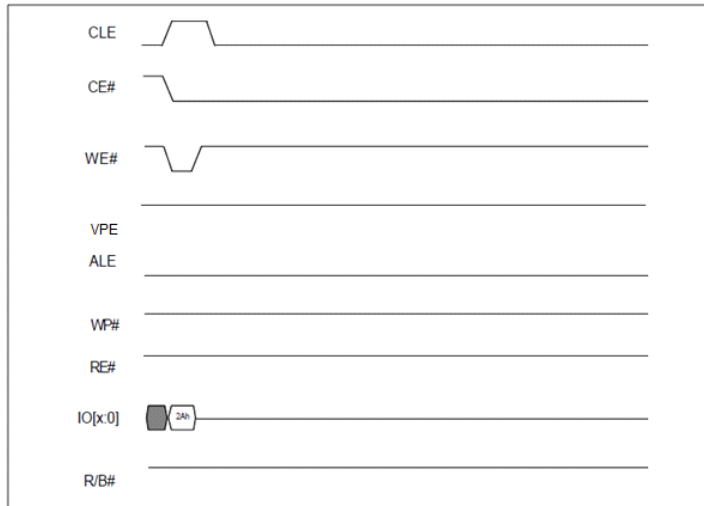
**Note**

32. Shaded boxes are protected by VBP.

### 4.1.2 VBP Lock All (2Ah) Command Waveforms

The Lock All command (2Ah) can be used to protect all the blocks in the device. This command is useful to program a new unprotected range as shown in [Figure 11](#).

Figure 14. Waveforms for Lock All Blocks



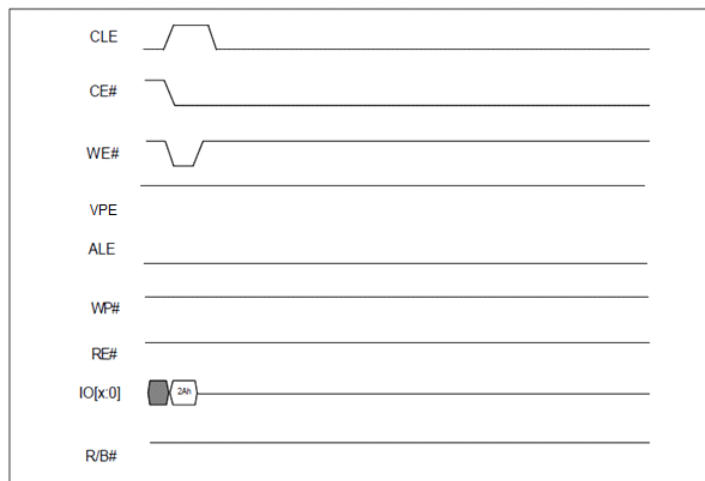
### 4.1.3 VBP Lock-down (2Ch) Command Waveforms

The Lock-down Command (2Ch) maintains the block protection parameters at the time the command is issued; the protected blocks cannot be unprotected and the unprotected blocks cannot be protected by software. Once the Lock-down command is issued, only a power off to power on cycle will change the block protection status by returning to the default state (all blocks protected state if VPE input is high on power on). The WP# input and VPE input must be high before issuing the Lock-down command.

After, the Lock-down command is issued:

- VPE signal value and the VBP commands are ignored until the next power cycle or hardware reset.
- WP# can be used to protect all the blocks from program and erase, but will no longer invalidate the volatile protection parameter registers.

Figure 15. Waveforms for the Lock-down Command



## 4.2 Permanent Block Protection (PBP) Overview

The Permanent Block Protection (PBP) feature provides protection of up to sixteen groups (64 blocks total) from program and erase operations.

The device ships from the factory with no blocks protected by the PBP method.

Because this block protection is permanent, a power-on to power-off sequence does not affect the block protection status after the PBP command is issued.

The PBP method is used to select a group of blocks in the main array to be protected from program and erase operation. Multiple groups of blocks can be protected. Once a group of blocks is protected, the group of blocks can no longer be unprotected.

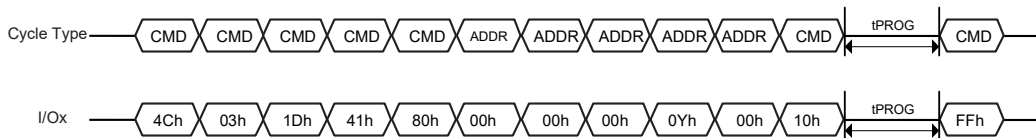
Additional unprotected groups can still be protected using the PBP sequence until the host issues a Permanent Block Protection Lock-down (PBPLDL) command.

When this PBPLDL command is issued, all groups of blocks protected by PBP are permanently protected from program and erase operations and a PBP operation can no longer be used to protect additional groups.

Issuing of the PBPLD sequence will both protect and lock down the protected group. Each PBP and PBPLDL sequence must be exited using the reset command (FFh).

The timing diagram in [Figure 16](#) shows the PBP sequence.

**Figure 16. Timing Diagram for the PBP Sequence**



The group of blocks being protected is determined by the value of Y (see [Table 20](#)) on the fourth address cycle.

During PBP PGM busy, if FFh or power-off occurs, PBP cannot be guaranteed.

**Table 20. Fourth Address Cycle (ADDR 4) Protection Scheme Table**

| Y Value | Protected Group | Protected Blocks |
|---------|-----------------|------------------|
| 0000    | 0               | 0,1,2,3          |
| 0001    | 1               | 4,5,6,7          |
| 0010    | 2               | 8,9,10,11        |
| 0011    | 3               | 12,13,14,15      |
| 0100    | 4               | 16,17,18,19      |
| 0101    | 5               | 20,21,22,23      |
| 0110    | 6               | 24,25,26,27      |
| 0111    | 7               | 28,29,30,31      |
| 1000    | 8               | 32,33,34,35      |
| 1001    | 9               | 36,37,38,39      |
| 1010    | 10              | 40,41,42,43      |
| 1011    | 11              | 44,45,46,47      |
| 1100    | 12              | 48,49,50,51      |
| 1101    | 13              | 52,53,54,55      |
| 1110    | 14              | 56,57,58,59      |
| 1111    | 15              | 60,61,62,63      |

**Note** Maximum number of PBP and PBPLDL sequences allowed are 16. Any generated sequence is considered as one attempt. The user should avoid issuing a sequence to protect a group that was previously protected.

**Table 21. PBP and PBPLDL Sequences**

| Description     | Entry Sequence |            |            |            | CMD Cycle | Address Cycles          | CMD Cycle | Read Status or Monitor RB# Output Cycles       | Reset (Exit) |
|-----------------|----------------|------------|------------|------------|-----------|-------------------------|-----------|--|--------------|
| PBP sequence    | CMD1 (4Ch)     | CMD2 (03h) | CMD3 (1Dh) | CMD4 (41h) | 80h       | 00h, 00h, 00h, 0Yh, 00h | 10h       | 70h or 78h (Program Operation forces RDBY low) | FFh          |
| PBPLDL sequence | CMD1 (4Ch)     | CMD2 (03h) | CMD3 (1Dh) | CMD4 (41h) | 80h       | 00h, 00h, 00h, 1Y, 00h  | 10h       | 70h or 78h (Program Operation forces RDBY low) | FFh          |

### 4.2.1 Block Protection Status Read command (7Ah) Waveform

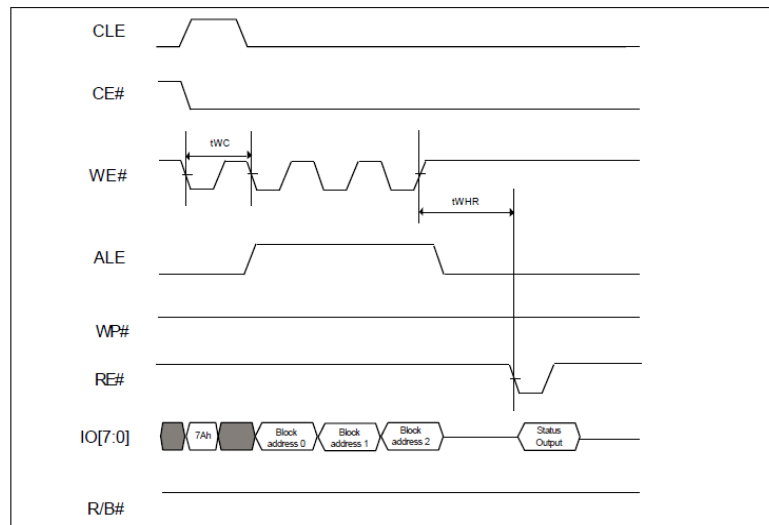
Figure 17 shows the Block Protection Status Read waveform. The Block Protection Status Read command (7Ah) is followed by 3 address cycles and one data cycle.

This register indicates whether a given block (addressed in the Block protection read address command field: BA[11:0]) is locked-down, locked or unlocked using the VBP or PBP protection methods.

| Address Cycle Mapping for Block Protection Read Command (7Ah) |           |       |       |       |       |       |       |        |        |
|---|-----------|-------|-------|-------|-------|-------|-------|--------|--------|
|   | Bus Cycle | IO[7] | IO[6] | IO[5] | IO[4] | IO[3] | IO[2] | IO[1]  | IO[0]  |
| Block Address 0   | 1st       | BA[1] | BA[0] | L     | L     | L     | L     | L      | L      |
| Block Address 1   | 2nd       | BA[9] | BA[8] | BA[7] | BA[6] | BA[5] | BA[4] | BA[3]  | BA[2]  |
| Block Address 2   | 3rd       | L     | L     | L     | L     | L     | L     | BA[11] | BA[10] |

BA[0] controls plane selection.

**Figure 17. Waveforms for Block Protection Status Read Operation**



### 4.2.2 Block Lock Status Register

This register indicates whether a given block (addressed in the Block protection read address command field) is locked-down, locked or unlocked using the VBP or PBP protection methods.

Table 22 provides the BLS register definition.

**Table 22. Block Lock Status Register**

| Bits | Function                          | Field Name              | Default State | Description  |
|------|-----------------------------------|-------------------------|---------------|--|
| 7    | Reserved                          | Reserved                | 0             |  |
| 6    | Reserved                          | Reserved                | 0             |  |
| 5    | Reserved                          | Reserved                | 0             |  |
| 4    | PBP Lock Down Status              | PBP lock down Status    | 0             | 0: The PBP block range is not locked down by PBP<br>1: The PBP block range is locked down by PBP     |
| 3    | Permanent Block Protection Status | Permanent Block Protect | 1             | 0: The address selected block is locked by PBP<br>1: The address selected block is not locked by PBP |
| 2    | Volatile Block Protection Status  | VBP Block-unlock        | 1             | 0: The address selected block is locked by VBP<br>1: The address selected block is not locked by VBP |
| 1    |                                   | VBP Not Locked-down     | 1             | 0: The VBP block range is locked down<br>1: The VBP block range is not locked down                   |
| 0    |                                   | VBP Lock-down           | 0             | 0: The VBP block range is not locked down<br>1: The VBP block range is locked down                   |



## 5. Signal Descriptions

### 5.1 Data Protection and Power On / Off Sequence

The device is designed to offer protection from any involuntary program/erase during power-transitions. An internal voltage detector disables all functions whenever VCC is below about 1.8V.

The power-up and power-down sequence is shown in Figure 54, Figure 55, and Figure 56.

The Ready/Busy signal will be valid within 100 μs after the power supplies have reached the minimum values (as specified on). The RESET command (FFh) must be issued to all targets as the first command after the NAND device is powered up and R/B# becomes valid. Issuing of FFh command after Power Up Sequence allows Auto CAM read of the device. Each target (CE) will be busy for a maximum of 2 ms after the RESET command (FFh) is issued.

The RESET busy time can be monitored by polling R/B# or issuing the READ STATUS (70h) command. In the case where multi LUNs shared the same CE, Read Status Enhanced command should be used instead of READ STATUS. During this busy time, the device executes the initialization process (cam reading), and dissipates a current ICC0 (50 mA max), in addition, it disregards all commands excluding Read Status Register (70h).

Each NAND die (LUN) draws less than 10 mA for over 1 ms before the execution of the first RESET command (FFh) after the device is powered up. During the power up sequence including the RESET busy time, each LUN consumes a maximum current of 50 mA.

At the end of this busy time, the device defaults into “read setup”, thus if the user decides to issue a page read command, the 00h command may be skipped.

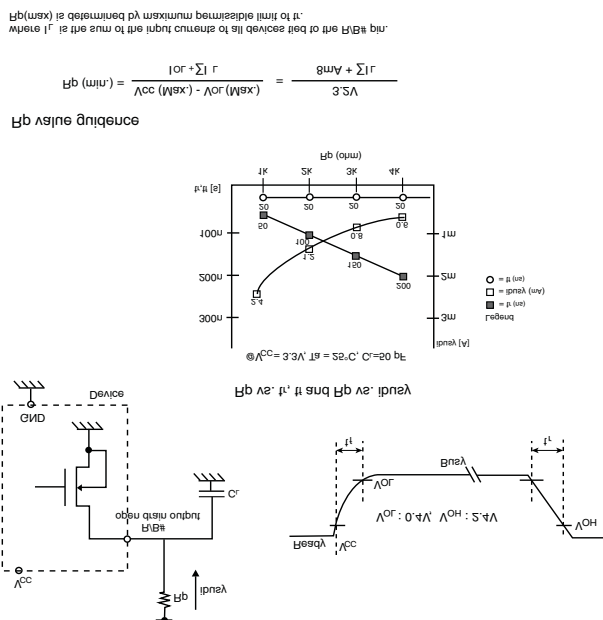
The WP# pin provides hardware protection and is recommended to be kept at V<sub>IL</sub> during power-up and power-down.

### 5.2 Ready/Busy

The Ready/Busy output provides a method of indicating the completion of a page program, erase, copyback, or read completion. The R/B# pin is normally high and goes to low when the device is busy (after a reset, read, program, or erase operation). It returns to high when the internal controller has finished the operation. The pin is an open-drain driver thereby allowing two or more R/B# outputs to be Or-tied. Because the pull-up resistor value is related to t<sub>r</sub> (R/B#) and the current drain during busy (ibusy), and output load capacitance is related to t<sub>f</sub>, an appropriate value can be obtained with the reference chart shown in Figure 18.

For example, for a particular system with 20 pF of output load, t<sub>r</sub> from V<sub>CC</sub> to V<sub>OL</sub> at 10% to 90% will be 10 ns, whereas for a particular load of 50 pF, SkyHigh measured it to be 20 ns as shown in Figure 18.

Figure 18. Ready/Busy Pin Electrical Application

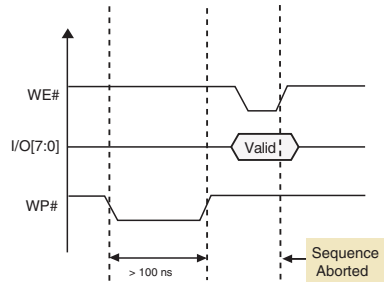


### 5.3 Write Protect Operation

Erase and program operations are aborted if WP# is driven low during busy time, and kept low for about 100 ns. Switching WP# low during this time is equivalent to issuing a Reset command (FFh). The contents of memory cells being altered are no longer valid, as the data will be partially programmed or erased. The R/B# pin will stay low for  $t_{RST}$  (similarly to Figure 46). At the end of this time, the command register is ready to process the next command, and the Status Register bit I/O6 will be cleared to 1, while I/O7 value will be related to the WP# value.

Erase and program operations are enabled or disabled by setting WP# to high or low respectively, before issuing the setup commands (80h or 60h). The level of WP# will be set  $t_{WW}$  ns before raising the WE# pin for the set up command, as explained in Figure 57 and Figure 58.

Figure 19. WP# Low Timing Requirements during Program/Erase Command Sequence



## 6. Electrical Characteristics

### 6.1 Valid Blocks

**Table 23. Valid Blocks**

| Device    | Symbol   | Min  | Typ | Max  | Unit   |
|-----------|----------|------|-----|------|--------|
| S34ML04G3 | $N_{VB}$ | 4016 | —   | 4096 | Blocks |

### 6.2 Absolute Maximum Ratings

**Table 24. Absolute Maximum Ratings<sup>[33, 35]</sup>**

| Parameter   | Symbol        | Value        | Unit |
|---|---------------|--------------|------|
| Ambient Operating Temperature (Industrial Temperature Range)      | $T_A$         | -40 to +85   | °C   |
| Ambient Operating Temperature (Industrial Plus Temperature Range) | $T_A$         | -40 to +105  | °C   |
| Temperature under Bias  | $T_{BIAS}$    | -50 to +125  | °C   |
| Storage Temperature   | $T_{STG}$     | -65 to +150  | °C   |
| Input or Output Voltage   | $V_{IO}$ (34) | -0.6 to +4.6 | V    |
| Supply Voltage  | $V_{CC}$      | -0.6 to +4.6 | V    |

**Notes**

33. Except for the rating "Operating Temperature Range", stresses above those listed in the table *Absolute Maximum Ratings*[33, 35] "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the Operating sections of this specification is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

34. Minimum Voltage may undershoot to -2V during transition and for less than 20 ns during transitions.

35. Maximum Voltage may overshoot to  $V_{CC} + 2.0V$  during transition and for less than 20 ns during transitions.

### 6.3 Recommended Operating Conditions

**Table 25. Recommended Operating Conditions**

| Parameter             | Symbol   | Min | Typ | Max | Units |
|-----------------------|----------|-----|-----|-----|-------|
| Vcc Supply Voltage    | $V_{CC}$ | 2.7 | 3.3 | 3.6 | V     |
| Ground Supply Voltage | $V_{SS}$ | 0   | 0   | 0   | V     |

### 6.4 AC Test Conditions

**Table 26. AC Test Conditions**

| Parameter                      | Value                       |
|--------------------------------|-----------------------------|
| Input Pulse Levels             | 0.0 V to $V_{CC}$           |
| Input Rise and Fall Times      | 5 ns                        |
| Input and Output Timing Levels | $V_{CC} / 2$                |
| Output Load (2.7 V–3.6 V)      | 1 TTL Gate and $CL = 50$ pF |

### 6.5 AC Characteristics

**Table 27. AC Characteristics<sup>[36, 37, 38]</sup>**

| Parameter        | Symbol    | Min | Typ | Max | Unit |
|------------------|-----------|-----|-----|-----|------|
| ALE to RE# delay | $t_{AR}$  | 10  | —   | —   | ns   |
| ALE hold time    | $t_{ALH}$ | 5   | —   | —   | ns   |

**Notes**

36. The time to Ready depends on the value of the pull-up resistor tied to R/B# pin.

37. If Reset Command (FFh) is written at Ready state, the device goes into Busy for maximum 5  $\mu$ s.

38. CE# low to high or RE# low to high can be at different times and produce three cases. Depending on which signal comes high first, either  $t_{COH}$  or  $t_{RHOH}$  will be met.

**Table 27. AC Characteristics**<sup>[36, 37, 38]</sup>

| Parameter  | Symbol          | Min | Typ | Max      | Unit    |
|--|-----------------|-----|-----|----------|---------|
| ALE setup time                                     | $t_{ALS}$       | 10  | —   | —        | ns      |
| Address to data loading time                       | $t_{ADL}$       | 70  | —   | —        | ns      |
| CE# low to RE# low                                 | $t_{CR}$        | 10  | —   | —        | ns      |
| CE# hold time                                      | $t_{CH}$        | 5   | —   | —        | ns      |
| CE# high to output High-Z                          | $t_{CHZ}$       | —   | —   | 30       | ns      |
| CLE hold time                                      | $t_{CLH}$       | 5   | —   | —        | ns      |
| CLE to RE# delay                                   | $t_{CLR}$       | 10  | —   | —        | ns      |
| CLE setup time                                     | $t_{CLS}$       | 10  | —   | —        | ns      |
| CE# access time                                    | $t_{CEA}$       | —   | —   | 25       | ns      |
| CE# high to output hold                            | $t_{COH}$ (38)  | 15  | —   | —        | ns      |
| CE# high to ALE or CLE don't care                  | $t_{CSD}$       | 10  | —   | —        | ns      |
| CE# setup time                                     | $t_{CS}$        | 15  | —   | —        | ns      |
| Data hold time                                     | $t_{DH}$        | 5   | —   | —        | ns      |
| Data setup time                                    | $t_{DS}$        | 7   | —   | —        | ns      |
| Data transfer from cell to register (Single Plane) | $t_R$           | —   | 45  | 250      | $\mu$ s |
| Data transfer from cell to register (Multi Plane)  |                 | —   | 55  | 450      | $\mu$ s |
| Output High-Z to RE# low                           | $t_{IR}$        | 0   | —   | —        | ns      |
| Read cycle time                                    | $t_{RC}$        | 20  | —   | —        | ns      |
| RE# access time                                    | $t_{REA}$       | —   | —   | 16       | ns      |
| RE# high hold time                                 | $t_{REH}$       | 7   | —   | —        | ns      |
| RE# high to output hold                            | $t_{RHOH}$ (38) | 15  | —   | —        | ns      |
| RE# high to WE# low                                | $t_{RHW}$       | 100 | —   | —        | ns      |
| RE# high to output High-Z                          | $t_{RHZ}$       | —   | —   | 100      | ns      |
| RE# low to output hold                             | $t_{RLOH}$      | 5   | —   | —        | ns      |
| RE# pulse width                                    | $t_{RP}$        | 10  | —   | —        | ns      |
| Ready to RE# low                                   | $t_{RR}$        | 20  | —   | —        | ns      |
| Reset time (Read/Program/Erase)                    | $t_{RST}$       | —   | —   | 5/10/500 | $\mu$ s |
| WE# high to busy                                   | $t_{WB}$        | —   | —   | 100      | ns      |
| Write cycle time                                   | $t_{WC}$        | 20  | —   | —        | ns      |
| WE# high hold time                                 | $t_{WH}$        | 7   | —   | —        | ns      |
| WE# high to RE# low                                | $t_{WHR}$       | 60  | —   | —        | ns      |
| WE# high to RE# low for Random Data Output         | $t_{WHR2}$      | 200 | —   | —        | ns      |
| WE# pulse width                                    | $t_{WP}$        | 10  | —   | —        | ns      |
| Write protect time                                 | $t_{WW}$        | 100 | —   | —        | ns      |

**Notes**

36. The time to Ready depends on the value of the pull-up resistor tied to R/B# pin.

37. If Reset Command (FFh) is written at Ready state, the device goes into Busy for maximum 5  $\mu$ s.

38. CE# low to high or RE# low to high can be at different times and produce three cases. Depending on which signal comes high first, either  $t_{COH}$  or  $t_{RHOH}$  will be met.

## 6.6 DC Characteristics

**Table 28. DC Characteristics and Operating Conditions**<sup>[39, 40, 41, 42]</sup>

| Parameter                         |                 | Symbol          | Test Conditions   | Min                 | Typ | Max                 | Units         |
|-----------------------------------|-----------------|-----------------|---|---------------------|-----|---------------------|---------------|
| Power On Current                  |                 | $I_{CC0}$       | FFh command input after power on  | —                   | —   | 50 per device       | mA            |
| Operating Current                 | Sequential Read | $I_{CC1}$       | $t_{RC} = t_{RC}(\text{min})$<br>$CE\# = V_{IL}$ , $I_{out} = 0 \text{ mA}$ | —                   | 25  | 35                  | mA            |
|                                   | Program         | $I_{CC2}$       | Normal  | —                   | 25  | 35                  | mA            |
|                                   | Erase           | $I_{CC3}$       | —   | —                   | 15  | 30                  | mA            |
| Standby Current, (TTL)            |                 | $I_{CC4}$       | $CE\# = V_{IH}$ ,<br>$WP\# = 0V/V_{CC}$                                     | —                   | —   | 1                   | mA            |
| Standby Current, (CMOS)           |                 | $I_{CC5}$       | $CE\# = V_{CC} - 0.2$ ,<br>$WP\# = 0/V_{CC}$<br>$VPE = 0/V_{CC}$            | —                   | 20  | 100                 | $\mu\text{A}$ |
| Input Leakage Current             |                 | $I_{LI}$        | $V_{IN} = 0 \text{ to } V_{CC}(\text{max})$                                 | —                   | —   | $\pm 10$            | $\mu\text{A}$ |
| Output Leakage Current            |                 | $I_{LO}$        | $V_{OUT} = 0 \text{ to } V_{CC}(\text{max})$                                | —                   | —   | $\pm 10$            | $\mu\text{A}$ |
| Input High Voltage                |                 | $V_{IH}$        | —   | $V_{CC} \times 0.8$ | —   | $V_{CC} + 0.3$      | V             |
| Input Low Voltage                 |                 | $V_{IL}$        | —   | -0.3                | —   | $V_{CC} \times 0.2$ | V             |
| Output High Voltage               |                 | $V_{OH}$        | $I_{OH} = -400 \mu\text{A}$   | 2.4                 | —   | —                   | V             |
| Output Low Voltage                |                 | $V_{OL}$        | $I_{OL} = 2.1 \text{ mA}$   | —                   | —   | 0.4                 | V             |
| Output Low Current (R/B#)         |                 | $I_{OL(R/B\#)}$ | $V_{OL} = 0.4 \text{ V}$  | 8                   | 10  | —                   | mA            |
| Erase and Program Lockout Voltage |                 | $V_{LKO}$       | —   | —                   | 1.8 | —                   | V             |

**Notes**

39. All  $V_{CC}$  pins, and  $V_{SS}$  pins respectively, are shorted together.  
40. Values listed in this table refer to the complete voltage range for  $V_{CC}$  and to a single device in case of device stacking.  
41. All current measurements are performed with a 0.1  $\mu\text{F}$  capacitor connected between the  $V_{CC}$  Supply Voltage pin and the  $V_{SS}$  Ground pin.  
42. Standby current measurement can be performed after the device has completed the initialization process at power up. Refer to Section 5.1 for more details.

## 6.7 Pin Capacitance

**Table 29. Pin Capacitance (TA = 25°C, f = 1.0 MHz)**<sup>[43]</sup>

| Parameter      | Symbol   | Test Condition         | Min | Max | Unit |
|----------------|----------|------------------------|-----|-----|------|
| Input          | $C_{IN}$ | $V_{IN} = 0 \text{ V}$ | —   | 10  | pF   |
| Input / Output | $C_{IO}$ | $V_{IL} = 0 \text{ V}$ | —   | 10  | pF   |

**Note**

43. For the stacked devices version the Input is 10 pF x [number of stacked chips] and the Input/Output is 10 pF x [number of stacked chips].

## 6.8 Thermal Resistance

**Table 30. Thermal Resistance**<sup>[44]</sup>

| Parameter   | Description                              | TS048 | VBM063 | Unit                 |
|-------------|--|-------|--------|----------------------|
| Theta $J_A$ | Thermal Resistance (Junction to Ambient) | 40    | 39     | $^{\circ}\text{C/W}$ |

**Note**

44. Test conditions follow standard methods and procedures for measuring thermal impedance in accordance with EIA/JESD51.

## 6.9 Program / Erase Characteristics

**Table 31. Program / Erase Characteristics<sup>[45]</sup>**

| Parameter  |              | Description                     | Min | Typ | Max | Unit          |
|--|--------------|---------------------------------|-----|-----|-----|---------------|
| Program Time / Multiplane Program Time <sup>[46, 47]</sup> |              | $t_{\text{PROG}}$               | —   | 350 | 600 | $\mu\text{s}$ |
| Dummy Busy Time for Multiplane Program                     |              | $t_{\text{DBSY}}$               | —   | 0.5 | 1   | $\mu\text{s}$ |
| Number of partial Program Cycles in the same page          | Main + Spare | NOP                             | —   | —   | 4   | Cycle         |
| Block Erase Time   |              | $t_{\text{BERS}}$               | —   | 4   | 10  | ms            |
| Busy time for SET FEATURES and GET FEATURES operations     |              | $t_{\text{FEAT}}^{\text{[48]}}$ |     |     | 1   | $\mu\text{s}$ |
| Power on Reset Time  |              | $t_{\text{POR}}$                |     |     | 3   | ms            |

**Notes**

45. Typical program time is defined as the time within which more than 50% of the whole pages are programmed ( $V_{\text{CC}} = 3.3\text{V}$ ,  $25^{\circ}\text{C}$ ).

46. Copy Back Read and Copy Back Program for a given plane must be between odd address pages or between even address pages for the device to meet the program time ( $t_{\text{PROG}}$ ) specification. Copy Back Program may not meet this specification when copying from an odd address page (source page) to an even address page (target page) or from an even address page (source page) to an odd address page (target page).

47.  $t_{\text{PROG}}$  for PBP/OTP has a typical value of  $500\ \mu\text{s}$  and a max value of  $800\ \mu\text{s}$ .

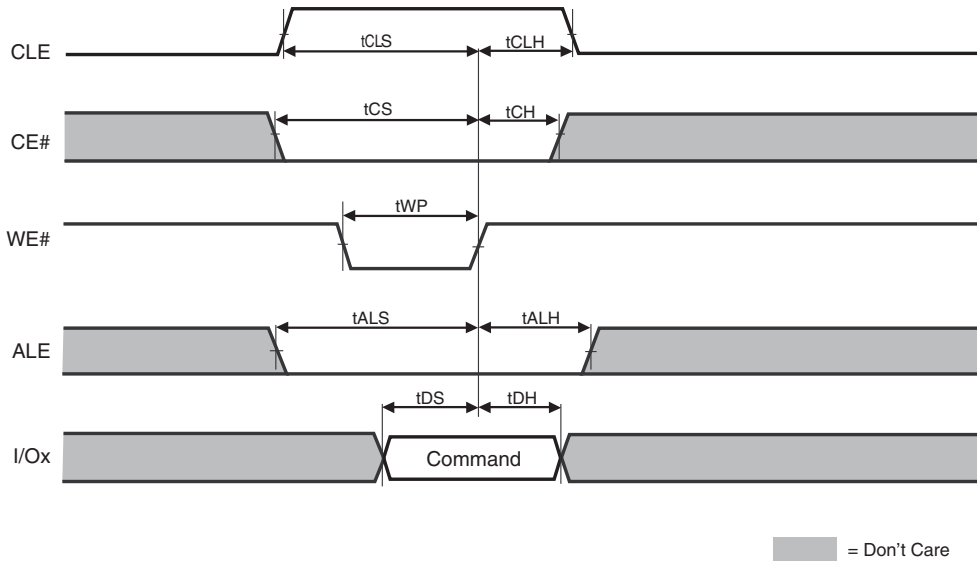
48.  $t_{\text{FEAT}}$  (busy time for SET FEATURES) spec for OTP protection has a typical value of  $500\ \mu\text{s}$  and a max value of  $800\ \mu\text{s}$ .

## 7. Timing Diagrams

### 7.1 Command Latch Cycle

Command Input bus operation is used to give a command to the memory device. Commands are accepted with Chip Enable low, Command Latch Enable High, Address Latch Enable low, and Read Enable High and latched on the rising edge of Write Enable. Moreover for commands that starts a modify operation (write/ erase) the Write Protect pin must be high.

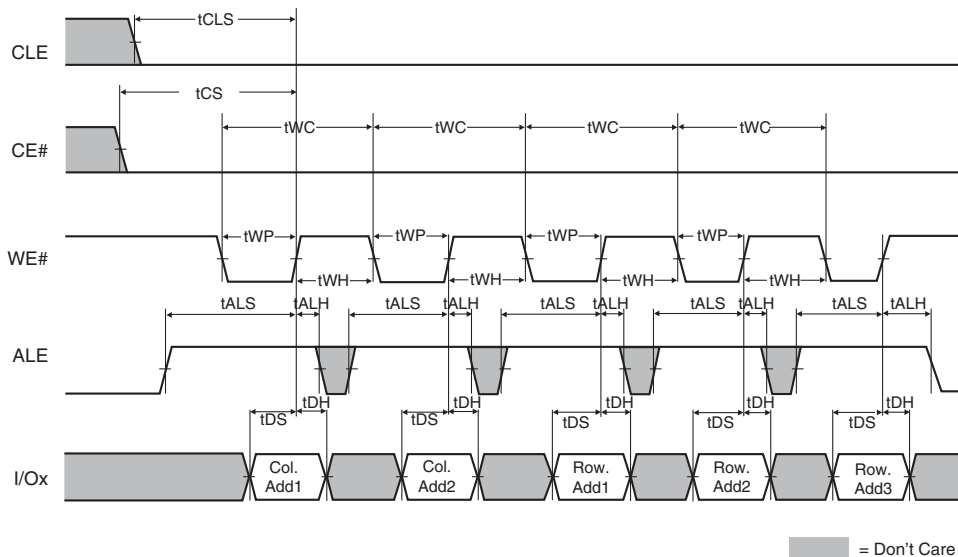
Figure 20. Command Latch Cycle



### 7.2 Address Latch Cycle

Address Input bus operation allows the insertion of the memory address. To insert the 27 ( $\times 8$  Device) addresses needed to access the 1 Gb, four write cycles are needed. Addresses are accepted with Chip Enable low, Address Latch Enable High, Command Latch Enable low, and Read Enable High and latched on the rising edge of Write Enable. Moreover, for commands that start a modify operation (write/erase) the Write Protect pin must be high.

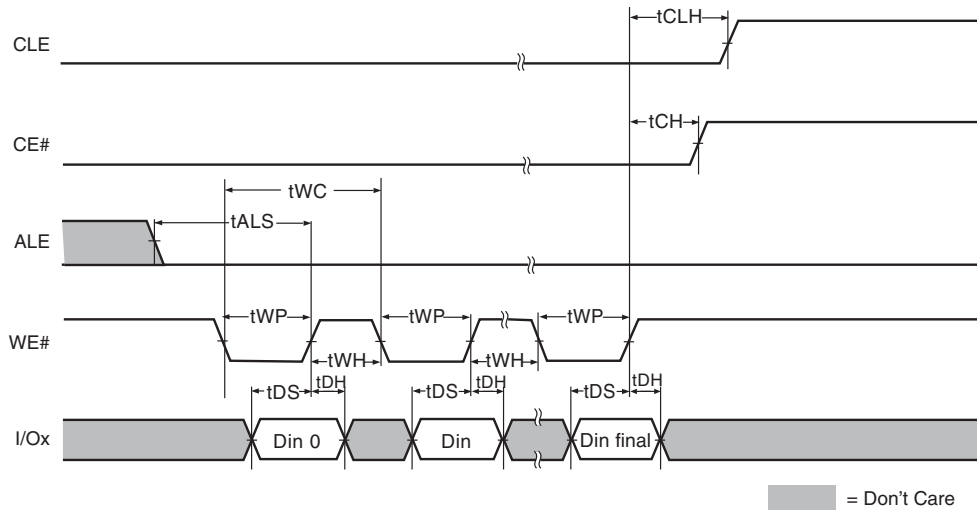
Figure 21. Address Latch Cycle



### 7.3 Data Input Cycle Timing

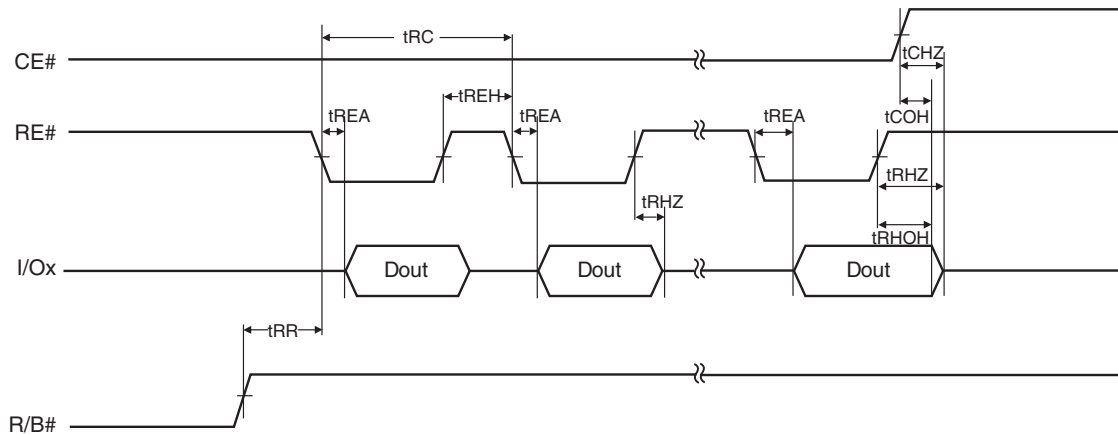
Data Input bus operation allows the data to be programmed to be sent to the device. The data insertion is serially, and timed by the Write Enable cycles. Data is accepted only with Chip Enable low, Address Latch Enable low, Command Latch Enable low, Read Enable High, and Write Protect High and latched on the rising edge of Write Enable.

Figure 22. Input Data Latch Cycle



### 7.4 Data Output Cycle Timing (CLE=L, WE#=H, ALE=L, WP#=H)

Figure 23. Data Output Cycle Timing<sup>[49, 50, 51]</sup>



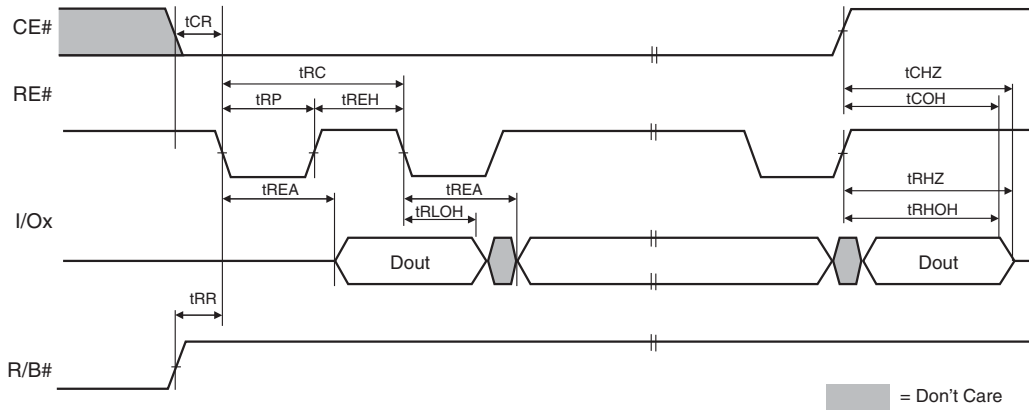
**Notes**

- 49. Transition is measured at ± 200 mV from steady state voltage with load.
- 50. This parameter is sampled and not 100% tested.
- 51. t<sub>RHOH</sub> starts to be valid when frequency is lower than 33 MHz.



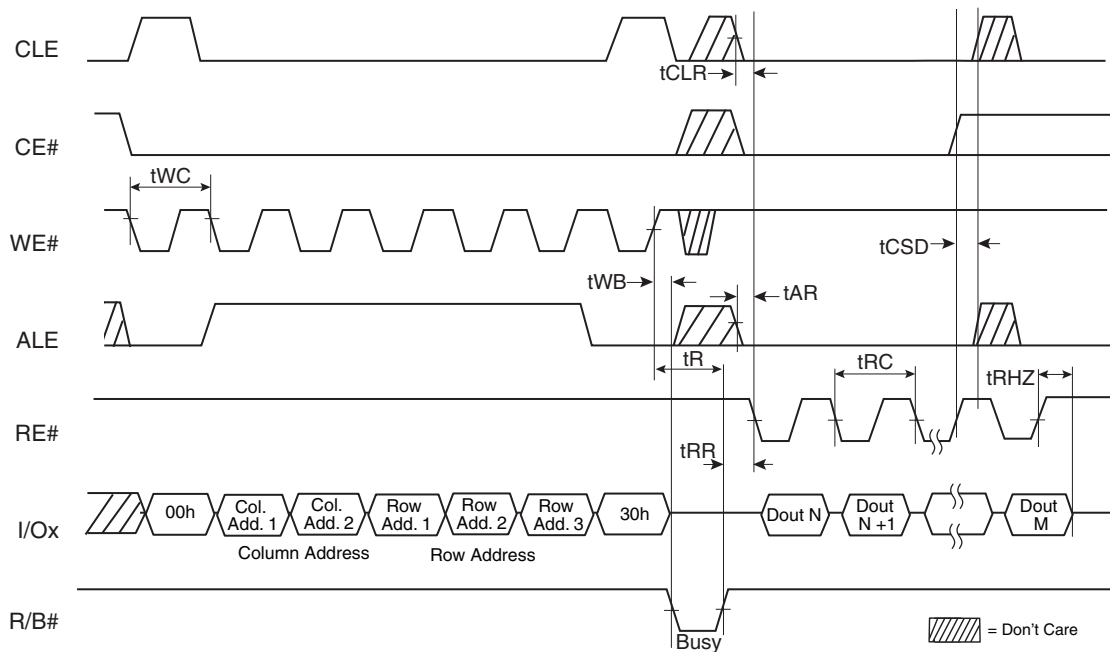
### 7.5 Data Output Cycle Timing (EDO Type, CLE=L, WE#=H, ALE=L)

Figure 24. Data Output Cycle Timing (EDO)<sup>[52, 53, 54, 55]</sup>



### 7.6 Page Read Operation

Figure 25. Page Read Operation (Read One Page)<sup>[56]</sup>

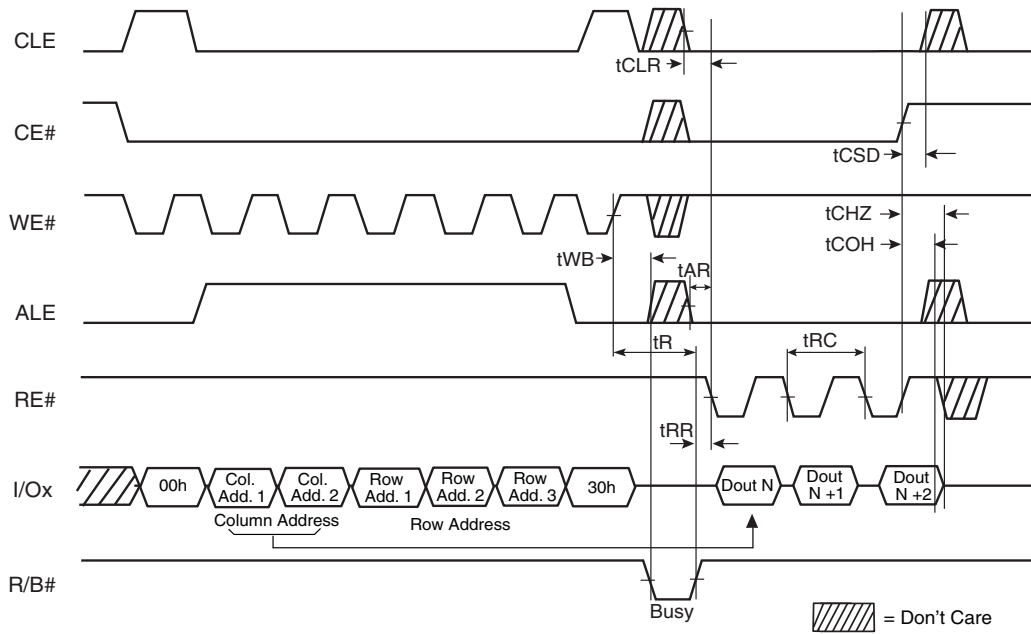


**Notes**

- 52. Transition is measured at  $\pm 200$  mV from steady state voltage with load.
- 53. This parameter is sampled and not 100% tested.
- 54.  $t_{RLOH}$  is valid when frequency is higher than 33 MHz.
- 55.  $t_{RHOH}$  starts to be valid when frequency is lower than 33 MHz.
- 56. If Status Register polling is used to determine completion of the read operation, the Read Command (00h) must be issued before data can be read from the page buffer.

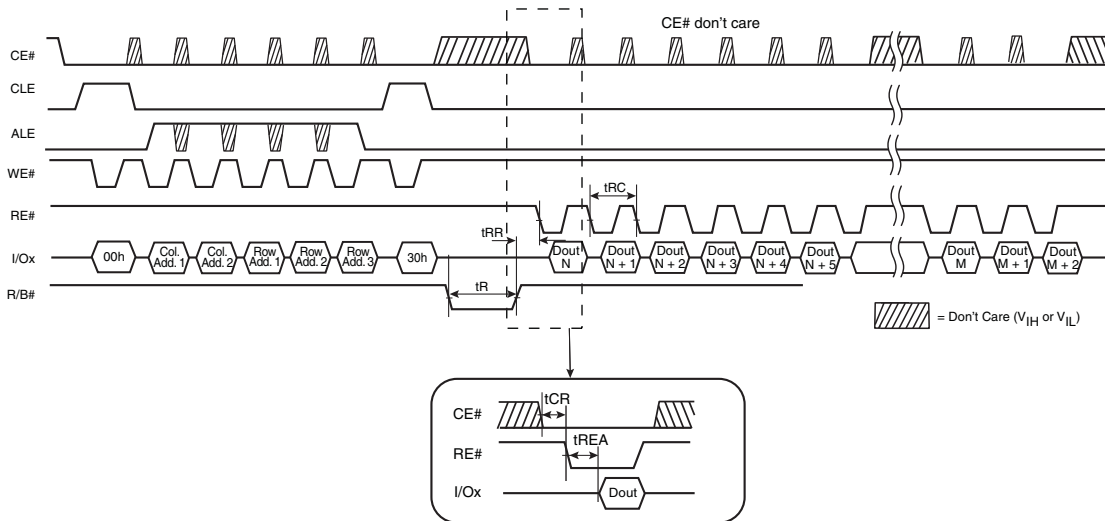
### 7.7 Page Read Operation (Interrupted by CE#)

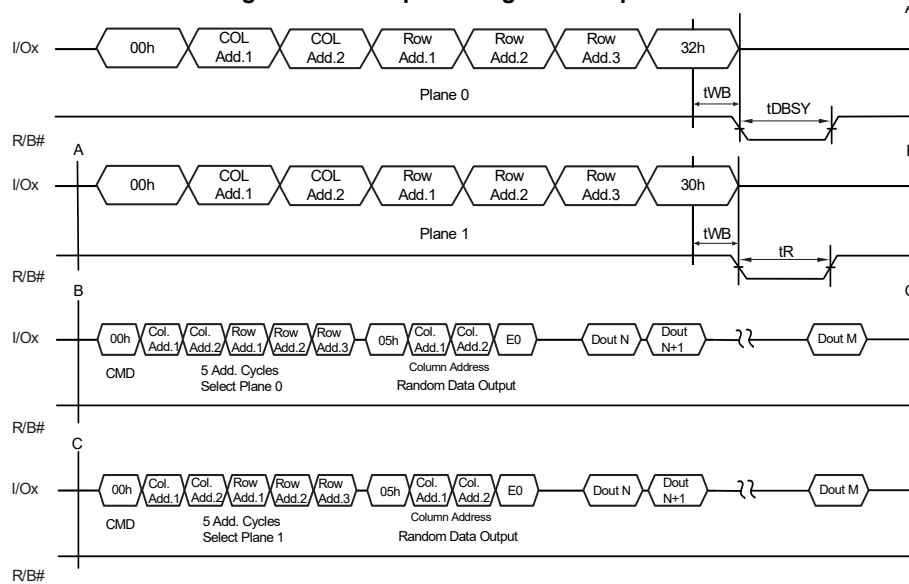
Figure 26. Page Read Operation Interrupted by CE#



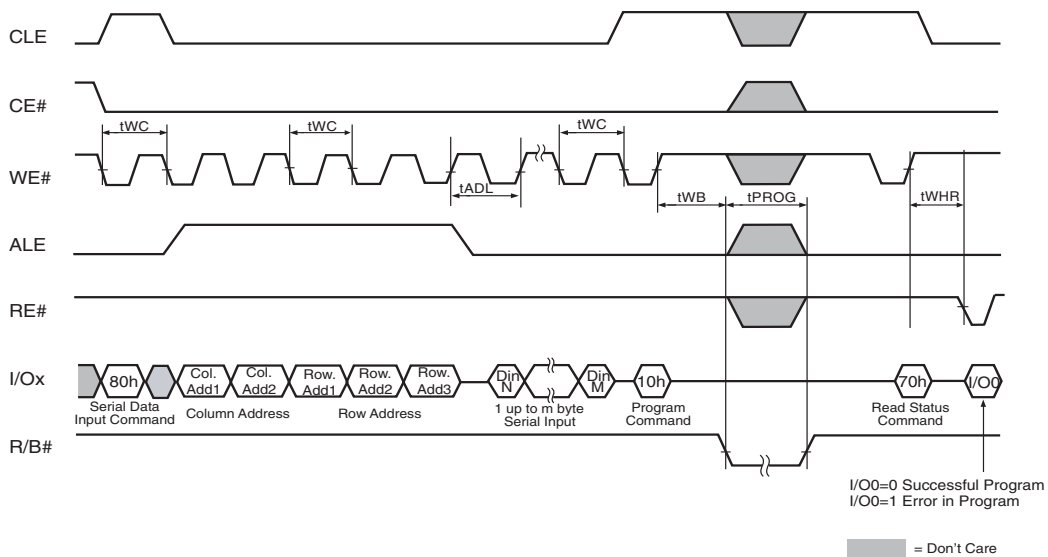
### 7.8 Page Read Operation Timing with CE# Don't Care

Figure 27. Page Read Operation Timing with CE# Don't Care



**Figure 28. Multiplane Page Read Operation**


## 7.9 Page Program Operation

**Figure 29. Page Program Operation<sup>[57]</sup>**

**Note**

57.  $t_{ADL}$  is the time from the WE# rising edge of final address cycle to the WE# rising edge of first data cycle.

### 7.10 User Spare Program

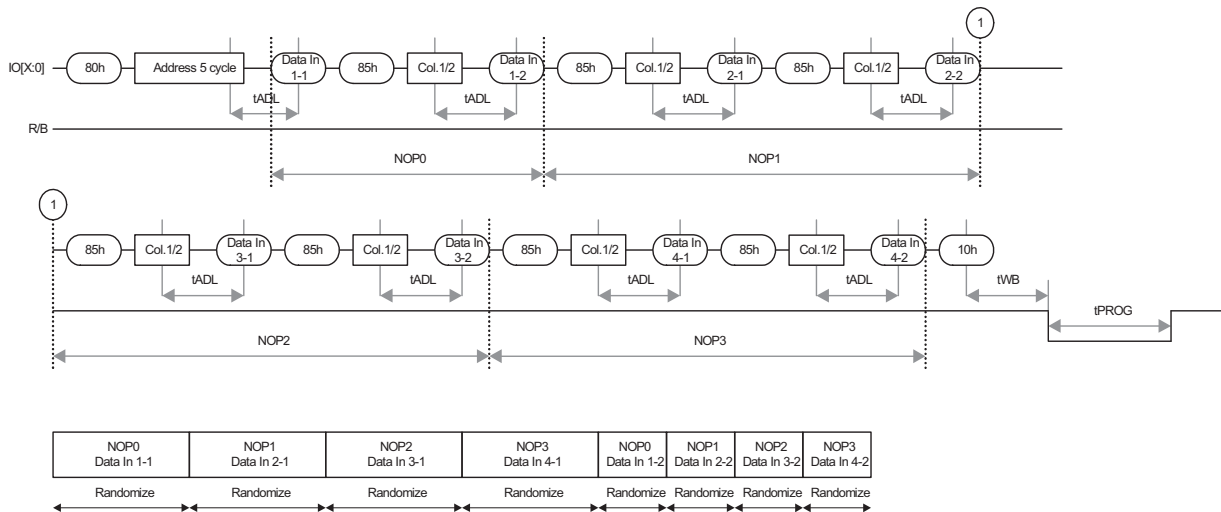
The number of consecutive partial page programming operations within the same page must not exceed 4. for example, 2 times for main array (1time/512byte) and 2 times for spare array (1time/32byte) in the case of 2KB Page. Number of Program (NOP) refers to main area that is divided and programmed in each number of partial program operation.

During NOP program, data that is designated to user spare area must use random data input to change column address. Because NOP is allowed in maximum of 4 times, user spare area is also divided into 4 regions to match up to each NOP area. Main data is divided using NOP, and randomized while programming the data. Although user spare that is included in each NOP is also randomized, randomization done between main data and user spare are different as shown in Figure 30. Therefore, for each NOP, column address change should match up correct NOP with NOP user spare.

First, input 512 bytes of data for NOP0; then, input user spare data for NOP0 after changing of column address using Random Data Input. After programming data, use Random Data Input to return back to starting address of NOP1 main data. Secondly, input 512 bytes of NOP1 data, using Random Data Input to change column address to user spare data for NOP1 input. After programming user spare data for NOP1, return to starting address of NOP2 main data. NOP2 and NOP3 must follow the same process. Both main data and user spare should be input at the same time for NOP operation; otherwise, data is not guaranteed.

If user decide to follow the same order as programming order during data out, read out NOP0 area first, then use Random Data Output to change column address to read out NOP0 user spare area.

Figure 30. Random Data Input Timings



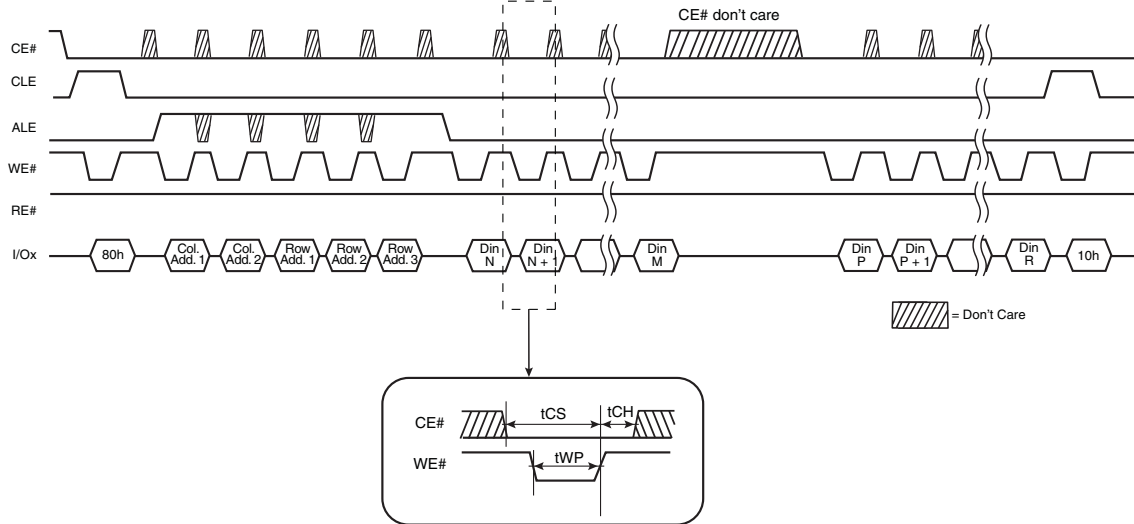
### 7.11 Small Data Input Guidelines

Small data input is allowed within an NOP provided that it meets the following conditions:

- Data size must be a minimum of 4 bytes or greater within single NOP.
- Data input column address must start from xxxx0h, xxx4h, xxx8h, and xxxCh.

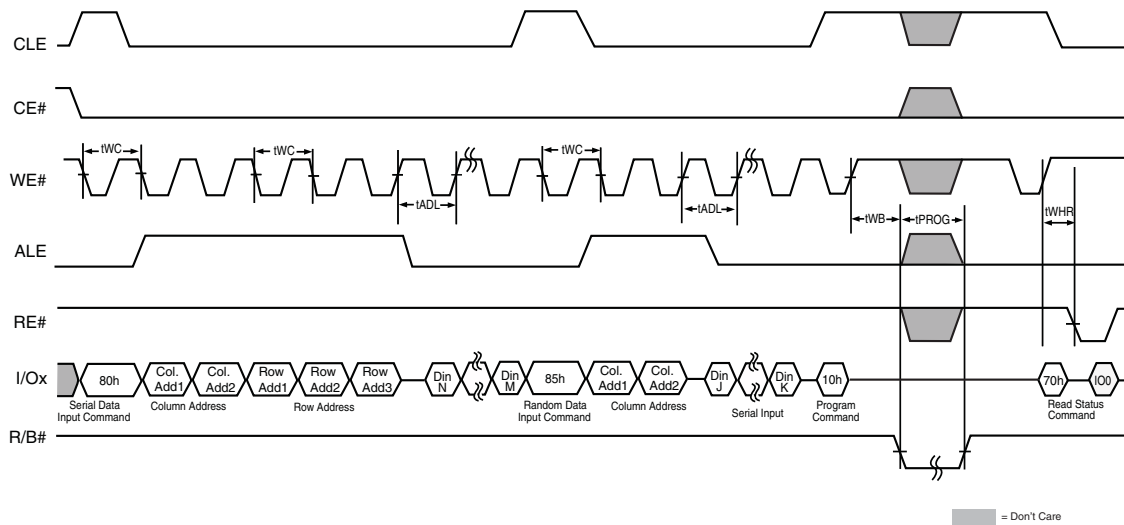
### 7.12 Page Program Operation Timing with CE# Don't Care

Figure 31. Page Program Operation Timing with CE# Don't Care



### 7.13 Page Program Operation with Random Data Input

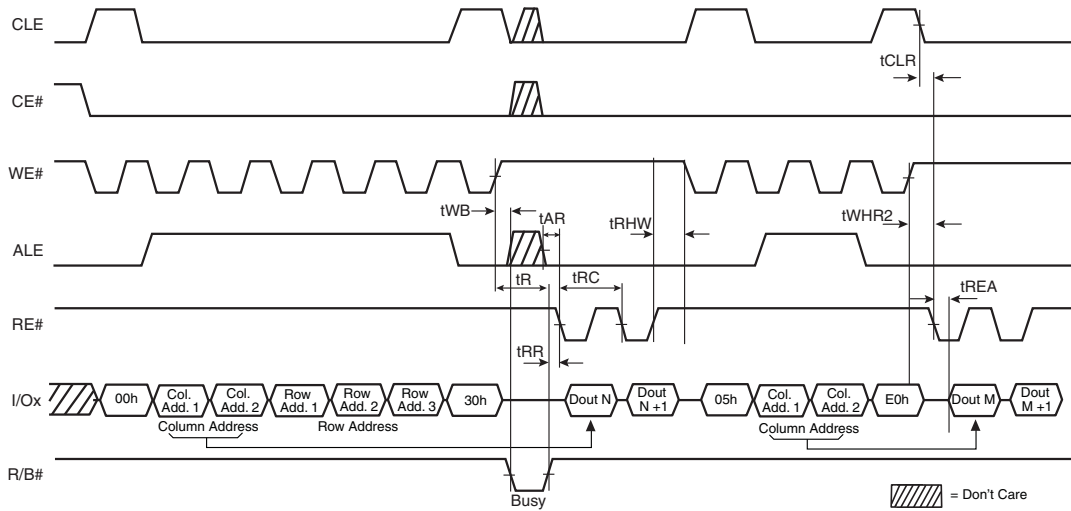
Figure 32. Random Data Input<sup>[58]</sup>



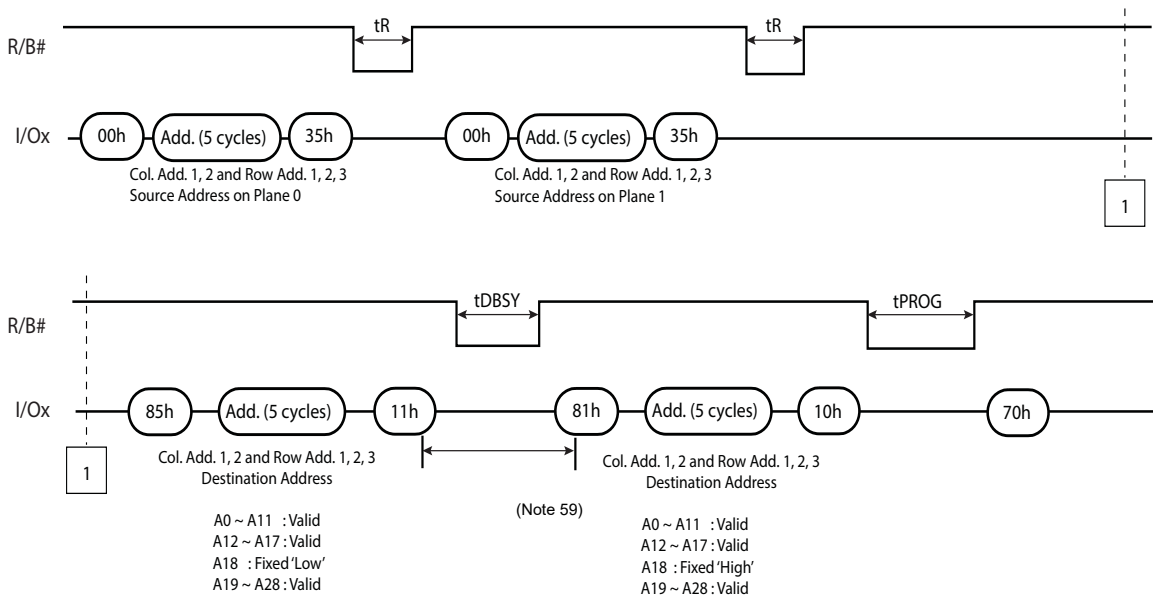
**Note**

58.  $t_{ADL}$  is the time from the WE# rising edge of final address cycle to the WE# rising edge of first data cycle.

### 7.14 Random Data Output In a Page

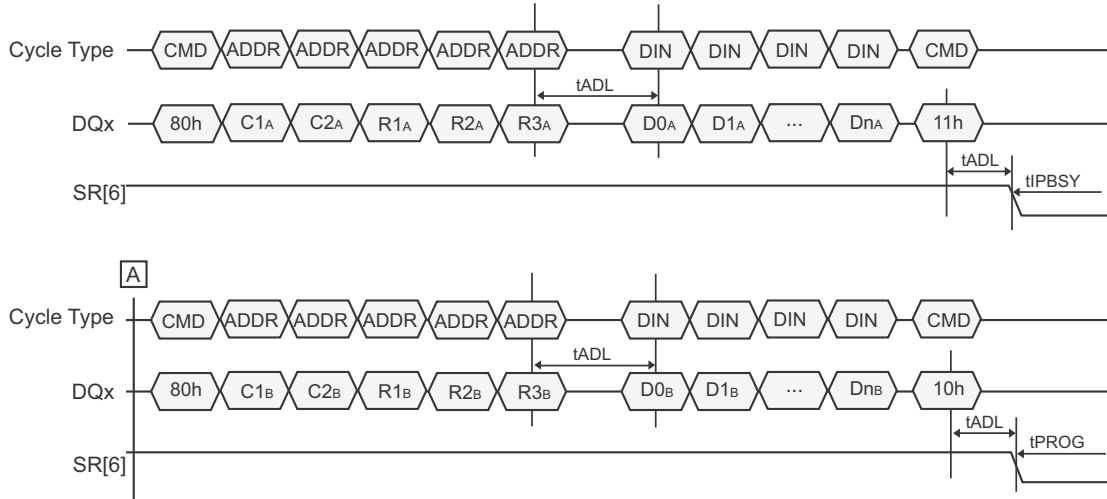
**Figure 33. Random Data Output**


### 7.15 Multiplane Page Program Operation

**Figure 34. Multiplane Page Program** <sup>[59, 60, 61]</sup>

**Note**

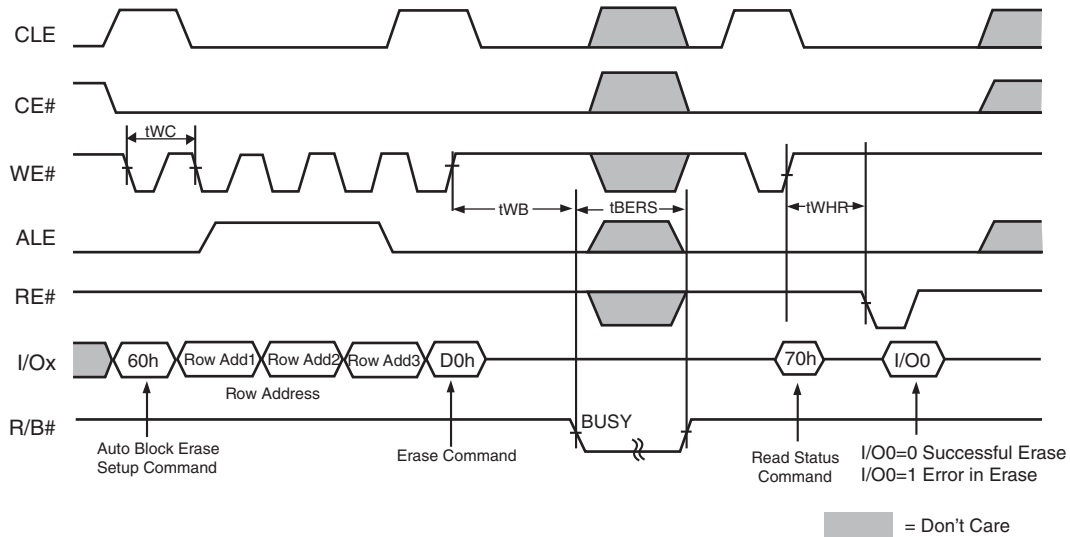
- 59. Any command between 11h and 81h is prohibited except 70h, 78h, and FFh.
- 60. A18 is the plane address bit for \*8 devices.
- 61. The block address bits must be the same except for the bit(s) that select the plane.

**Figure 35. Multiplane Page Program (ONFI 1.0 Protocol)**<sup>[62, 63, 64, 65, 66, 67, 68]</sup>



## 7.16 Block Erase Operation

**Figure 36. Block Erase Operation (Erase One Block)**

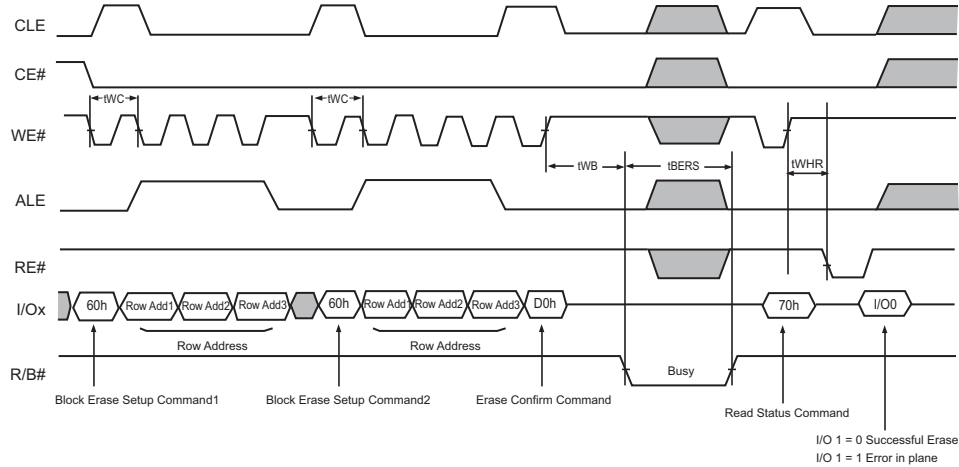


**Notes**

- 62. C1A-C2A Column address for page A. C1A is the least significant byte.
- 63. R1A-R3A Row address for page A. R1A is the least significant byte.
- 64. D0A-DnA Data to program for page A.
- 65. C1B-C2B Column address for page B. C1B is the least significant byte.
- 66. R1B-R3B Row address for page B. R1B is the least significant byte.
- 67. D0B-DnB Data to program for page B.
- 68. The block address bits must be the same except for the bit(s) that select the plane.

### 7.17 Multiplane Block Erase

Figure 37. Multiplane Block Erase<sup>[69, 70]</sup>



Ex.) Address Restriction for Multiplane Block Erase Operation

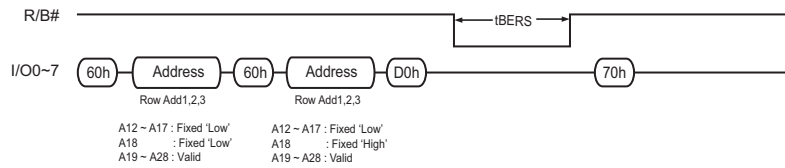
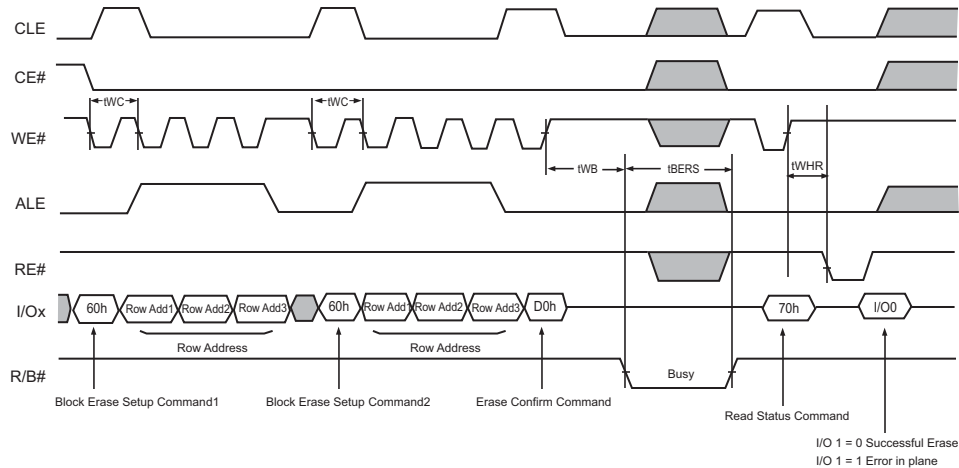
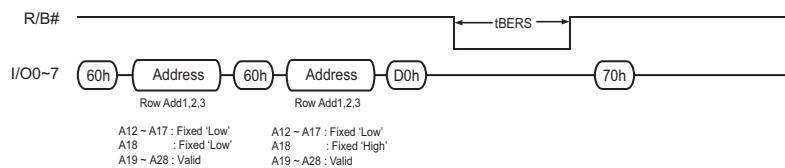


Figure 38. Multiplane Block Erase<sup>[69, 70]</sup>



Ex.) Address Restriction for Multiplane Block Erase Operation

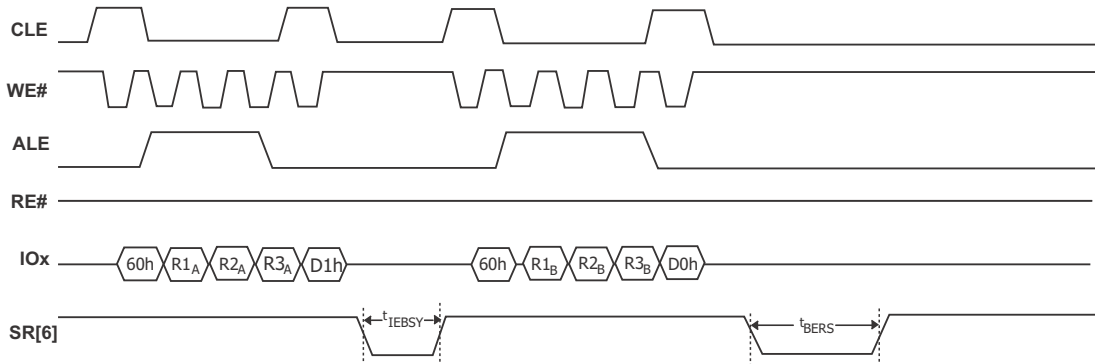


**Notes**

- 69. A18 is the plane address bit for ×8 devices.
- 70. The block address bits must be the same except for the bit(s) that select the plane.

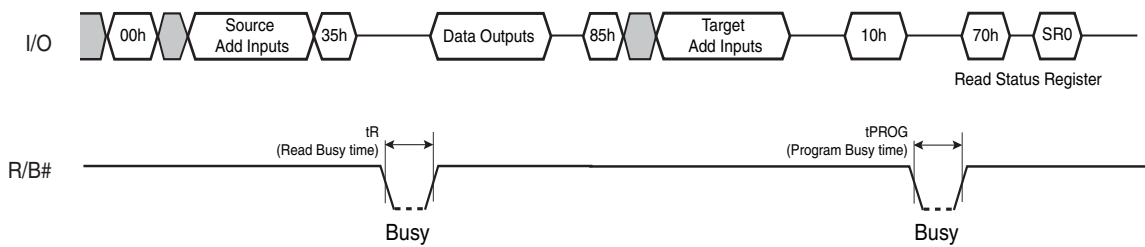


Figure 39. Multiplane Block Erase (ONFI 1.0 Protocol)<sup>[71, 72, 73]</sup>



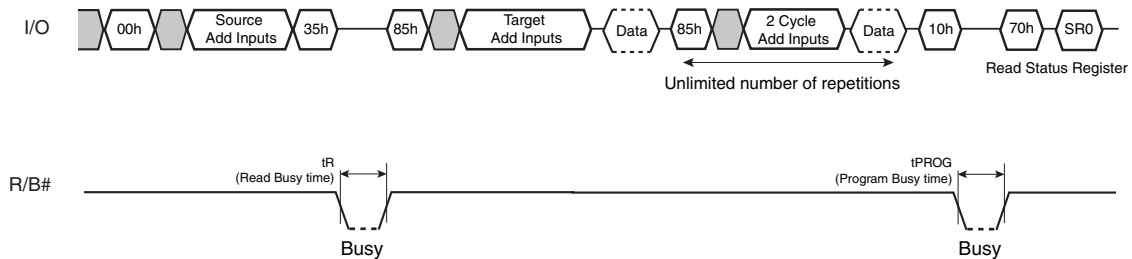
### 7.18 Copy Back Read With Optional Data Readout

Figure 40. Copy Back Read with Optional Data Readout



### 7.19 Copy Back Program Operation With Random Data Input

Figure 41. Copy Back Program with Random Data Input

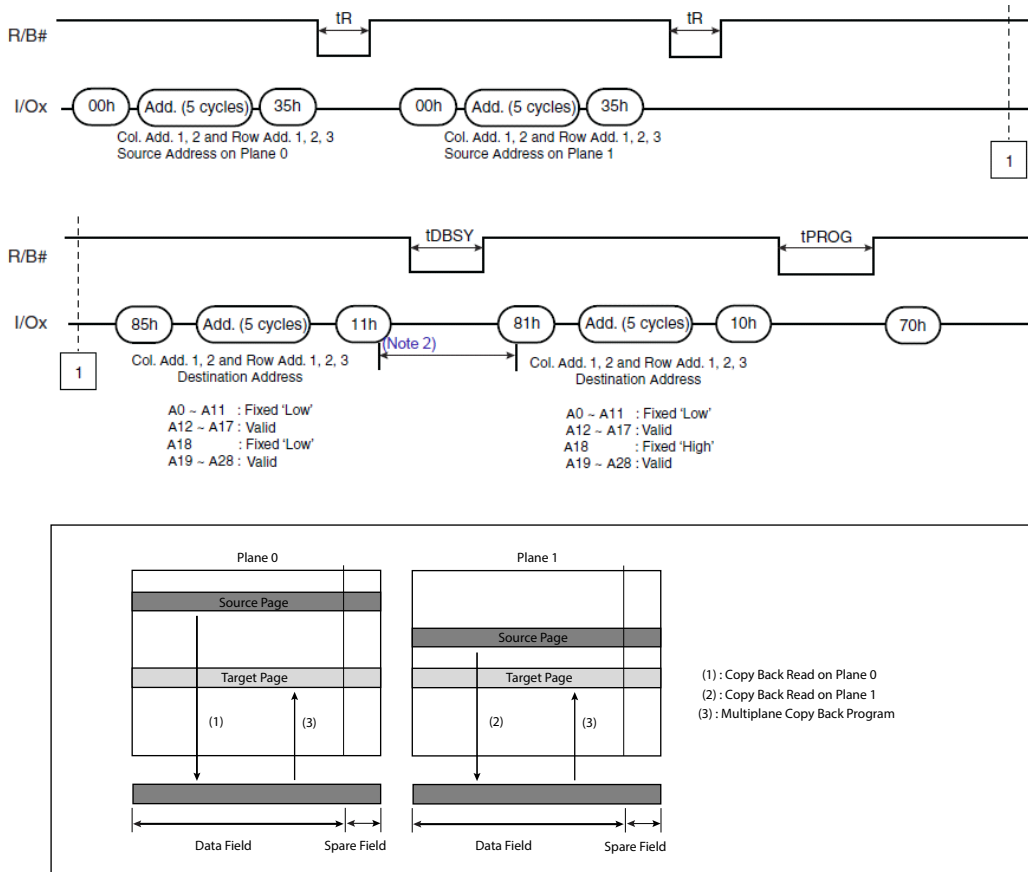


**Notes**

- 71. R1A-R3A Row address for block on plane 0. R1A is the least significant byte.
- 72. R1B-R3B Row address for block on plane 1. R1B is the least significant byte.
- 73. The block address bits must be the same except for the bit(s) that select the plane.

## 7.20 Multiplane Copy Back Program

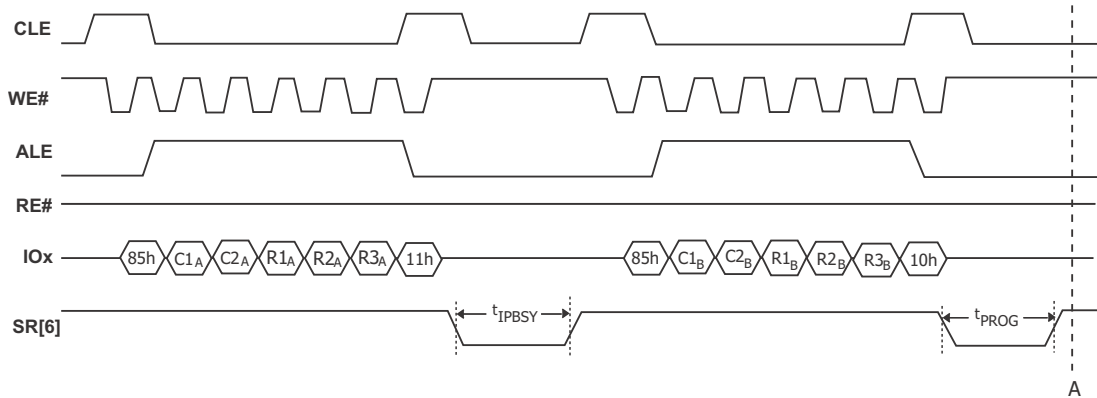
Figure 42. Multiplane Copy Back Program<sup>[74, 75, 76, 77]</sup>



**Notes**

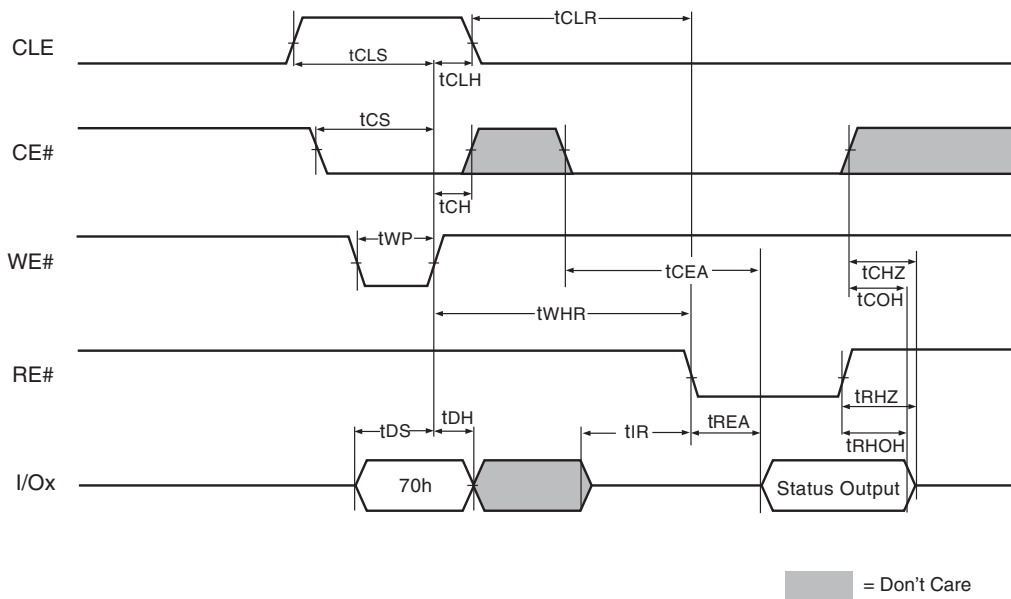
- 74. Copy Back Program operation is allowed only within the same memory plane.
- 75. Any command between 11h and 81h is prohibited except 70h, 78h, and FFh.
- 76. A18 is the plane address bit for ×8 devices.
- 77. The block address bits must be the same except for the bit(s) that select the plane.

Figure 43. Multiplane Copy Back Program (ONFI 1.0 Protocol)<sup>[78, 79, 80, 81, 82]</sup>



## 7.21 Read Status Register Timing

Figure 44. Read Status Cycle

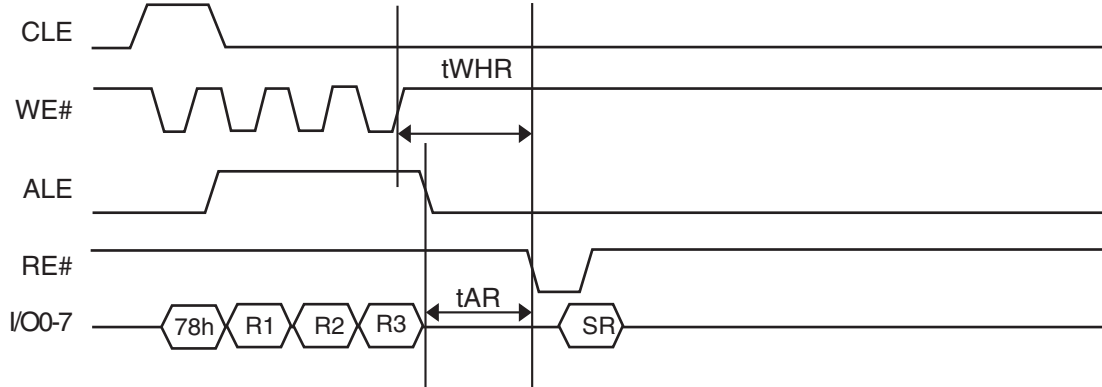


**Notes**

- 78. C1A-C2A Column address for page A. C1A is the least significant byte.
- 79. R1A-R3A Row address for page A. R1A is the least significant byte.
- 80. C1B-C2B Column address for page B. C1B is the least significant byte.
- 81. R1B-R3B Row address for page B. R1B is the least significant byte.
- 82. The block address bits must be the same except for the bit(s) that select the plane.

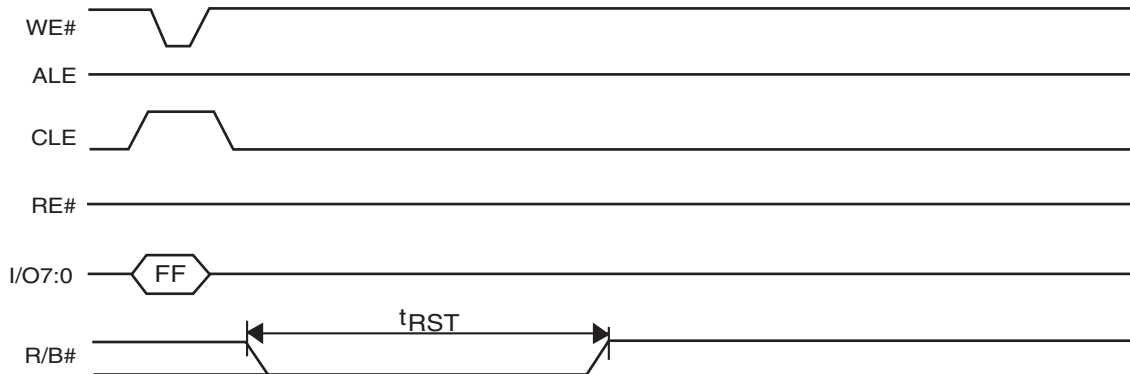
### 7.22 Read Status Enhanced Timing

Figure 45. Read Status Enhanced Timing



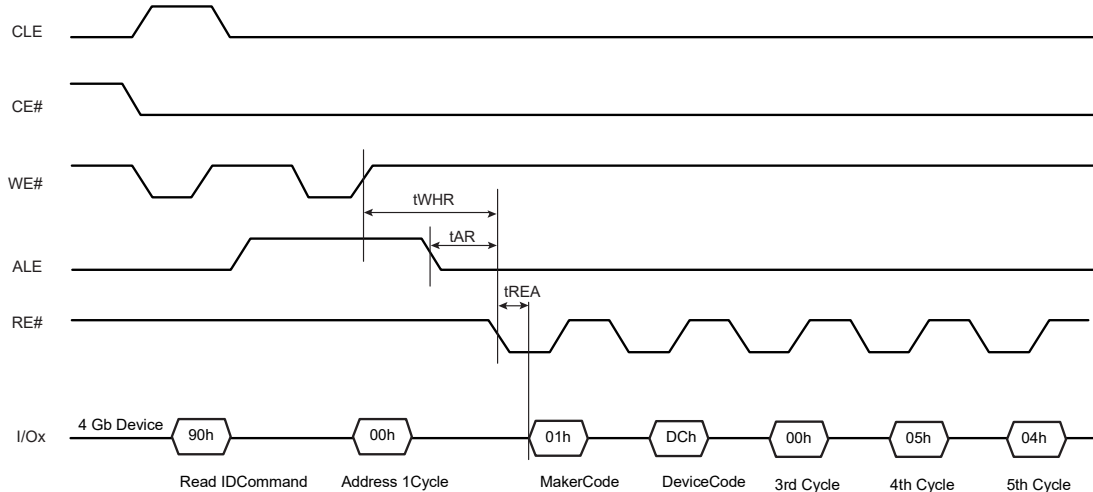
### 7.23 Reset Operation Timing

Figure 46. Reset Operation Timing



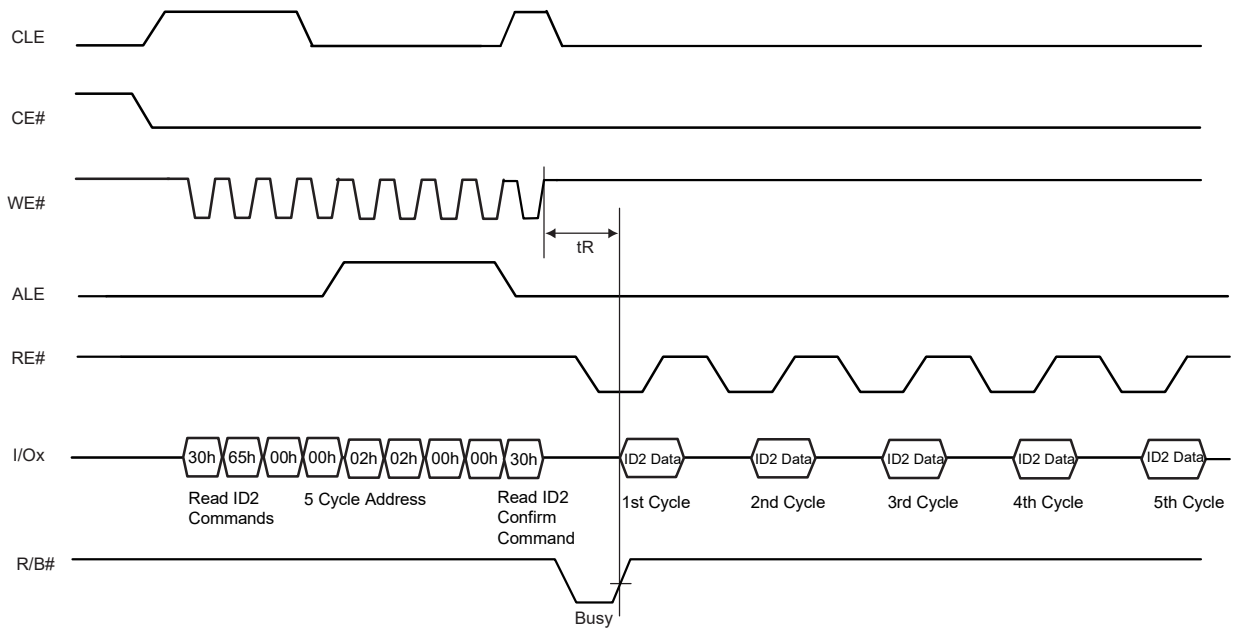
### 7.24 Read ID Operation Timing

Figure 47. Read ID Operation Timing



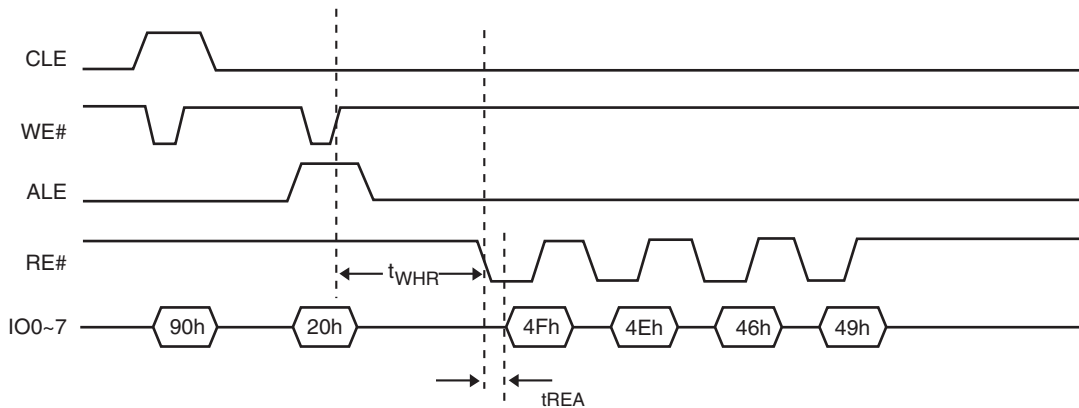
## 7.25 Read ID2 Operation Timing

Figure 48. Read ID2 Operation Timing<sup>[83]</sup>



## 7.26 Read ONFI Signature Timing

Figure 49. ONFI Signature Timing

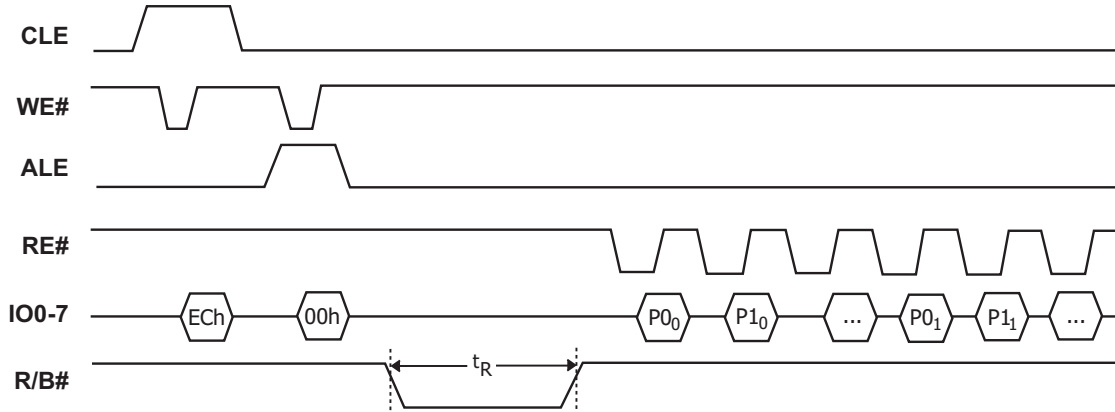


**Note**

83. If Status Register polling is used to determine completion of the Read ID2 operation, the Read Command (00h) must be issued before ID2 data can be read from the flash.

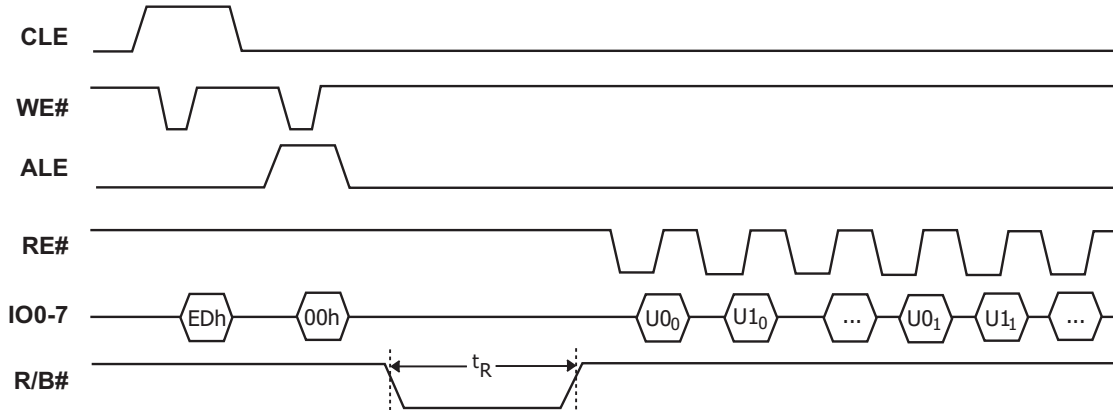
### 7.27 Read Parameter Page Timing

Figure 50. Read Parameter Page Timing<sup>[84]</sup>



### 7.28 Read Unique ID Timing

Figure 51. Read Unique ID Timing

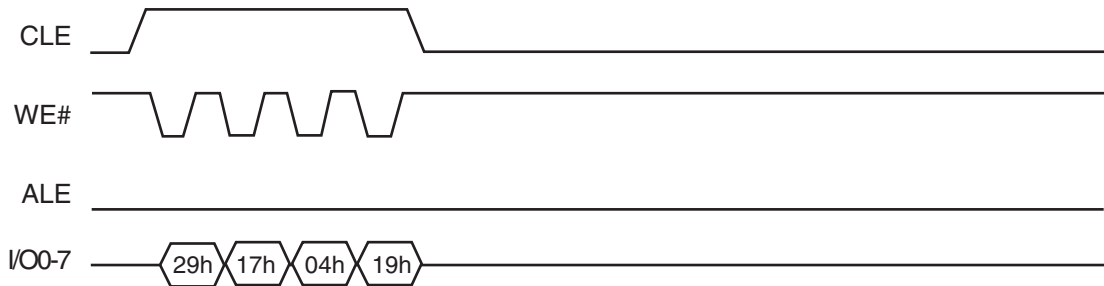


**Note**

84. If Status Register polling is used to determine completion of the read operation, the Read Command (00h) must be issued before data can be read from the page buffer.

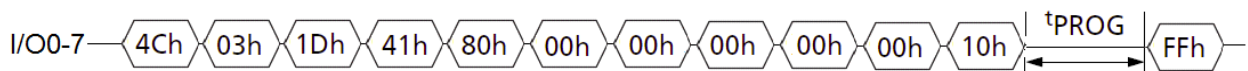
### 7.29 OTP Entry Timing

Figure 52. OTP Entry Timing



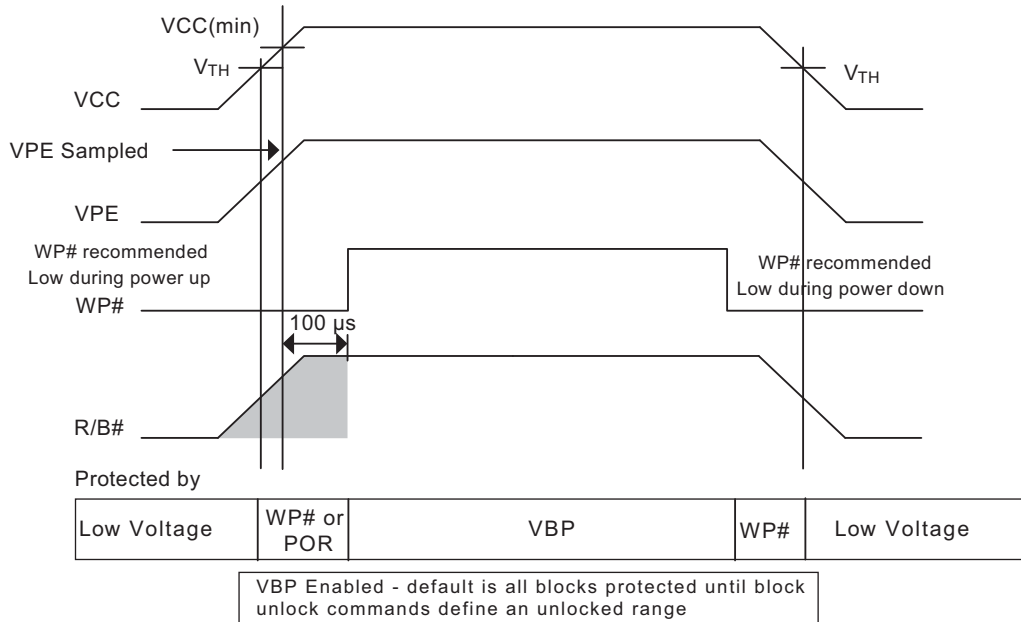
### 7.30 Legacy OTP Protection Timing

Figure 53. Legacy OTP Protection Timing



### 7.31 Power On and Data Protection Timing

Figure 54. VPE High at Power up Timing<sup>[85, 86, 87]</sup>



**Notes**

- 85. V<sub>TH</sub> = 1.8 Volts (Typ).
- 86. The VPE pin must be sampled between V<sub>TH</sub> and V<sub>CC</sub> (min).
- 87. During power up, VCC and VPE slopes are equal.

Figure 55. VPE LOW at Power up Timing

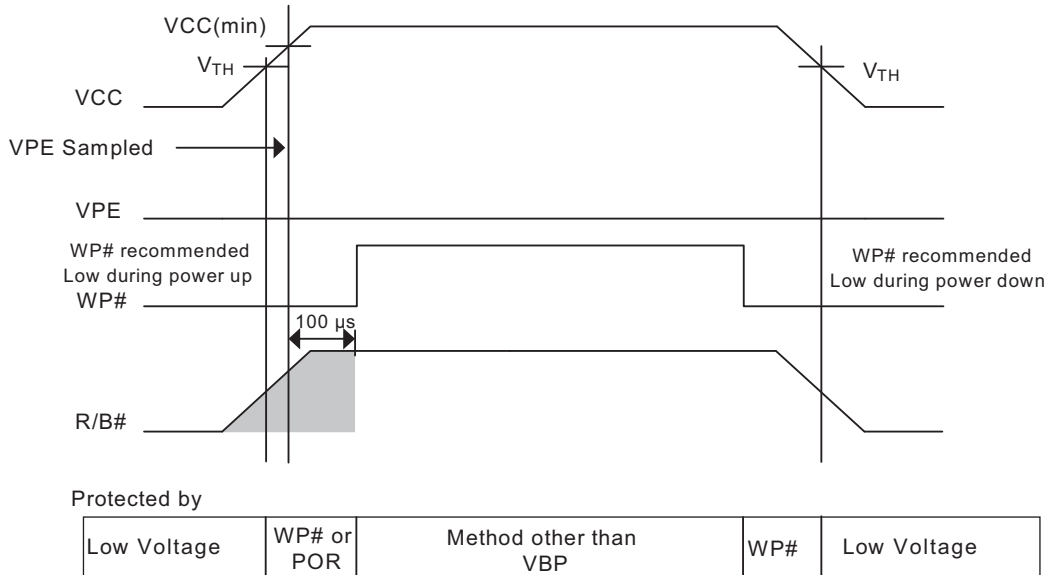
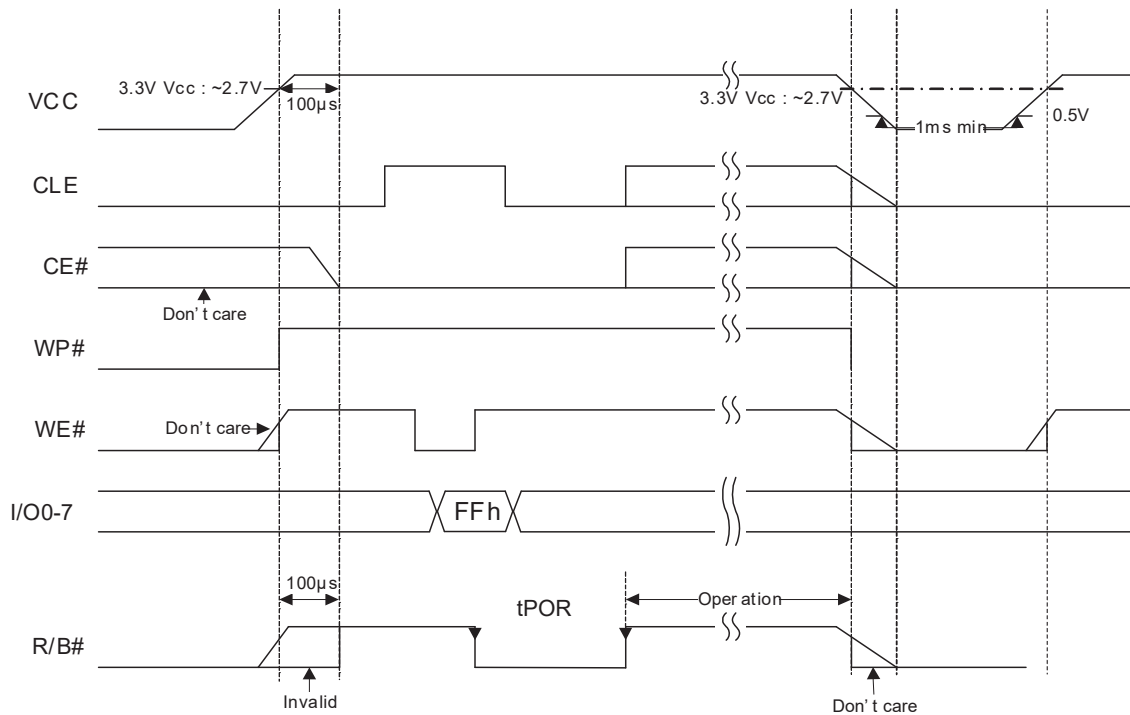


Figure 56. Device Initialization<sup>[88, 89]</sup>



Notes

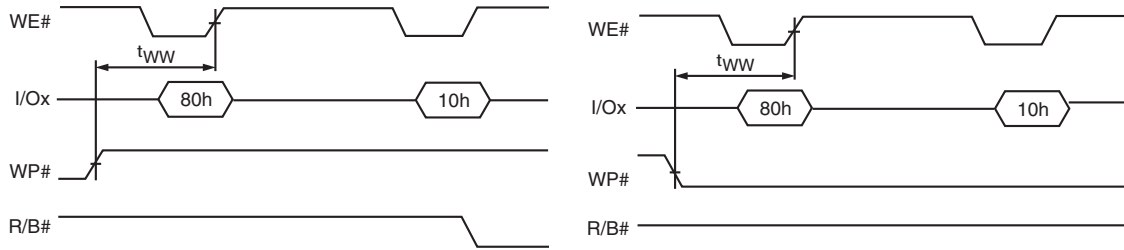
88. Reset (FFh) command is required after power-on and R/B# = high as a first command.

89. During Power-On, VCC should rise monotonically and must remain greater than VLKO (Low VCC Lock-Out Voltage) to execute the initialization process successfully.

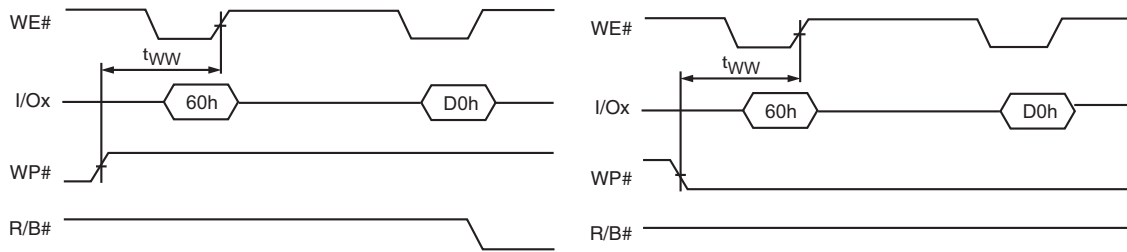


### 7.32 WP# Handling

**Figure 57. Program Enabling / Disabling Through WP# Handling**



**Figure 58. Erase Enabling / Disabling Through WP# Handling**

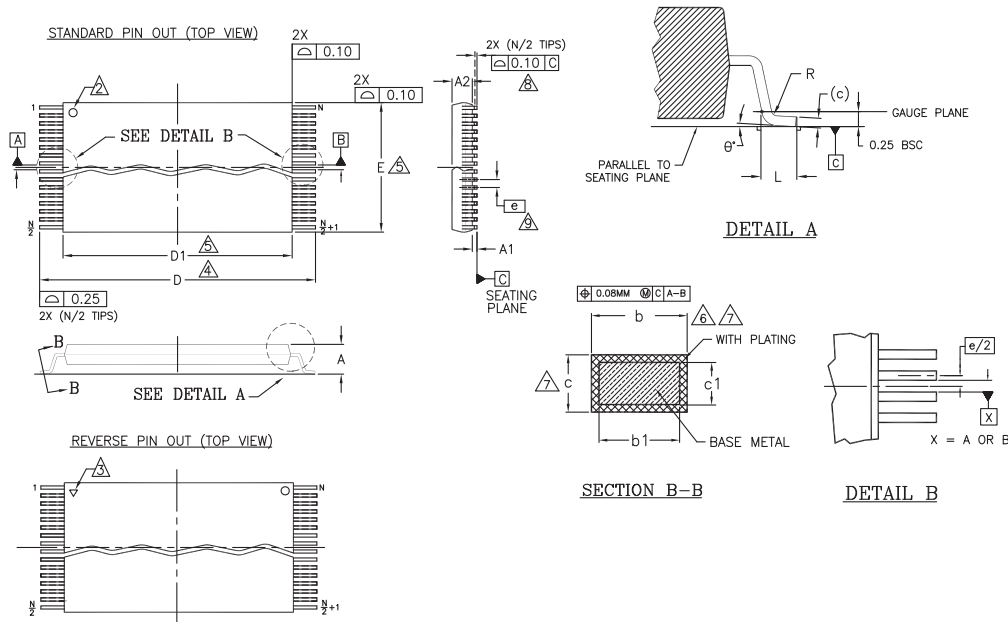


## 8. Physical Interface

### 8.1 Physical Diagram

#### 8.1.1 48-Pin Thin Small Outline Package (TSOP1)

Figure 59. TS/TSR 48 — 48-lead Plastic Thin Small Outline, 12 x 20 mm, Package Outline



| PACKAGE | TS/TSR 48     |       |       |
|---------|---------------|-------|-------|
| JEDEC   | MO-142 (D) DD |       |       |
| SYMBOL  | MIN           | NOM   | MAX   |
| A       | ---           | ---   | 1.20  |
| A1      | 0.05          | ---   | 0.15  |
| A2      | 0.95          | 1.00  | 1.05  |
| b1      | 0.17          | 0.20  | 0.23  |
| b       | 0.17          | 0.22  | 0.27  |
| c1      | 0.10          | ---   | 0.16  |
| c       | 0.10          | ---   | 0.21  |
| D       | 19.80         | 20.00 | 20.20 |
| D1      | 18.30         | 18.40 | 18.50 |
| E       | 11.90         | 12.00 | 12.10 |
| e       | 0.50 BASIC    |       |       |
| L       | 0.50          | 0.60  | 0.70  |
| Θ       | 0°            | ---   | 8     |
| R       | 0.08          | ---   | 0.20  |
| N       | 48            |       |       |

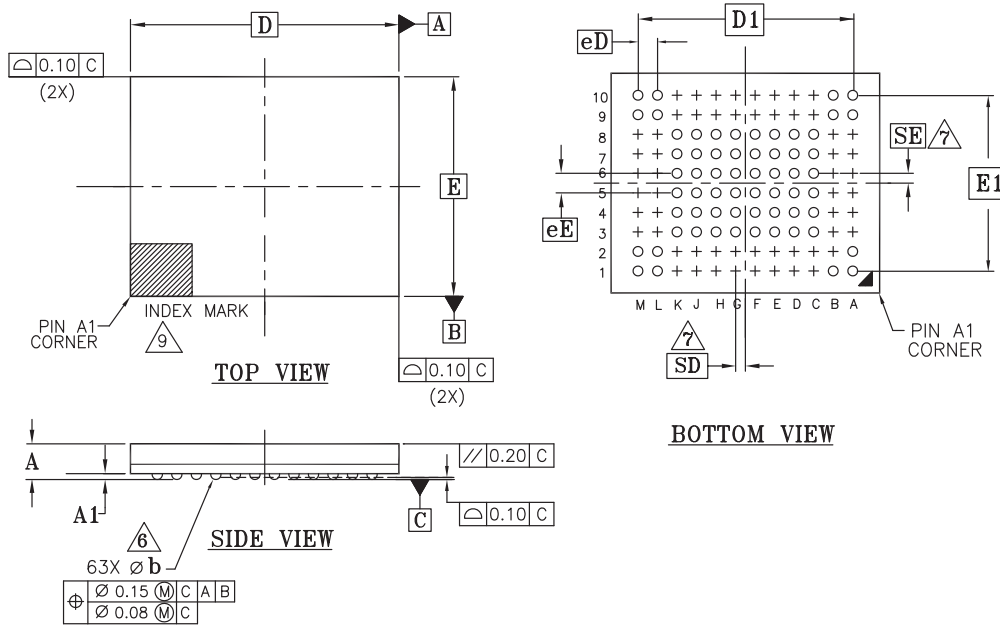
NOTES:

1. DIMENSIONS ARE IN MILLIMETERS (mm). (DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1994).
2. PIN 1 IDENTIFIER FOR STANDARD PIN OUT (DIE UP).
3. PIN 1 IDENTIFIER FOR REVERSE PIN OUT (DIE DOWN): INK OR LASER MARK.
4. TO BE DETERMINED AT THE SEATING PLANE [C]. THE SEATING PLANE IS DEFINED AS THE PLANE OF CONTACT THAT IS MADE WHEN THE PACKAGE LEADS ARE ALLOWED TO REST FREELY ON A FLAT HORIZONTAL SURFACE.
5. DIMENSIONS D1 AND E DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION ON E IS 0.15mm PER SIDE AND ON D1 IS 0.25mm PER SIDE.
6. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08mm TOTAL IN EXCESS OF b DIMENSION AT MAX. MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND AN ADJACENT LEAD TO BE 0.07mm.
7. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10mm AND 0.25mm FROM THE LEAD TIP.
8. LEAD COPLANARITY SHALL BE WITHIN 0.10mm AS MEASURED FROM THE SEATING PLANE.
9. DIMENSION "e" IS MEASURED AT THE CENTERLINE OF THE LEADS.

5006 \ F16-038 \ 6.5.13

### 8.1.2 63-Ball, Ball Grid Array (BGA)

Figure 60. VBM063 — 63-Pin BGA, 11 mm x 9 mm Package



| PACKAGE  | VBM 063  |      |      |                          |
|----------|--|------|------|--------------------------|
| JEDEC    | M0-207(M)  |      |      |                          |
|          | 11.00 mm x 9.00 mm NOM PACKAGE   |      |      |                          |
| SYMBOL   | MIN  | NOM  | MAX  | NOTE                     |
| A        | ---  | ---  | 1.00 | PROFILE                  |
| A1       | 0.25   | ---  | ---  | BALL HEIGHT              |
| D        | 11.00 BSC.   |      |      | BODY SIZE                |
| E        | 9.00 BSC.  |      |      | BODY SIZE                |
| D1       | 8.80 BSC.  |      |      | MATRIX FOOTPRINT         |
| E1       | 7.20 BSC.  |      |      | MATRIX FOOTPRINT         |
| MD       | 12   |      |      | MATRIX SIZE D DIRECTION  |
| ME       | 10   |      |      | MATRIX SIZE E DIRECTION  |
| n        | 63   |      |      | BALL COUNT               |
| $\phi b$ | 0.40   | 0.45 | 0.50 | BALL DIAMETER            |
| eE       | 0.80 BSC.  |      |      | BALL PITCH               |
| eD       | 0.80 BSC.  |      |      | BALL PITCH               |
| SD       | 0.40 BSC.  |      |      | SOLDER BALL PLACEMENT    |
| SE       | 0.40 BSC.  |      |      | SOLDER BALL PLACEMENT    |
|          | A3-A8, B2-B8, C1, C2, C9, C10<br>D1, D2, D9, D10, E1, E2, E9, E10<br>F1, F2, F9, F10, G1, G2, G9, G10<br>H1, H2, H9, H10, J1, J2, J9, J10<br>K1, K2, K9, K10<br>L3-L8, M3-M8 |      |      | DEPOPULATED SOLDER BALLS |

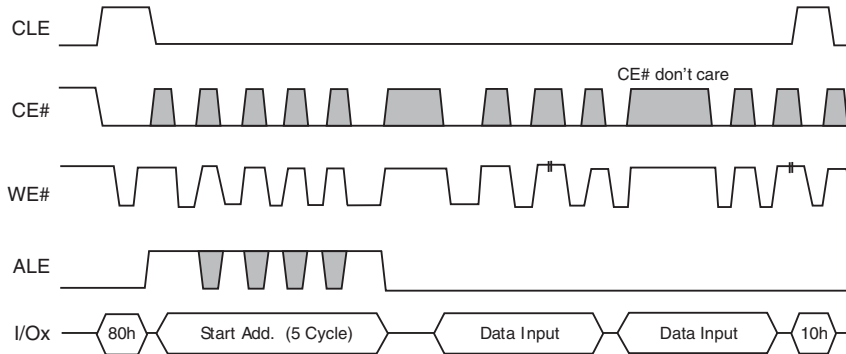
NOTES:

- DIMENSIONING AND TOLERANCING METHODS PER ASME Y14.5M-1994.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- BALL POSITION DESIGNATION PER JEP95, SECTION 3, SPP-020.
- [e] REPRESENTS THE SOLDER BALL GRID PITCH.
- SYMBOL "MD" IS THE BALL MATRIX SIZE IN THE "D" DIRECTION.  
SYMBOL "ME" IS THE BALL MATRIX SIZE IN THE "E" DIRECTION.  
n IS THE TOTAL NUMBER OF POPULATED SOLDER BALL POSITIONS FOR MATRIX SIZE MD X ME.
- [6] DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
- [7] "SD" AND "SE" ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW.  
WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW "SD" OR "SE" = 0.  
WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW, "SD" =  $\phi D/2$  AND "SE" =  $\phi E/2$ .
- "+" INDICATES THE THEORETICAL CENTER OF DEPOPULATED BALLS.
- A1 CORNER TO BE IDENTIFIED BY CHAMFER, LASER OR INK MARK, METALLIZED MARK INDENTATION OR OTHER MEANS.

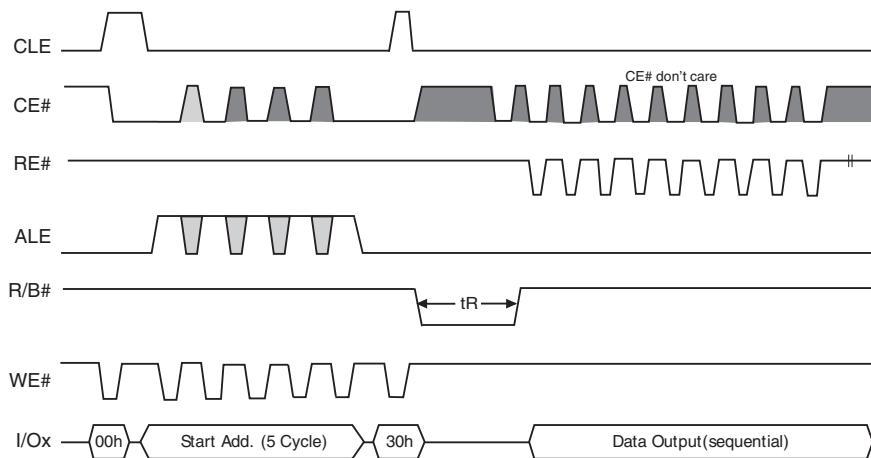
## 9. System Interface

To simplify system interface, CE# may be unasserted during data loading or sequential data reading as shown in Figure 61. By operating in this way, it is possible to connect NAND flash to a microprocessor.

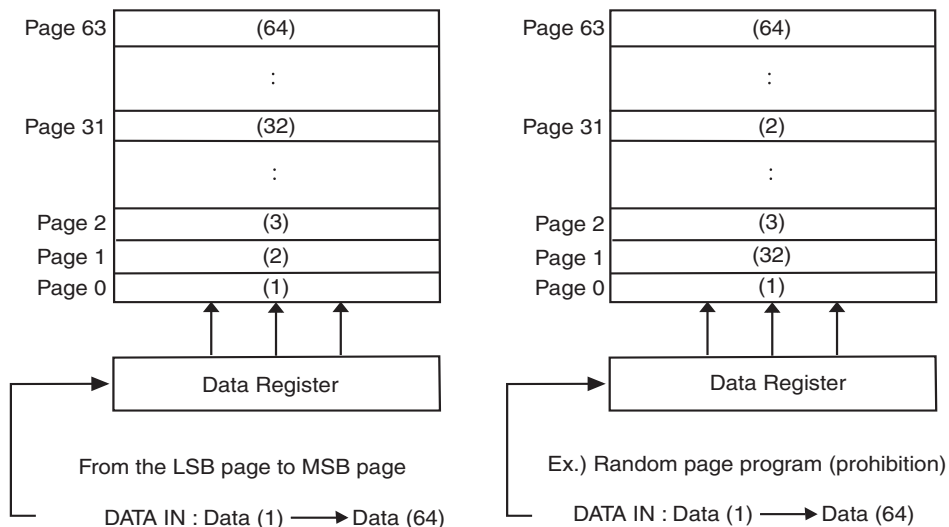
**Figure 61. Program Operation with CE# Don't Care**



**Figure 62. Read Operation with CE# Don't Care**



**Figure 63. Page Programming Within a Block**



## 10. Error Management

### 10.1 System Bad Block Replacement

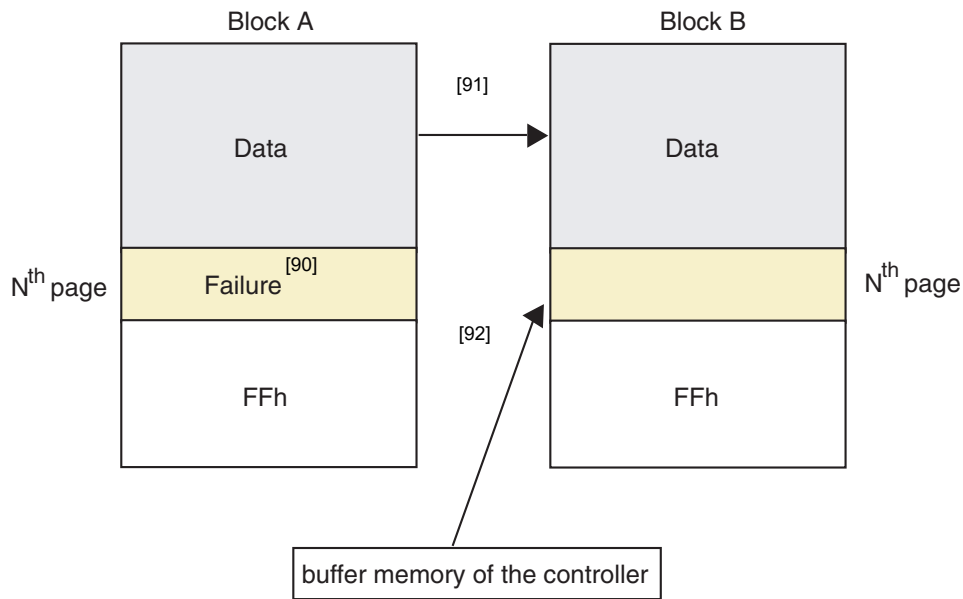
Over the lifetime of the device, additional Bad Blocks may develop. In this case, each bad block has to be replaced by copying any valid data to a new block. These additional Bad Blocks can be identified whenever a program or erase operation reports “Fail” in the Status Register.

The failure of a page program operation does not affect the data in other pages in the same block, thus the block can be replaced by re-programming the current data and copying the rest of the replaced block to an available valid block. Refer to [Table 32](#) and [Figure 64](#) for the recommended procedure to follow if an error occurs during an operation.

**Table 32. Block Failure**

| Operation | Recommended Procedure      |
|-----------|----------------------------|
| Erase     | Block Replacement          |
| Program   | Block Replacement          |
| Read      | Check Read Status Register |

**Figure 64. Bad Block Replacement**



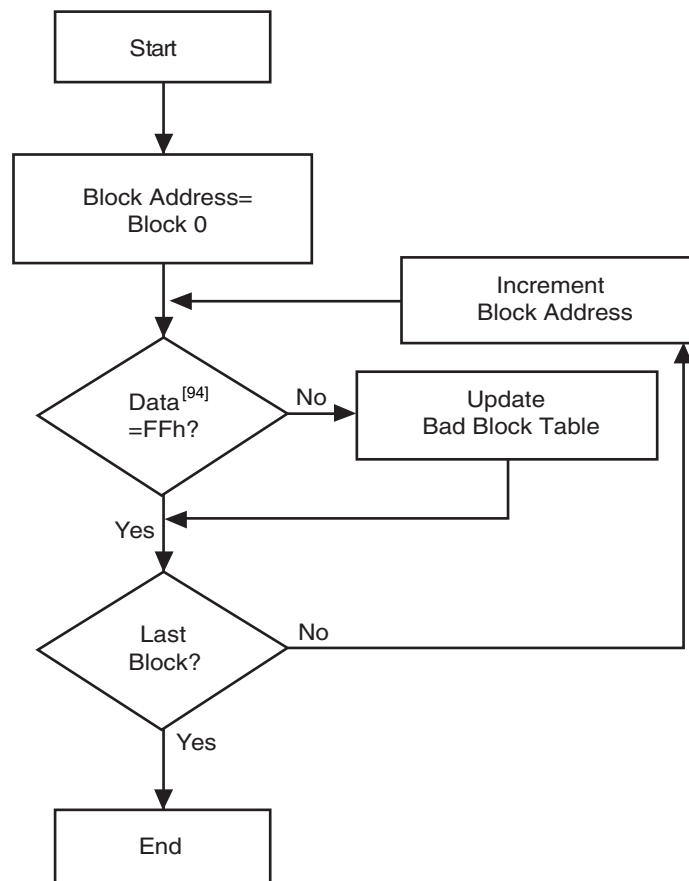
**Notes**

- 90. An error occurs on the Nth page of Block A during a program operation.
- 91. Data in Block A is copied to the same location in Block B, which is a valid block.
- 92. The Nth page of block A, which is in controller buffer memory, is copied into the Nth page of Block B.
- 93. Bad block table should be updated to prevent from erasing or programming Block A.

## 10.2 Bad Block Management

Devices with Bad Blocks have the same quality level and the same AC and DC characteristics as devices where all the blocks are valid. A Bad Block does not affect the performance of valid blocks because it is isolated from the bit line and common source line by a select transistor. The devices are supplied with all the locations inside valid blocks erased (FFh). The Bad Block Information is written before shipping. Any block where the 1st byte in the spare area of the 1st or 2nd or last page does not contain FFh is a Bad Block. That is, if the first page has an FF value and should have been a non-FF value, then the non-FF value in the second page or the last page will indicate a bad block. The Bad Block Information must be read before any erase is attempted, as the Bad Block Information may be erased. For the system to be able to recognize the Bad Blocks based on the original information, it is recommended to create a Bad Block table following the flowchart shown in Figure 65. The host is responsible to detect and track bad blocks, both factory bad blocks and blocks that may go bad during operation. Once a block is found to be bad, data should not be written to that block. Blocks 0-7 are guaranteed good at the time of shipment.

Figure 65. Bad Block Management Flowchart<sup>[94]</sup>

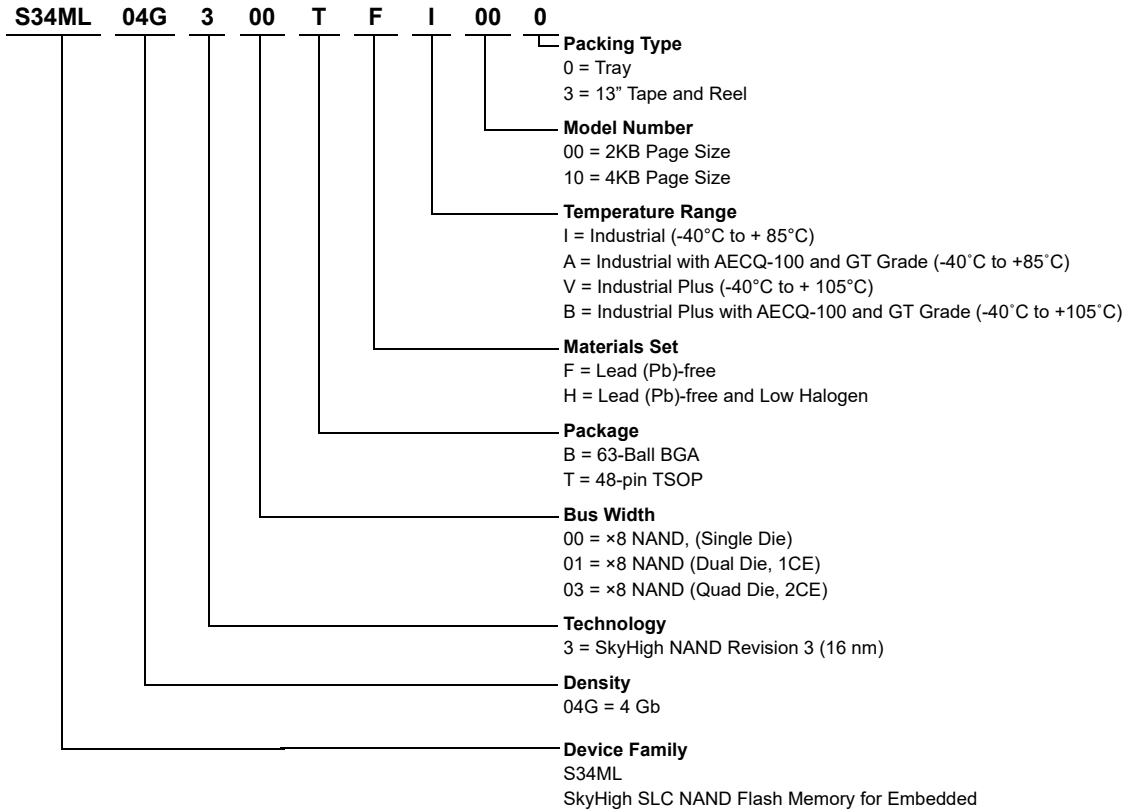


**Note**

94. Check for FFh at the 1st byte in the spare area of the 1st, 2nd, and last pages.

## 11. Ordering Information

The ordering part number is formed by a valid combination of the following:



### Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Contact your local sales office to confirm availability of specific valid combinations and to check on newly released combinations.

| Device Family | Density | Technology | Bus Width | Package Type | Temperature Range | Additional Ordering Options | Packing Type | Package Description       |
|---------------|---------|------------|-----------|--------------|-------------------|-----------------------------|--------------|---------------------------|
| S34ML         | 04G     | 3          | 00        | BH, TF       | I                 | 00                          | 0, 3         | TSOP, BGA <sup>[95]</sup> |

**Note**

95. BGA package marking omits the leading "S34" and the Packing Type designator from the ordering part number.

## 12. Document History Page

| Document Title: S34ML04G3 4 Gb, 3 V, 2K Page Size, x8 I/O, SLC NAND Flash Memory for Embedded |         |                 |                 |   |
|---|---------|-----------------|-----------------|---|
| Document Number: 002-19204  |         |                 |                 |   |
| Rev.  | ECN No. | Orig. of Change | Submission Date | Description of Change   |
| **  | 5679035 | MNAD            | 04/03/2017      | Initial release   |
| *A  | 5703588 | MNAD            | 04/28/2017      | Updated Sales page.   |
| *B  | 5774013 | MNAD            | 06/21/2017      | Added <a href="#">Security Features</a> , <a href="#">Page Read</a> , and <a href="#">Page Program</a> .<br>Updated <a href="#">Table 5</a> , <a href="#">Table 7</a> , <a href="#">Table 8</a> , <a href="#">Table 12</a> , <a href="#">Table 14</a> , <a href="#">Table 17</a> , and <a href="#">Table 22</a> .<br>Updated <a href="#">Figure 12</a> , <a href="#">Figure 7.24</a> , <a href="#">Figure 48</a> , and <a href="#">Figure 56</a> .<br>Updated <a href="#">Command Set</a> , <a href="#">One-Time Programmable (OTP)</a> , <a href="#">Copy Back Program</a> , <a href="#">Read Status Register</a> , <a href="#">Read ID</a> , <a href="#">Read ID2</a> , <a href="#">Permanent Block Protection (PBP) Overview</a> , <a href="#">Ordering Information</a> .<br>Updated Sales page and Copyright information.   |
| *C  | 5889797 | MNAD            | 09/20/2017      | Updated <a href="#">Performance</a> .<br>Updated <a href="#">Memory Address Phase Cycles</a> .<br>Updated <a href="#">READ ID</a> and removed Firmware SLC Mode commands in <a href="#">Command Set</a> .<br>Added <a href="#">Multiplane Page Read</a> .<br>Updated <a href="#">Page Program</a> , <a href="#">Read Status Register Field Definition</a> , and <a href="#">Reset</a> .<br>Updated <a href="#">Parameter Page Description</a> and <a href="#">Feature Address 90h-Array Operation Mode (P1 Register)[29, 30]</a> tables.<br>Removed the Firmware SLC Mode section.<br>Updated <a href="#">Address Definition of Unlock Block</a> .<br>Updated <a href="#">Permanent Block Protection (PBP) Overview</a> .<br>Updated <a href="#">AC Characteristics</a> .<br>Added <a href="#">Thermal Resistance</a> .<br>Updated <a href="#">Program / Erase Characteristics</a> .<br>Added <a href="#">Multiplane Page Read Operation</a> diagram.   |
| *D  | 5906463 | MNAD            | 10/04/2017      | Updated Document Status to "Advance".<br>Updated <a href="#">Table 7</a> and <a href="#">Table 22</a> .<br>Updated <a href="#">Section 3.18.1. OTP Access</a> and <a href="#">Section 3.18.2. OTP Protection</a> .<br>Added sections <a href="#">Section 7.11. Small Data Input Guidelines</a> and <a href="#">Section 7.11. Small Data Input Guidelines</a> .  |
| *E  | 5965491 | MNAD            | 11/17/2017      | Removed references to part numbers "S34ML01G3 and S34ML02G3" in the datasheet.<br>Removed <a href="#">Section 7.11 Open Block Guidelines</a> .<br>Add note in <a href="#">Section 7.31. Power On and Data Protection Timing</a> and <a href="#">Section 6.9. Program / Erase Characteristics</a> .<br>Updated <a href="#">Table 7</a> , <a href="#">Table 14</a> , <a href="#">Table 18</a> , <a href="#">Table 23</a> , and <a href="#">Table 31</a> .<br>Removed notes in <a href="#">Table 21</a> .<br>Updated the following sections: <a href="#">Section 1.. General Description</a> , <a href="#">Section 1.4. Block Diagram</a> <a href="#">Section 1.5. Array Organization</a> , <a href="#">Section 1.6.1. Memory Address Phase Cycles</a> , <a href="#">Section 2.2. Address Input</a> , <a href="#">Section 3.1. Page Read through</a> <a href="#">Section 3.4. Multiplane Program</a> , <a href="#">Section 3.9. Read Status Register</a> , <a href="#">Section 3.13. Read ID</a> , <a href="#">Section 3.14. Read ID2</a> <a href="#">Section 6.9. Program / Erase Characteristics</a> , <a href="#">Section 3.18.2. OTP Protection</a> , <a href="#">Section 4.2.1. Block Protection Status Read command (7Ah) Waveform</a> , <a href="#">Section 7.2. Address Latch Cycle</a> , <a href="#">Section 7.24. Read ID Operation Timing</a> , and <a href="#">Section 11.. Ordering Information</a> |
| *F  | 6043562 | MNAD            | 01/25/2018      | Updated <a href="#">Section 3.2. Multiplane Page Read</a> , <a href="#">Section 3.8.1. Multiplane Copy Back Program</a> , <a href="#">Section 4.1. Volatile Block Protection (VBP) Overview</a> , and <a href="#">Section . Valid Combinations</a> .<br>Updated <a href="#">Figure 12</a> , <a href="#">Figure 16</a> , <a href="#">Figure 28</a> , and <a href="#">Figure 42</a> .<br>Updated Sales page and Copyright year.   |
| *G  | 6110119 | MNAD            | 03/26/2018      | Updated <a href="#">Data Input Cycles</a> in <a href="#">Table 7</a> .<br>Removed <a href="#">Special Read</a> for <a href="#">Copy Back</a> command.<br>Added note 1 in <a href="#">Table 8</a> .<br>Updated <a href="#">Section 3.4</a> and <a href="#">Section 3.7</a><br>Updated <a href="#">Section 4.2.1</a><br>Updated data size in <a href="#">Section 7.11</a> .<br>Updated <a href="#">Figure 34</a> , <a href="#">Figure 38</a> , <a href="#">Figure 42</a> , and <a href="#">Figure 56</a> .  |
| *H  | 6163244 | MNAD            | 05/04/2018      | Updated <a href="#">Table 8</a> and <a href="#">Table 17</a> .  |
| *I  | 6456704 | MNAD            | 01/23/2019      | Removed "Advanced" status from the datasheet.<br>Changed Note reference 43 to 45.   |
| *J  | 6493350 | MNAD            | 03/13/2019      | Removed reference to the 67-ball BGA package<br>Removed "Advance" status from the Sales, Solutions, and Legal Information page  |
| *K  |         | MNAD            | 04/24/2019      | Update SkyHigh format   |
| *L  |         | MNAD            | 05/20/2019      | Removed 1 bit ECC requirement on page 1.<br>updated parameter on pages 22,23, bytes 112,254,255<br>Changed 1 bit ECC mandatory to recommended on Page 3   |
| *M  |         | MNAD            | 08/26/2019      | Update Parameter Page with 80K P/E cycle for -40°C to 85°C  |